

# Overview IMST

Rüdiger Follmann



# Profile



**legal  
founded  
area**

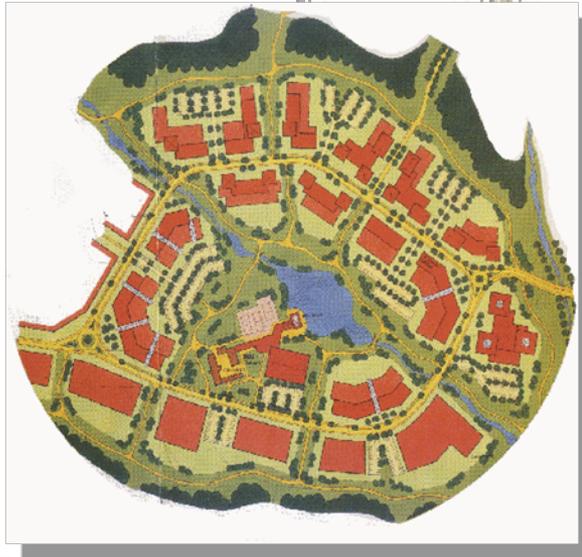
GmbH (Ltd.)  
September 1992  
Research +  
Development  
→ ComTech solutions  
→ RF Sensor  
→ MultiMedia  
→ EMC-techniques  
→ Wireless  
technologies

**IMST is industry's center  
of competence**



# Headquarters

- 10.000 sqm site area
- 4.500 sqm overall space
- 1.500 sqm laboratories
- 300 sqm hybrid technologies



# Organisation IMST

**Prof. Dr. Ingo  
Wolff**

**Dr. Peter Waldow**

- Marketing
- Technology Transfer
- MultiMedia & Layout
- Quality Assurance
- Controlling
- EDV-Administration
- Central Services

**G. Seidel  
Systems**

**Dr. Matthias  
Rittweger  
Circuits**

**Dr. M. Geissler  
Antennas & EM**

**J. J. Borkes  
Test Centre**

- > 100 Researchers    11 Administration
- 19 PhDs            20 Students, e.t.c
- 79 Engineers

# Products and services

## Services

- System Design
- Circuit & Antenna Design
- Integrated Circuit Design
- Active & Passive Device Modeling
- RF & Antenna Measurements
- Channel Sounder Measurements
- EMC - Tests
- Mobile Phone Tests
- Technical Consulting and [seminars](#)

## Products

-  Coplanar Design Library  
Add-On to Agilent EEsof's ADS
-  Advanced 3D EM Simulation Software
-  State-of-the-art HEMT, MESFET, LDMOS models and Parameter Extraction
- **MultiLib**<sup>TM</sup> Design Library for LTCC/PCB multi-layered circuits  
Add-On to Agilent EEsof's ADS

# Measurements, models and extractions

Rüdiger Follmann



# Contents

- Models
- Linear part
- Nonlinear part
- Current measurements
- S-parameter measurements
- Power measurements
- Noise
- Verification



# Ways of modeling

- **Physical models:** Particle models or semiconductor equations
- **Table based models:** Bias dependent S-parameters are saved in a table
- **Mathematical models:** Transfer behavior is described by mathematical functions
- **Equivalent circuits:** Physical behavior is emulated by lumped elements



# Ways of modeling

## Linear models

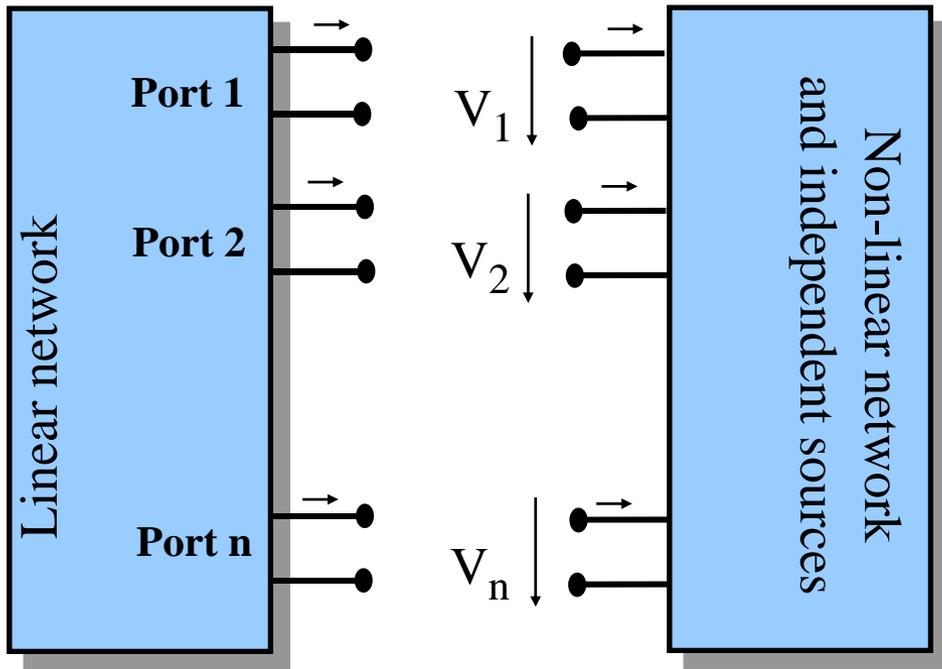
- Description of DC behavior
- Description of RF behavior, e.g. in dependence of bias point. Only small signal amplitudes close to bias point are allowed

## Non-linear models

- Large signal amplitudes and change of bias point (Harmonic balance).



# Harmonic balance



Only linear elements

Only non-linear elements

HB is a hybrid between time- and frequency domain calculations.

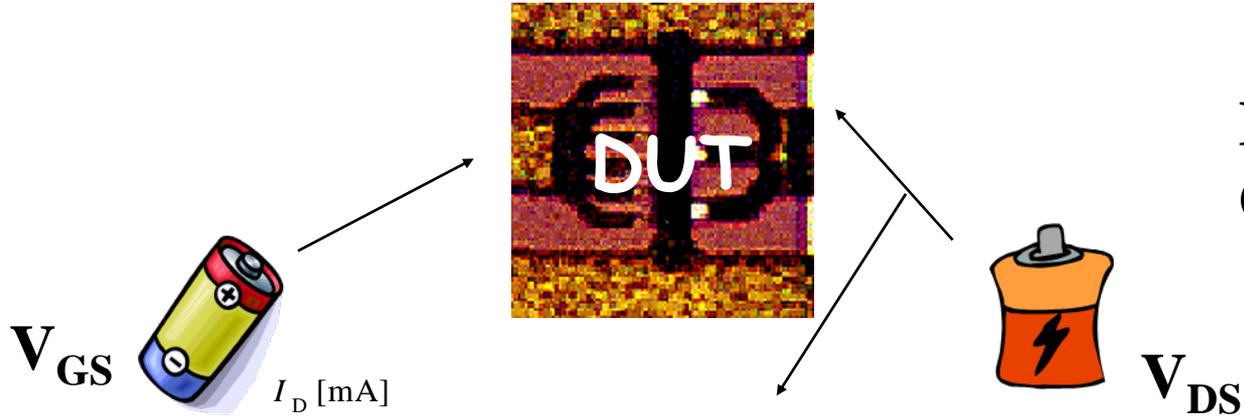
Non-linear part is calculated in time domain, linear part in frequency domain

Voltages and currents at each port are balanced, until they are equal for both part of network.



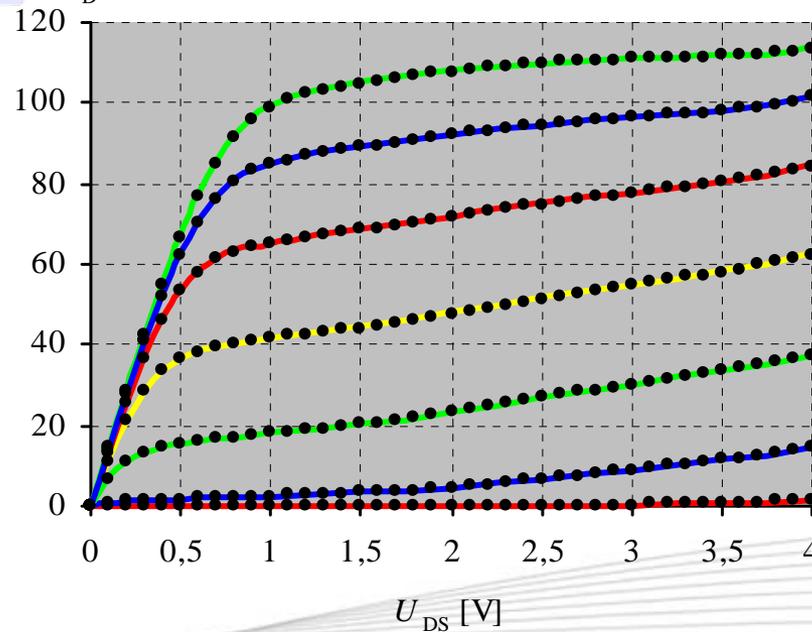
# DC measurements

Port 1  
Input



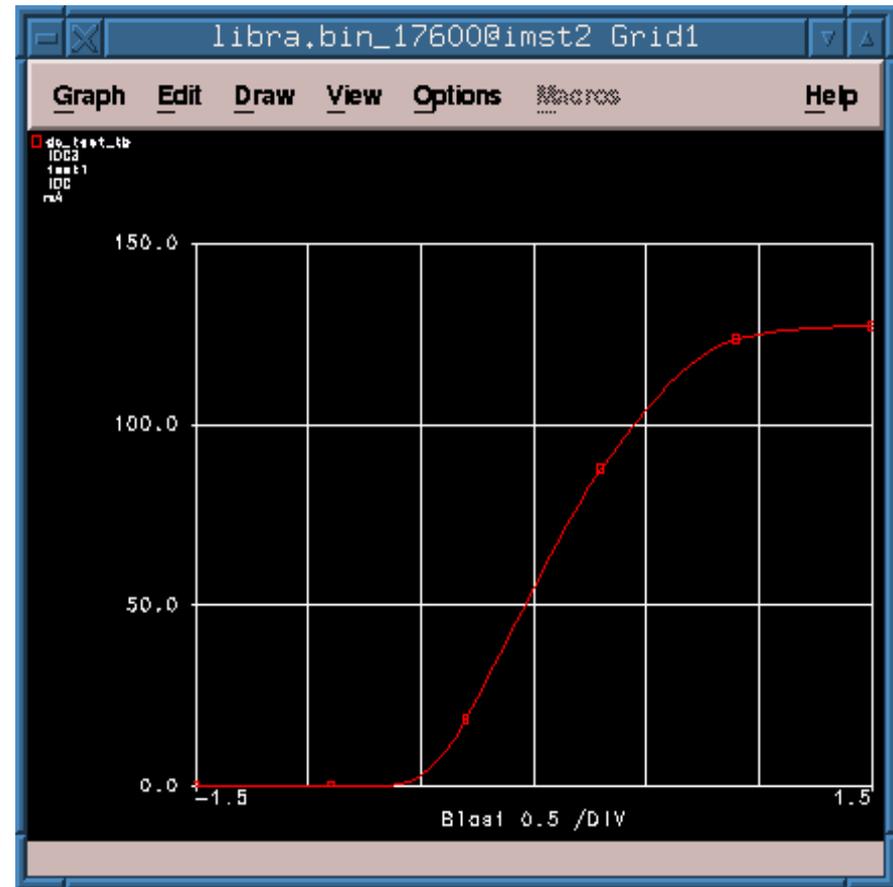
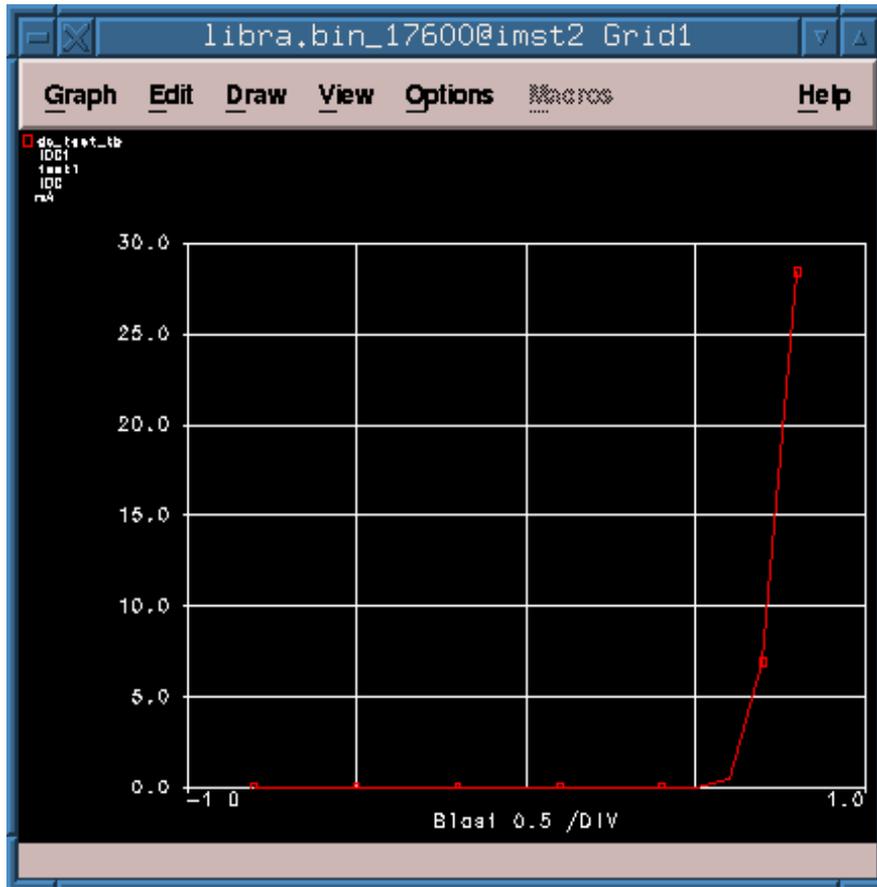
Port 2  
Output

DC IV-  
curves



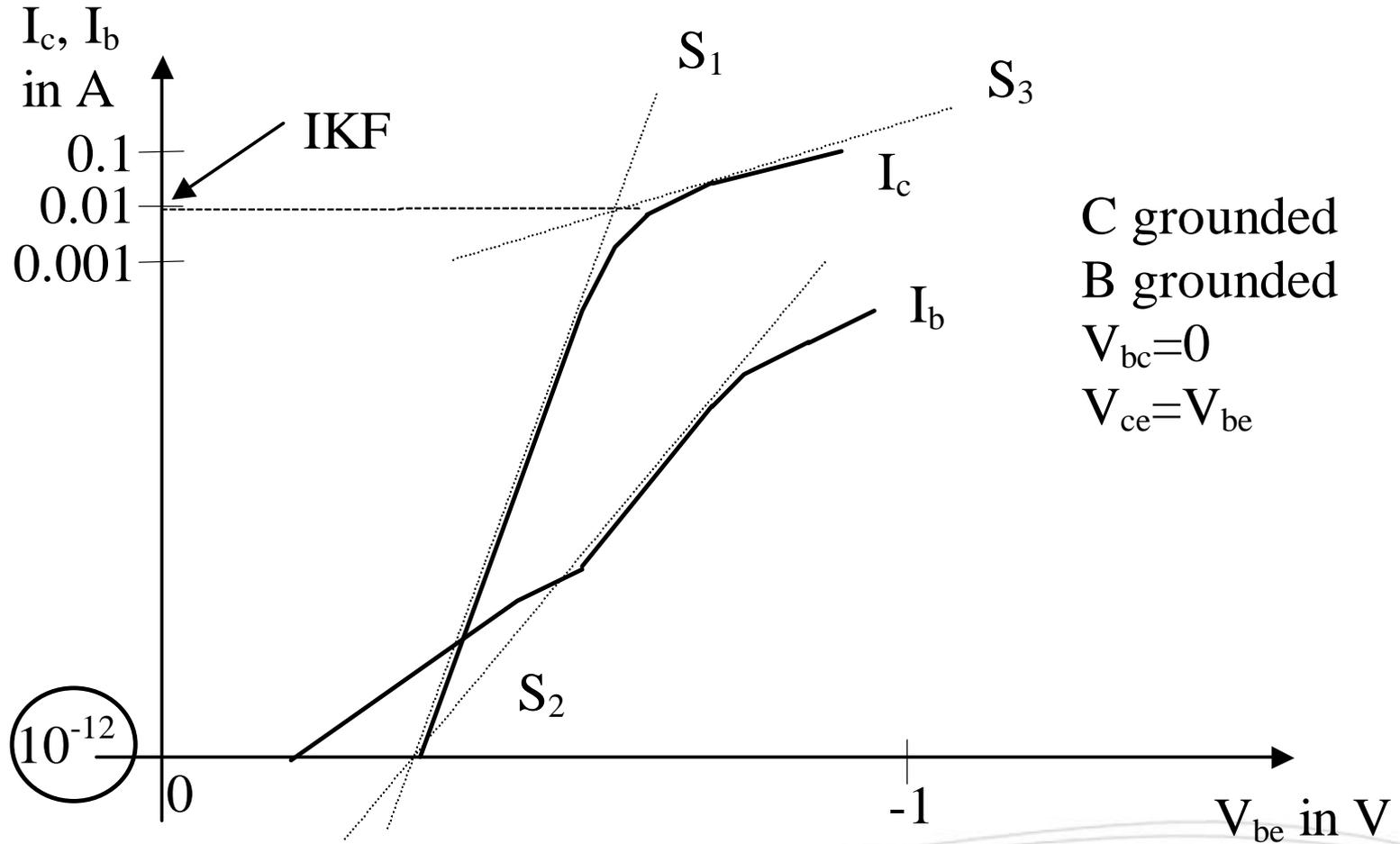


# Transistor transfer curves





# Gummel-Plots



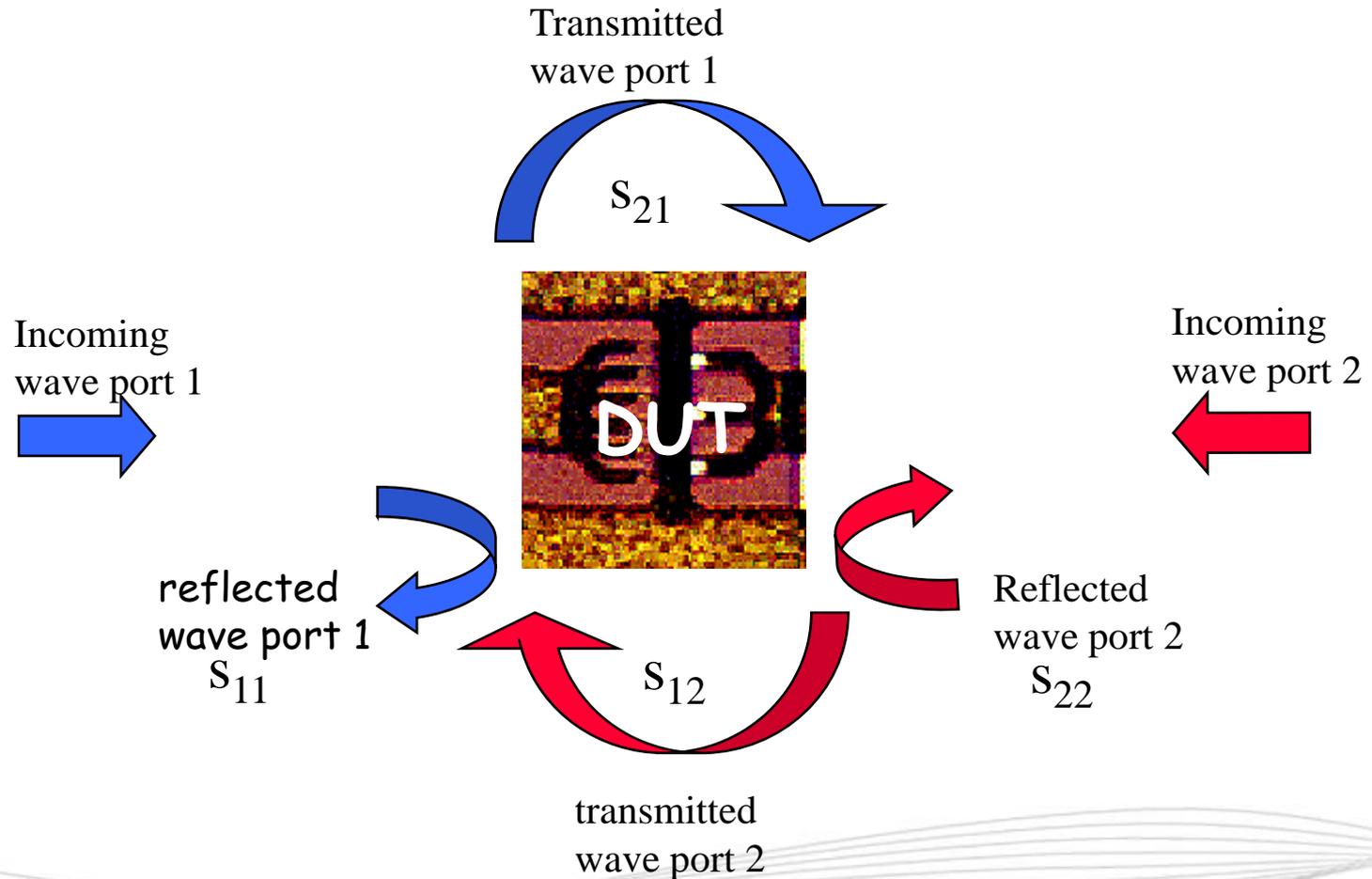
C grounded  
B grounded  
 $V_{bc} = 0$   
 $V_{ce} = V_{be}$





# RF measurements

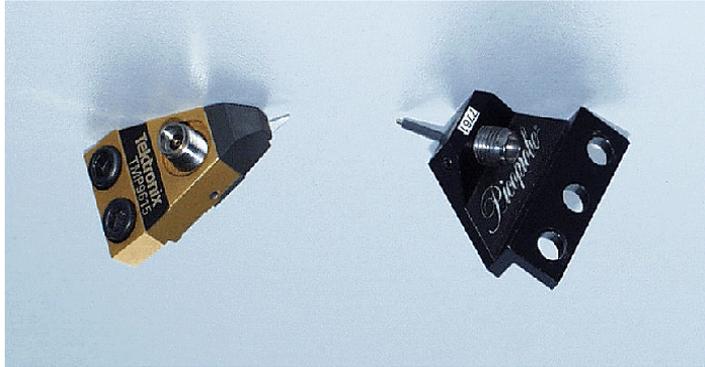
## S-parameter measurements





# RF measurements

## S-parameter measurements



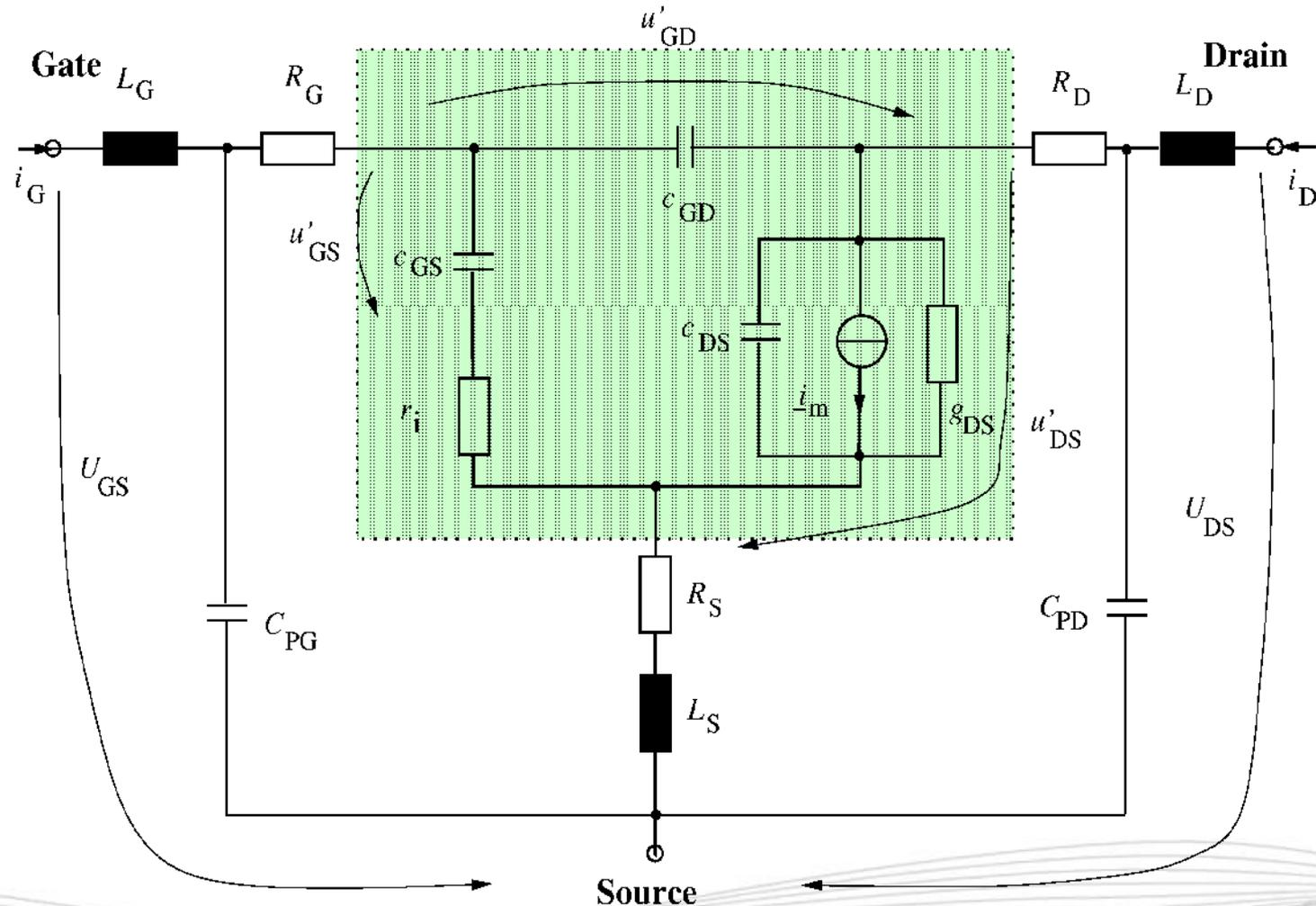


# Qualification

- Pinch-off of transistor device
- Enhancement or depletion mode
- Slope and IV curves
- Gate diode current
- amplification  $s_{21}$  and attenuation
- Compression behavior
- Other s-parameters  $< 0$  dB

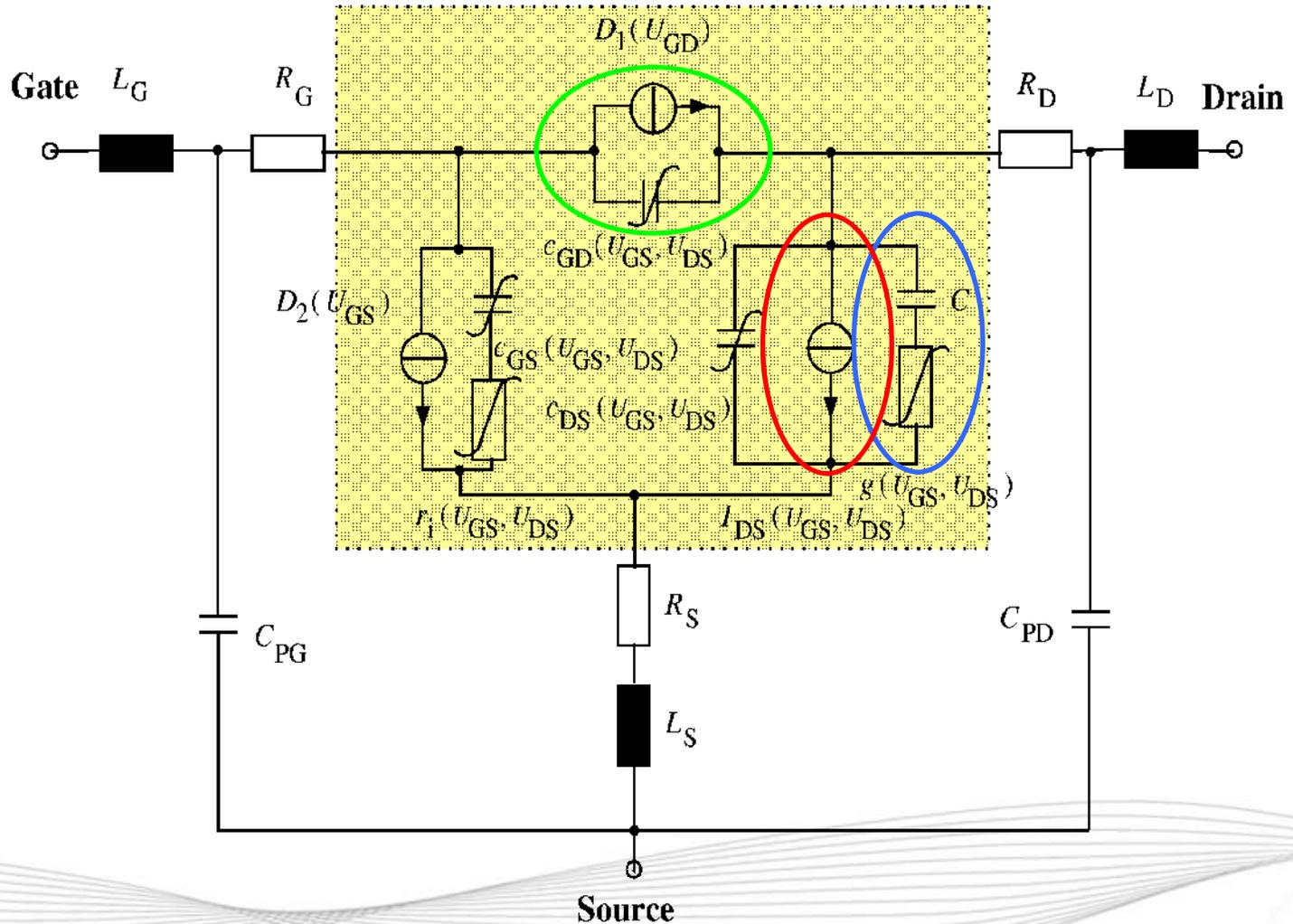


# Small signal equivalent circuit





# Enhanced small signal equivalent circuit



# Parameter extraction

S-Parameter  
IV curves



Extrinsic  
elements

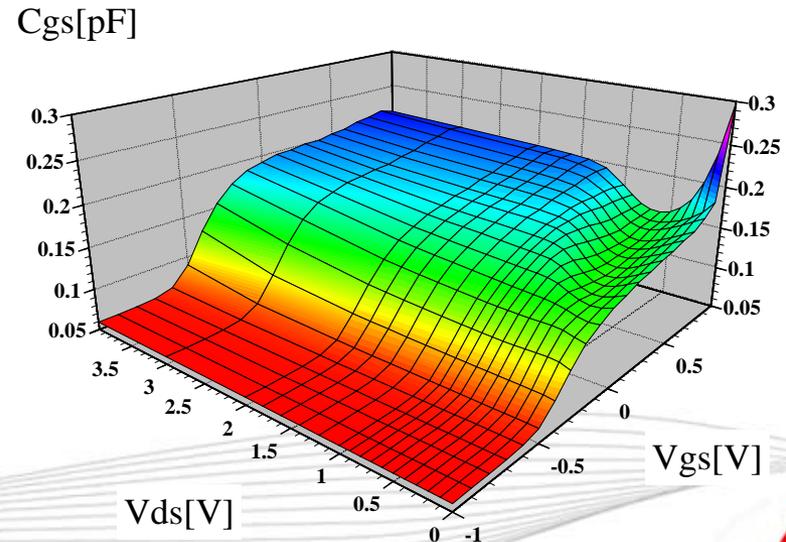
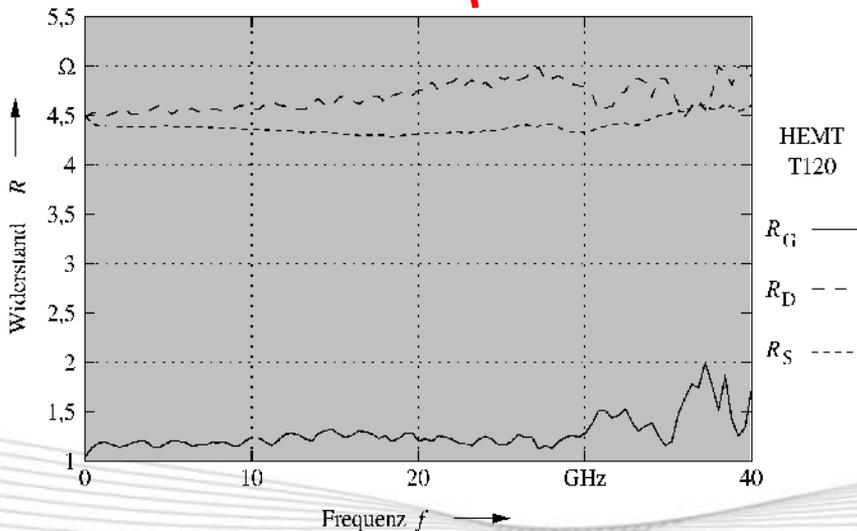


Intrinsic  
elements



$$R_S = \text{Re}\{z_{12}\}$$

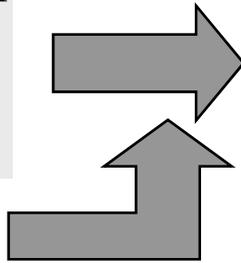
$$C_{GS}(V_{GS}, V_{DS}) = \sum_{f=f_1}^{f_2} \frac{1}{\omega} \left( \text{Im}\{y_{11}(V_{GS}, V_{DS})\} + \text{Im}\{y_{12}(V_{GS}, V_{DS})\} \right) / (n_{f2} - n_{f1})$$





# Parameter extraction

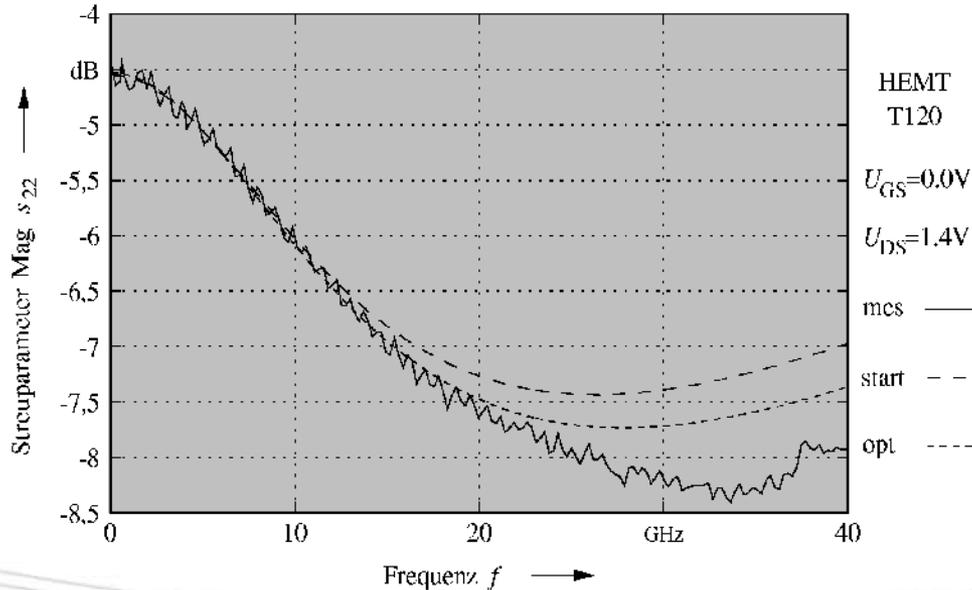
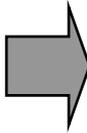
Optimization of  
intrinsic  
elements



Calculation of  
conductance  $g$



De-embedding  
of  
voltages



$$V'_{GS} = V_{GS} - I_{DS} R_S$$

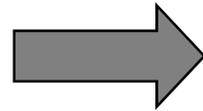
$$V'_{DS} = V_{DS} - I_{DS} (R_D + R_S)$$





# Parameterextraktion

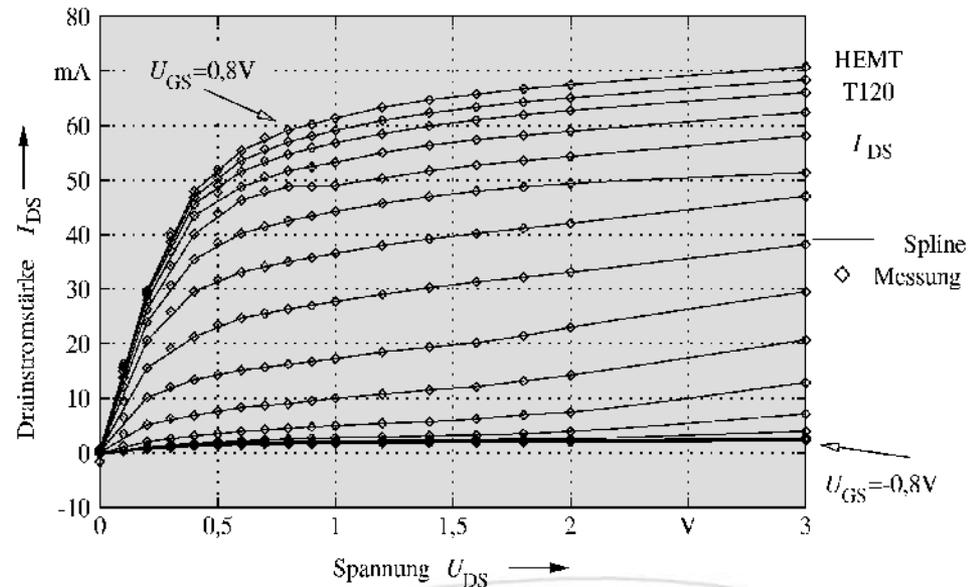
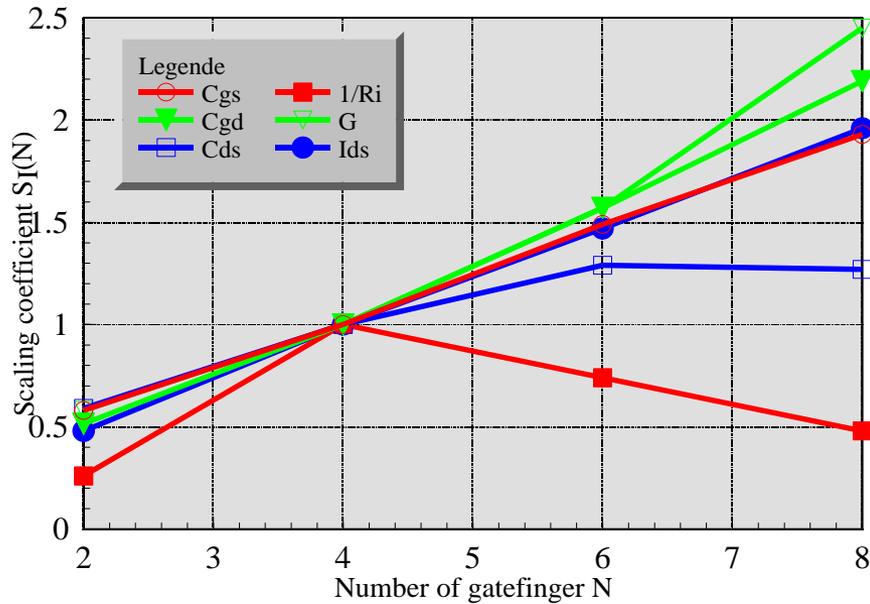
Calculation of scaling and noise parameters



Description of intrinsic elements



Store the Simulation file



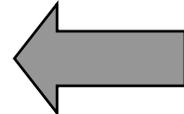
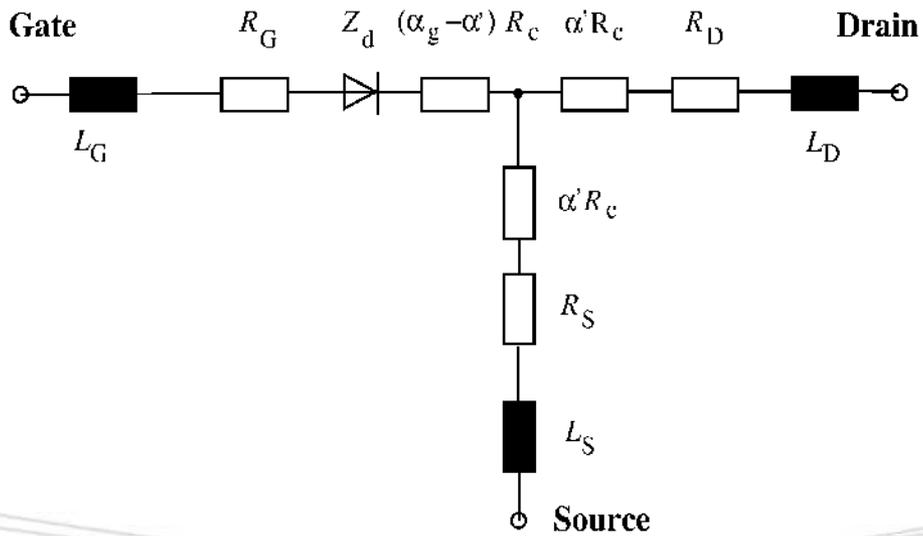
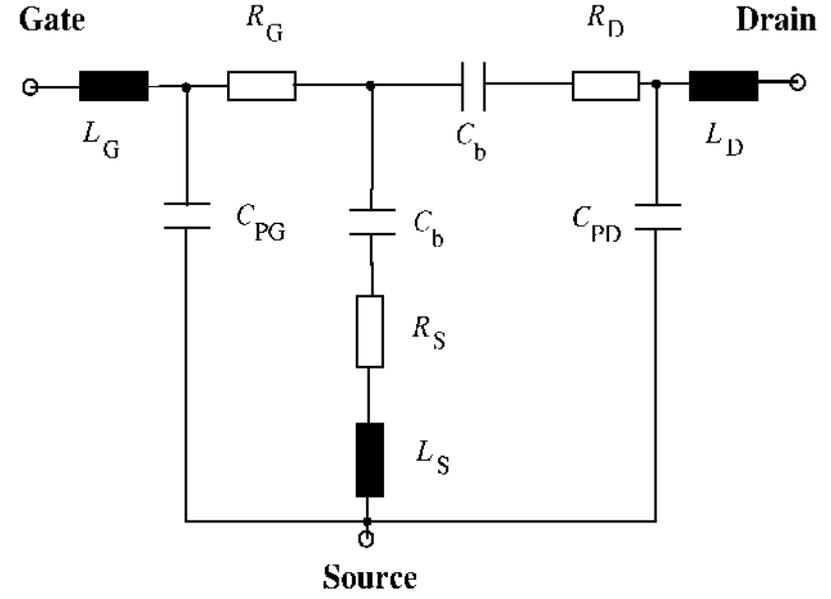
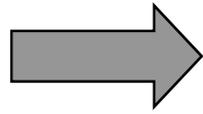


# Extraction of extrinsic elements

## Extraction of capacitances

$$V_{GS} < V_p$$

$$V_{DS} = 0 \text{ V}$$



## Extraction of inductances and resistors

$$V_{GS} > 0 \text{ V}$$

$$V_{DS} = 0 \text{ V}$$



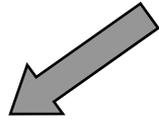


# Extraction of intrinsic elements

$$\underline{S} \rightarrow \underline{Z}$$



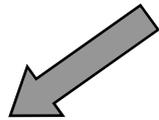
$$\begin{pmatrix} \underline{z}_{11} - j\omega L_G & \underline{z}_{12} \\ \underline{z}_{21} & \underline{z}_{22} - j\omega L_D \end{pmatrix}$$



$$\underline{Z} \rightarrow \underline{Y}$$



$$\begin{pmatrix} \underline{y}_{11} - j\omega C_{PG} & \underline{y}_{12} \\ \underline{y}_{21} & \underline{y}_{22} - j\omega C_{PD} \end{pmatrix}$$



$$\underline{Y} \rightarrow \underline{Z}$$

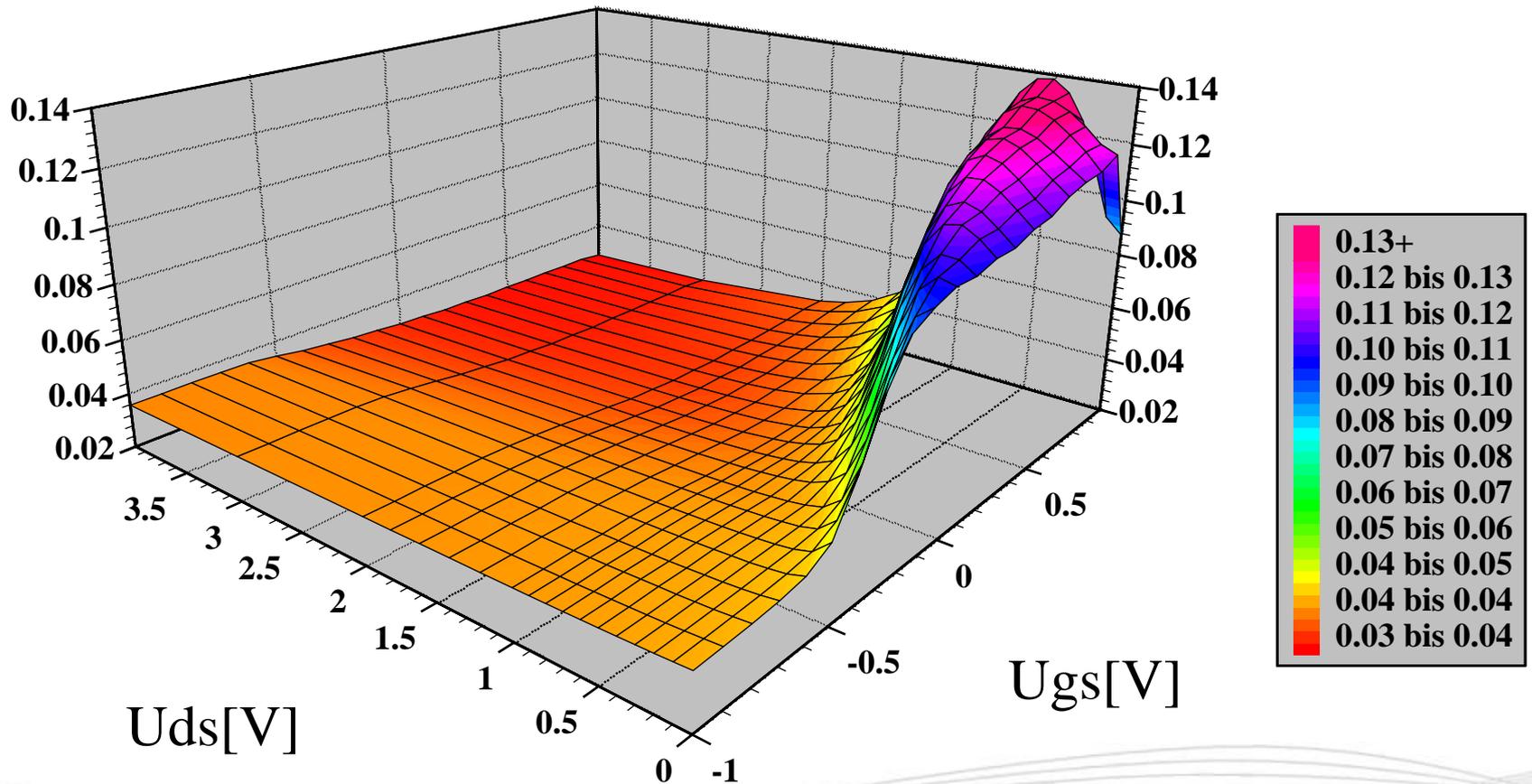


$$\begin{pmatrix} \underline{z}_{11} - R_S - R_G - j\omega L_S & \underline{z}_{12} - R_S - j\omega L_S \\ \underline{z}_{21} - R_S - j\omega L_S & \underline{z}_{22} - R_S - R_D - j\omega L_S \end{pmatrix}$$



# Extraction of intrinsic elements

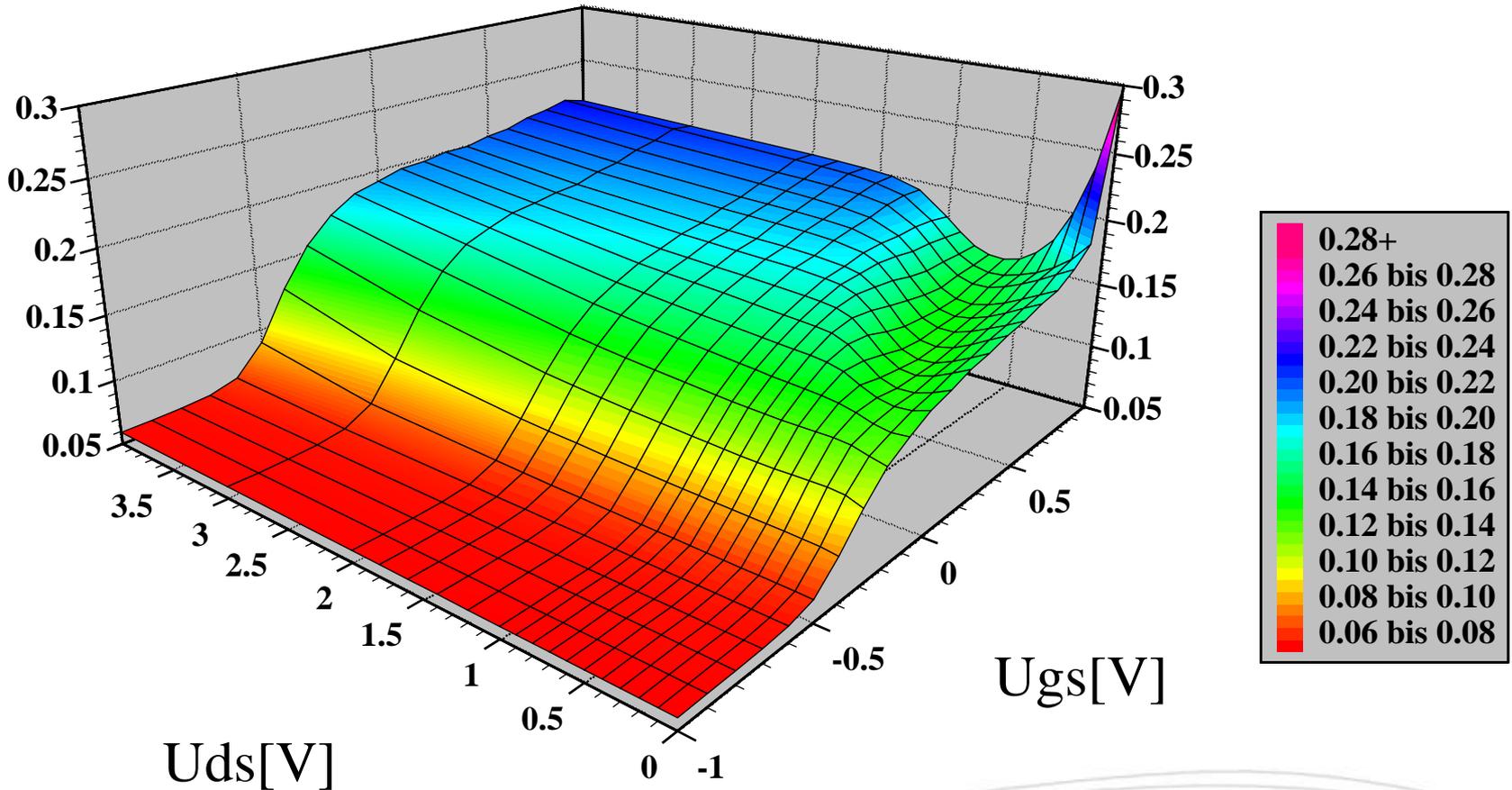
$C_{gd}[\text{pF}]$





# Extraction of intrinsic elements

$C_{gs}$ [pF]

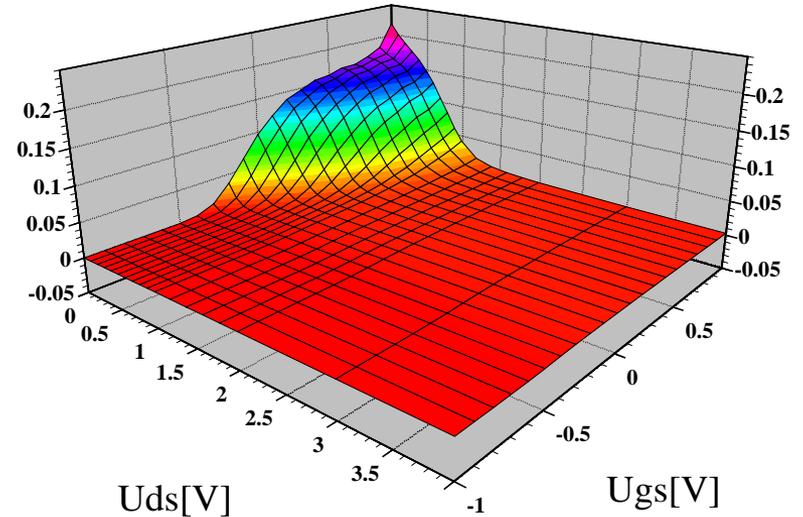




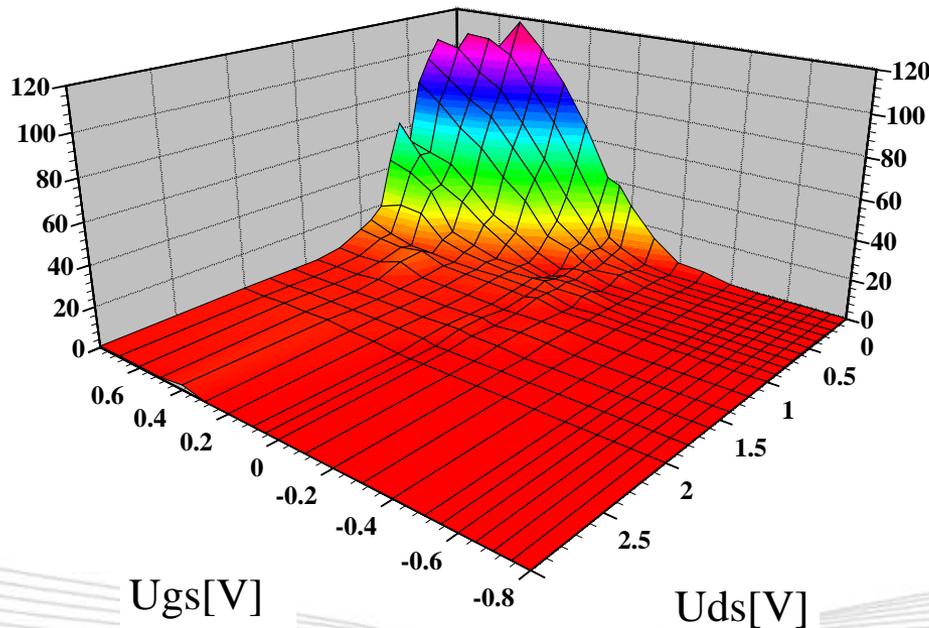
# Calculation of output conductance

## Extraction of output conductance $g$ using optimizing process

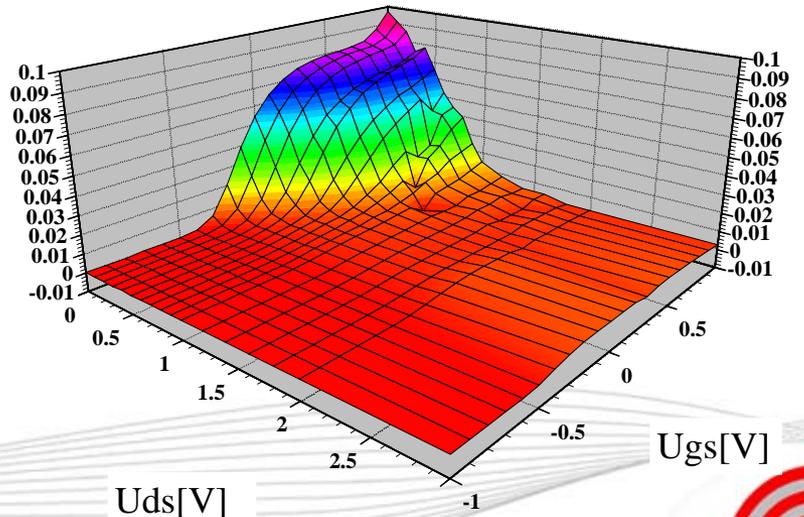
$g_d$  (HF) [S]



$g$  [mS]



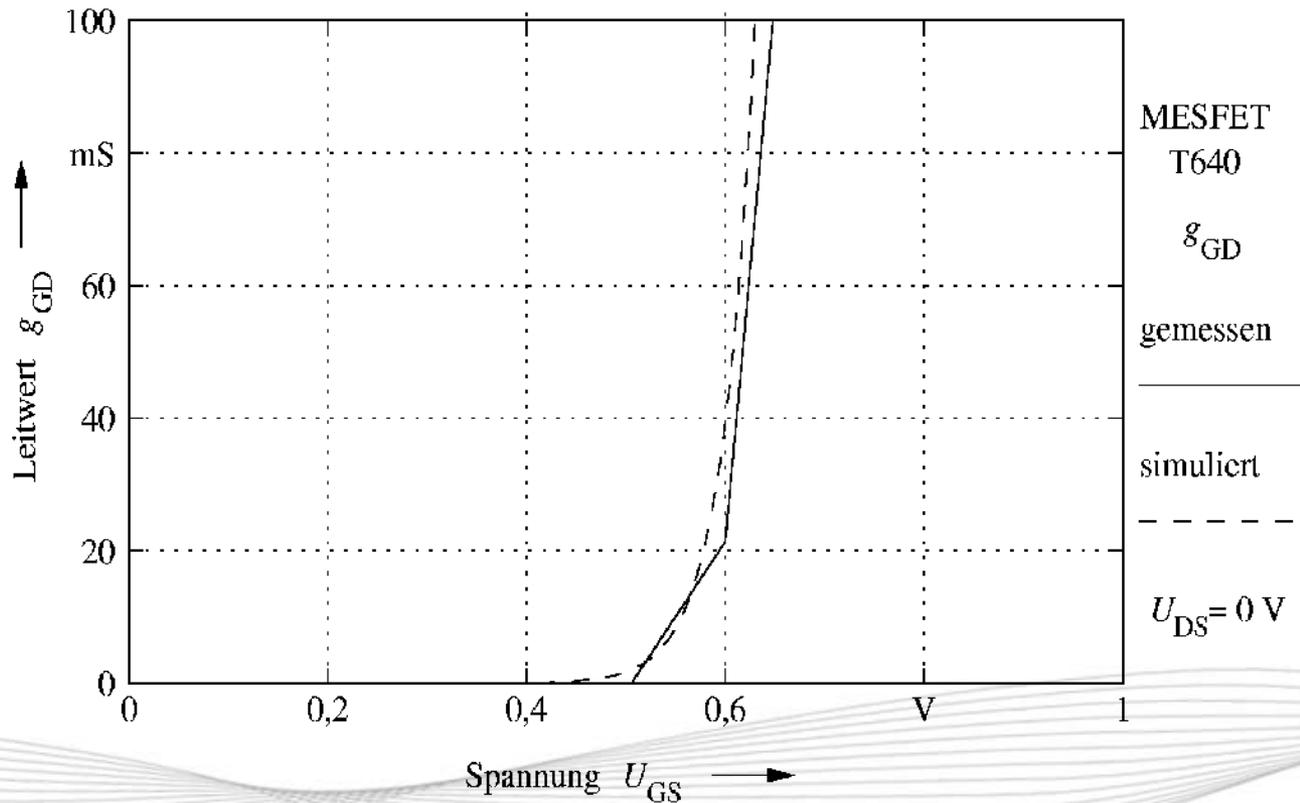
$g_d$  (DC) [S]





# Extraction of $I_S$ and $n$

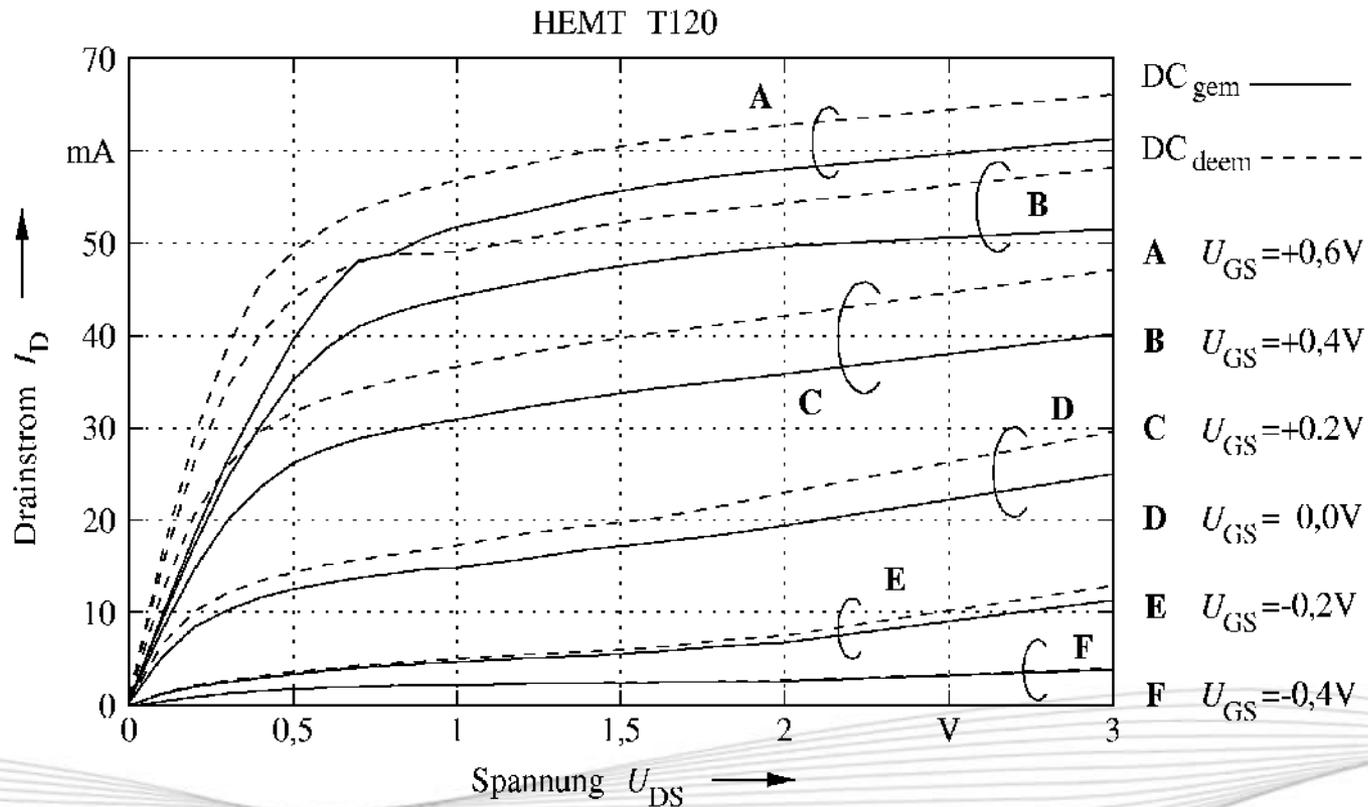
$$\operatorname{Re} \left\{ \underline{y}_{12} \right\} = - \frac{dI_{d1}}{dU_{GD}} = - \frac{I_S}{nU_t} \exp\left( \frac{U_{GD}}{nU_t} \right)$$



# Outer and inner voltages

$$V'_{GS} = V_{GS} - I_{DS} R_S$$

$$V'_{DS} = V_{DS} - I_{DS} (R_D + R_S)$$



# Description of intrinsic elements

$$c_{GS} = \begin{cases} k_h + k_g U_{DS} + x_{20} & U_{DS} > 0 \\ k_h + x_{20} & \text{sonst} \end{cases}$$

$$k_a = \begin{cases} x_0 (U_{GS} - x_1)^2 & U_{GS} \geq x_1 \\ 0 & \text{sonst} \end{cases}$$

$$k_h = k_a (\exp(k_b (U_{DS} - k_c)^2)) + k_d (\tanh(k_e (U_{DS} - k_f)) + 1)$$

$$k_b = x_2 (\tanh(x_3 (U_{GS} - x_{17})) + 1)$$

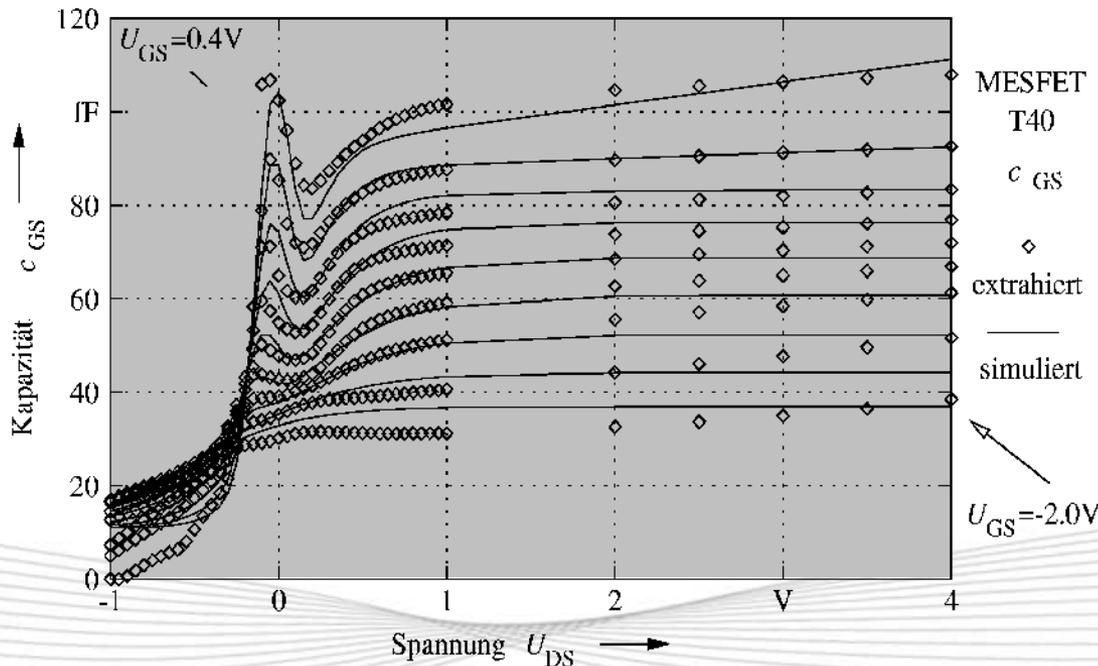
$$k_c = x_4 \exp(x_5 (U_{GS} - x_6)^2)$$

$$k_d = x_7 (\tanh(x_{21} (U_{GS} - x_8)) + 1)$$

$$k_e = x_9 (U_{GS} - x_{10})^2 + x_{11}$$

$$k_f = x_{12} \exp(x_{13} (U_{GS} - x_{14})^2) + x_{18}$$

$$k_g = x_{15} \exp(x_{16} (U_{GS} - x_{19})^2)$$





# Large signal simulation

$$Q_1(u_1) = \int_{u_{10}}^{u_1} c(\tilde{u}_1) d\tilde{u}_1$$

$$\Delta Q = \oint_{\partial\Omega} c(\tilde{u}_1) d\tilde{u}_1 = 0$$

$$Q_2(u_1, u_2) = \int_{u_{10}}^{u_1} c(\tilde{u}_1, u_2) d\tilde{u}_1 + Q'_1(u_2)$$

**Defined charge cycle**

**Trans elements**

$$C(u_1, u_2) = \sum_{i=0}^n c_i(u_1) T_i(u_2)$$

**Complete gate current**

$$i_G = i_{GS} + i_{GD}$$

$$u_{GS} = U_{GS} + u_{GS\sim} \Rightarrow \frac{du_{GS}}{dt} = \frac{du_{GS\sim}}{dt}$$

**GS-part of gate current**

$$i_{GS} = \frac{dQ_{GS}}{dt} = C'_{GS}(u_{GS}, u_{DS}) \frac{du_{GS}}{dt}$$





# Large signal simulation

$$i_{GS} = C'_{GS}(U_{GS} + u_{GS\sim}, U_{DS} + u_{DS\sim}) \frac{du_{GS\sim}}{dt}$$

**Taylor-series**

$$\begin{aligned} C'_{GS}(U_{GS} + u_{GS\sim}, U_{DS} + u_{DS\sim}) &= C'_{GS}(U_{GS}, U_{DS}) \\ &+ \left. \frac{\partial C'_{GS}(u_{GS}, u_{DS})}{\partial u_{GS}} \right|_{\substack{u_{GS}=U_{GS} \\ u_{DS}=U_{DS}}} u_{GS\sim} \\ &+ \left. \frac{\partial C'_{GS}(u_{GS}, u_{DS})}{\partial u_{DS}} \right|_{\substack{u_{GS}=U_{GS} \\ u_{DS}=U_{DS}}} u_{DS\sim} + \dots \end{aligned}$$

**GS-part of gate current**

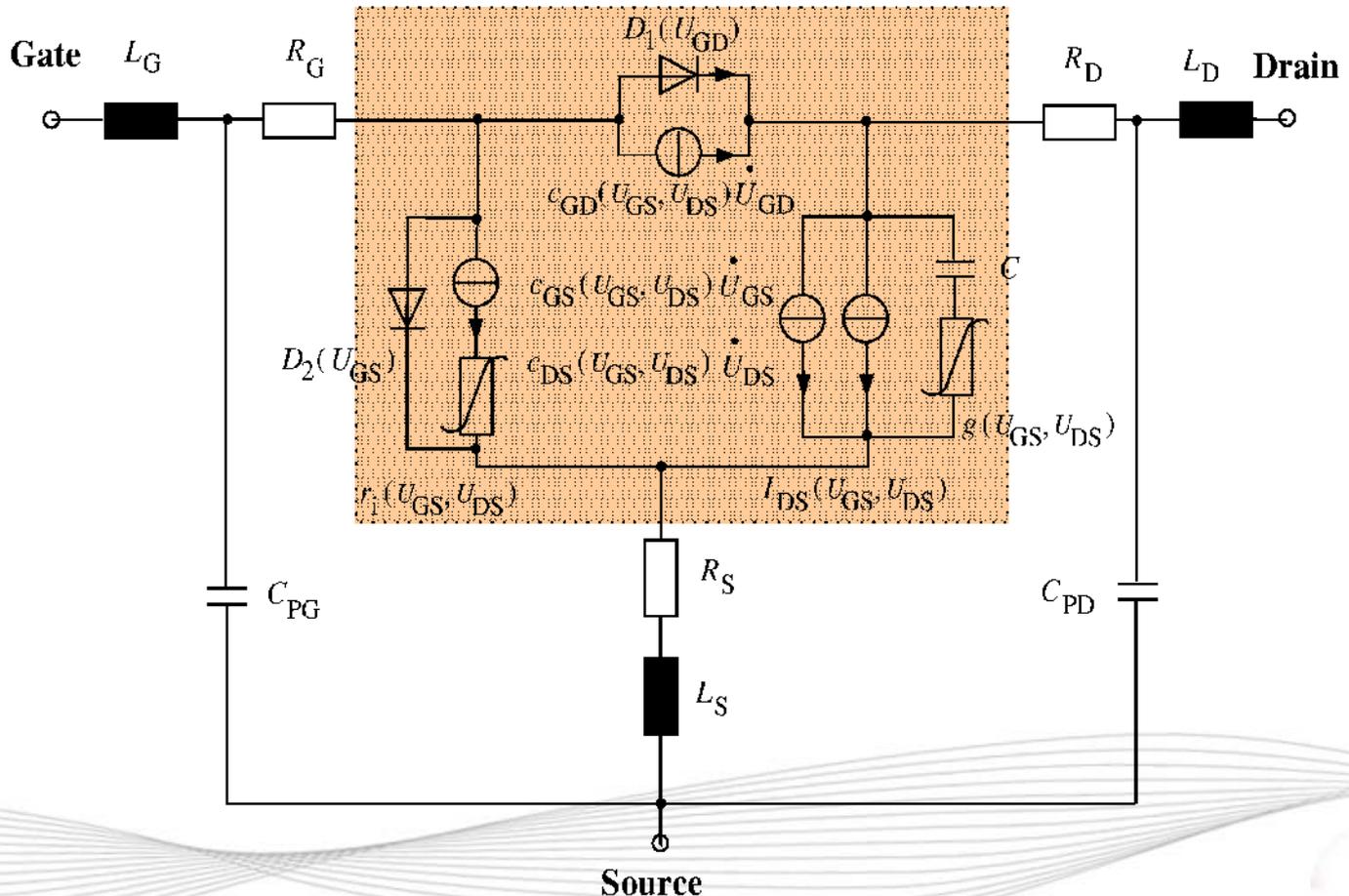
$$i_{GS} = c_{GS}(U_{GS}, U_{DS}) \frac{du_{GS}}{dt}$$





# Large signal simulation

$$i_G = \frac{dQ(u_{GS}, u_{DS})}{dt} = \frac{\partial Q(u_{GS}, u_{GD})}{\partial u_{GS}} \frac{du_{GS}}{dt} + \frac{\partial Q(u_{GS}, u_{GD})}{\partial u_{GD}} \frac{du_{GD}}{dt}$$





# Large signal simulation

Due to designation of 2 voltages of  $V_{gs}$ ,  $V_{ds}$  and  $V_{gd}$ , the third voltage is always defined!

## Case 1: Gate charge is known

$$Q_G = au_{GS}^2 + bu_{GS}u_{DS} + au_{DS}^2$$

$$i_G = \frac{dQ(u_{GS}, u_{DS})}{dt} = \frac{\partial Q_G(u_{GS}, u_{GD})}{\partial u_{GS}} \frac{du_{GS}}{dt} + \frac{\partial Q_G(u_{GS}, u_{GD})}{\partial u_{GD}} \frac{du_{GD}}{dt}$$

$$u_{DS} = f \cos(\omega t) \quad u_{GS} = e \sin(\omega t)$$

$$i_G = \omega(A \sin(2\omega t) + B \cos(2\omega t))$$

$$A = ae^2 - cf^2$$

$$B = bef$$

**Pure capacitive gate current, no DC part**



# Large signal simulation

## Case 2: The capacitances are known

$$c_{DS}(u_{GS}, u_{DS}) = \left. \frac{\partial Q_G}{\partial u_{DS}} \right|_{u_{GS}=\text{const.}} = bu_{GS} + 2cu_{DS}$$

$$c_{GS}(u_{GS}, u_{DS}) = \left. \frac{\partial Q_G}{\partial u_{GS}} \right|_{u_{DS}=\text{const.}} = 2au_{GS} + bu_{DS}$$

$$i_{GS} = \omega(C + D \sin(2\omega t) + C \cos(2\omega t))$$

$$C = 0,5bef$$

$$D = ae^2$$

$$i_{GD} = \omega(-C + E \sin(2\omega t) + C \cos(2\omega t))$$

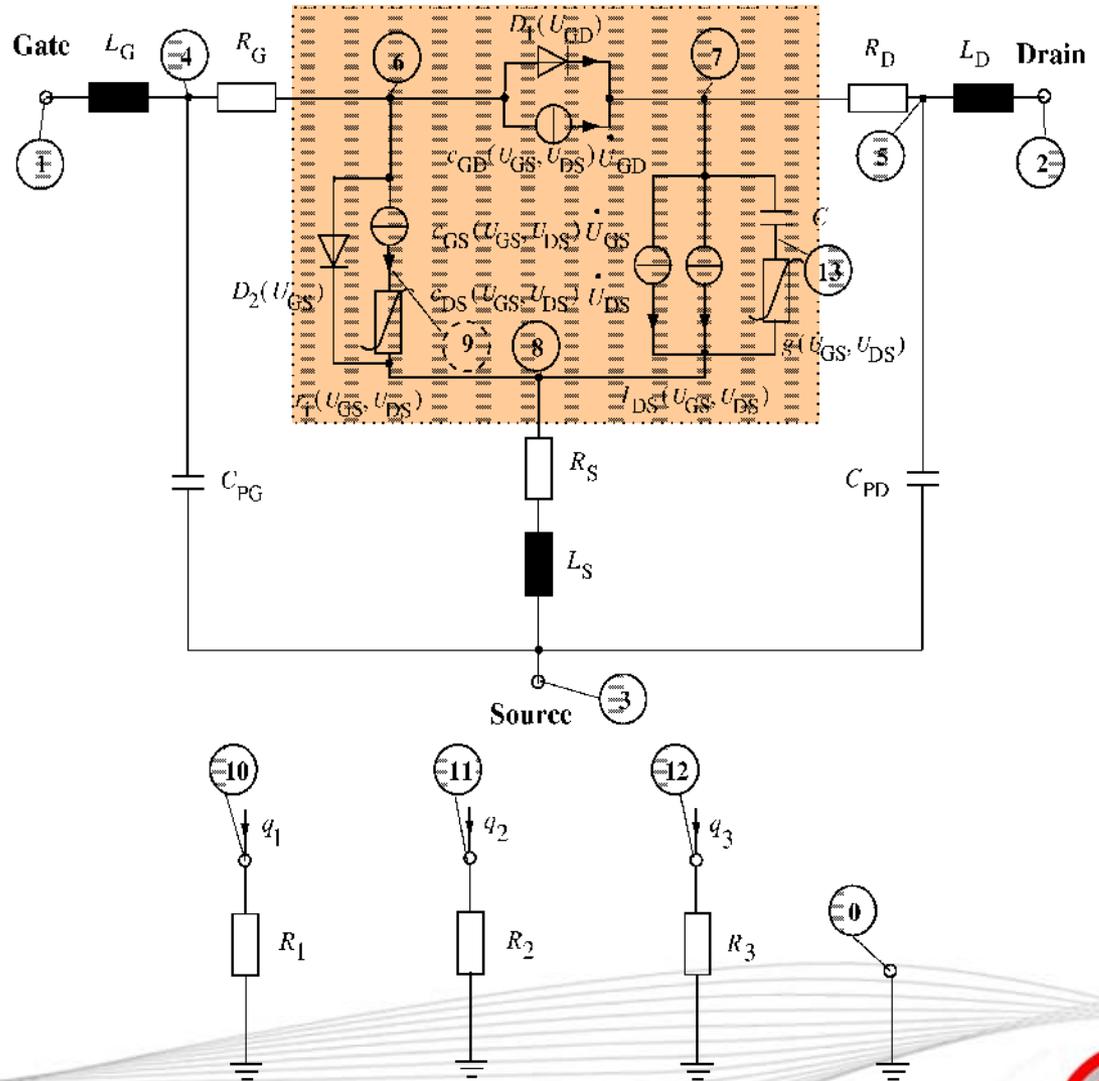
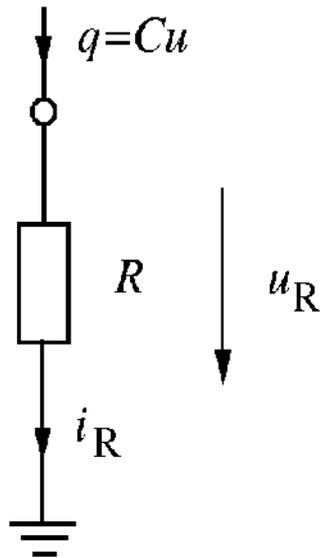
$$E = -cf^2$$

**DC current parts, which compensate each other**

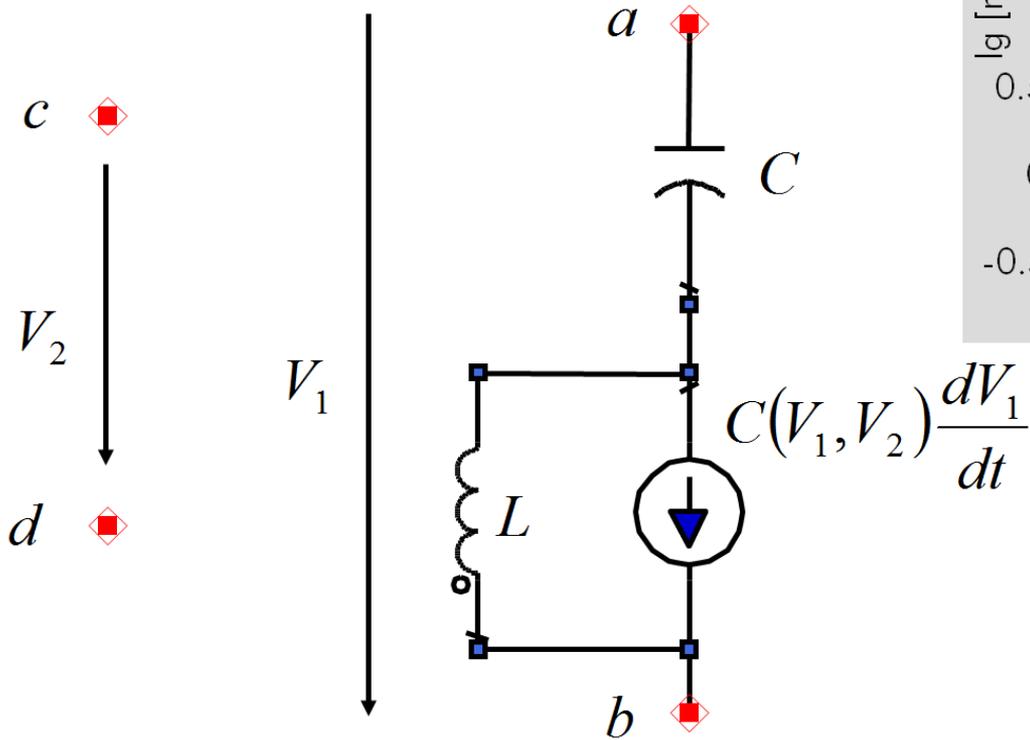
# Large signal simulation

$$i_R = \dot{q} = C \cdot \dot{V}$$

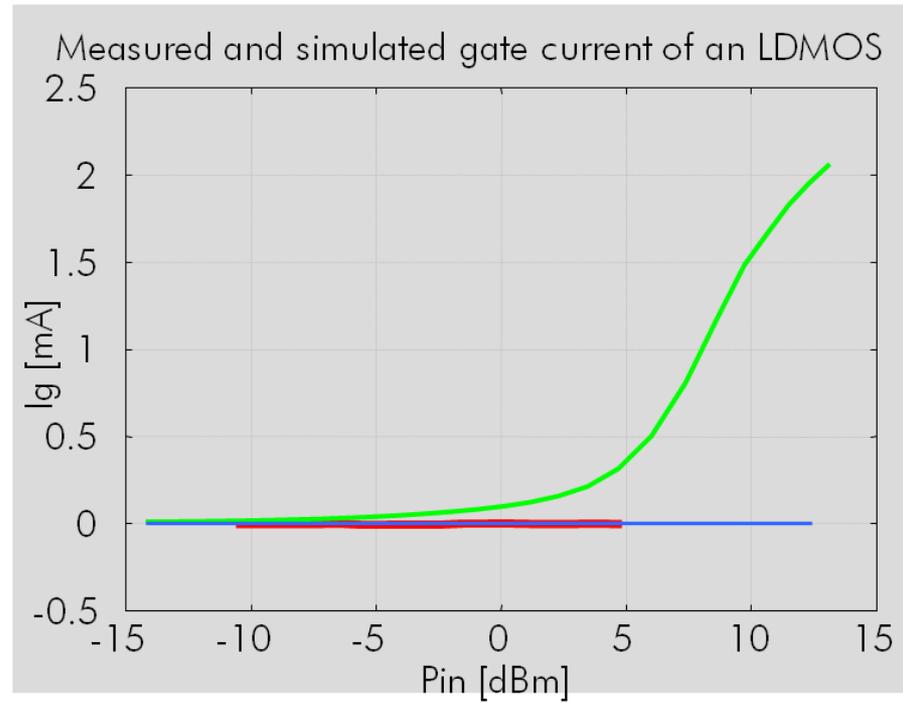
$$V_R = i_R R = CR \cdot \dot{V}$$



# Example

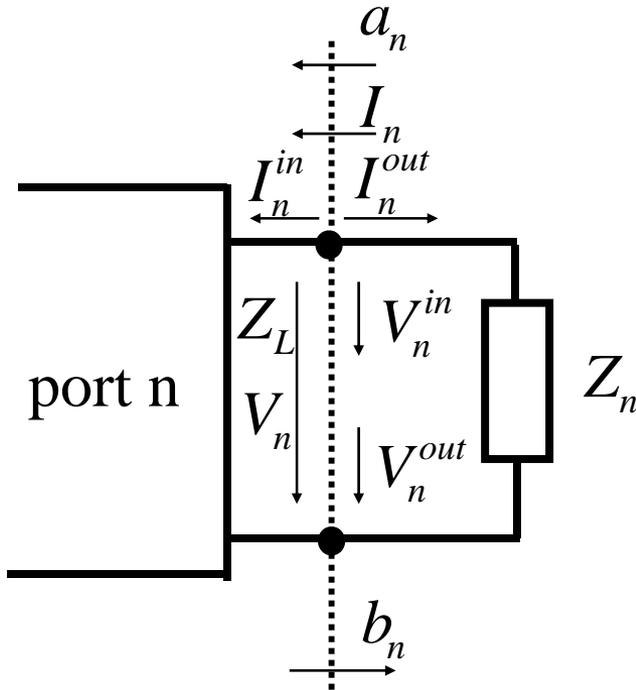


$L, C$  large



# Consistent implementation

Calculation of S-parameters using currents and voltages



Waves in an out of port n

$$a_n = \frac{V_n^{in}}{\sqrt{Z_{Ln}}} = I_n^{in} \sqrt{Z_{Ln}}$$

$$b_n = \frac{V_n^{out}}{\sqrt{Z_{Ln}}} = I_n^{out} \sqrt{Z_{Ln}}$$

Voltages and currents on the line

$$u_n = \frac{V_n}{\sqrt{Z_{Ln}}} = \frac{V_n^{in} + V_n^{out}}{\sqrt{Z_{Ln}}} = a_n + b_n$$

$$i_n = I_n \sqrt{Z_{Ln}} = (I_n^{in} - I_n^{out}) \sqrt{Z_{Ln}} = a_n - b_n$$

$$\Rightarrow \begin{cases} a_n = \frac{1}{2}(u_n + i_n) \\ b_n = \frac{1}{2}(u_n - i_n) \end{cases} \Rightarrow$$

S-Matrix

$$\|b\| = \|s\| \cdot \|a\|$$

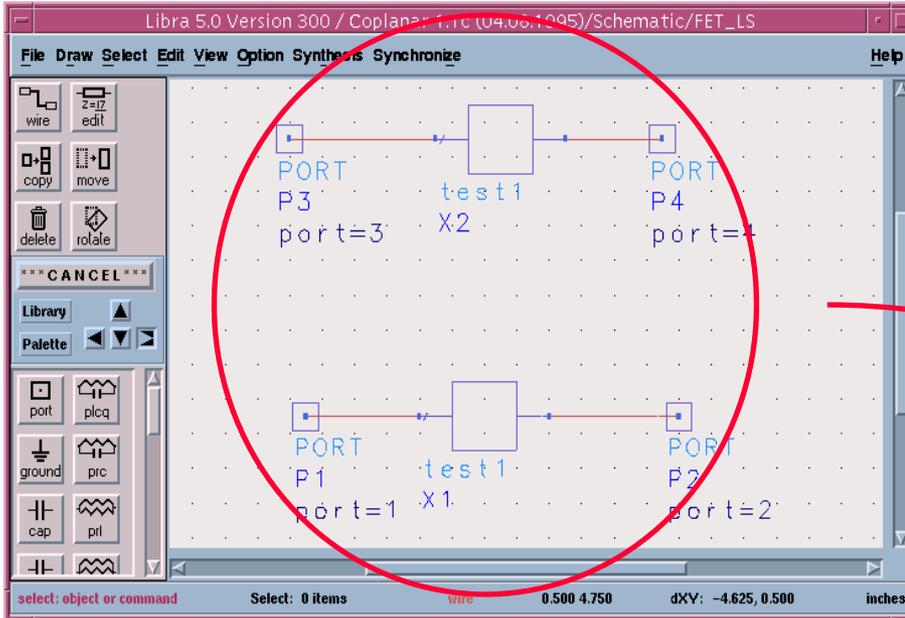
Example

$$s_{11} = \left. \frac{b_1}{a_1} \right|_{a_2=0}$$

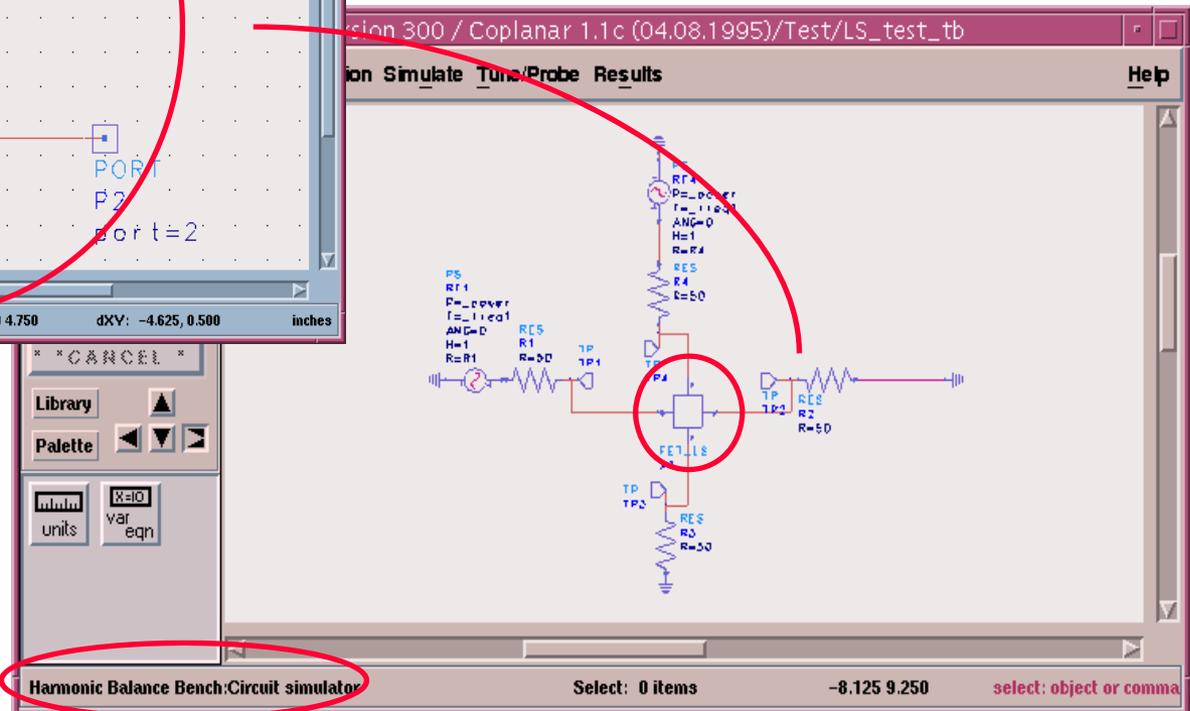
$$s_{11,dB} = 20 \cdot \log \frac{u_1 - i_1}{u_1 + i_1}$$

# Consistent implementation

Calculation of small signal s-parameters  
Using a harmonic balance large signal testbench



Harmonic balance testbench



# Consistent implementation

```

OUTPUT
EQUATION
OUTEON
_QUTEON
a11=VFC1/7.07+IFC1*7.07*1e-3
a22=VFC4/7.07+IFC4*7.07*1e-3
b11=VFC1/7.07-IFC1*7.07*1e-3
b22=VFC4/7.07-IFC4*7.07*1e-3
b21=VFC2/7.07-IFC2*7.07*1e-3
b12=VFC3/7.07-IFC3*7.07*1e-3
s11=20*log(b11/a11)
s11_ang=b11/a11
s22=20*log(b22/a22)
s22_ang=b22/a22
s21=20*log(b21/a11)
s21_ang=b21/a11
s12=20*log(b12/a22)
s12_ang=b12/a22
    
```

VFC1	IFC1	VFC2	IFC2	VFC3	IFC3
TP1 ID=TP1	ELEM=R1	TP1 ID=TP2	ELEM=R2	TP1 ID=TP3	ELEM=R3
TP2 ID=gnd	PIN=1	TP2 ID=gnd	PIN=1	TP2 ID=gnd	PIN=1
H1=1	H1=1	H1=1	H1=1	H1=1	H1=1
H2=0	H2=0	H2=0	H2=0	H2=0	H2=0
H3=0	H3=0	H3=0	H3=0	H3=0	H3=0

VFC4	IFC4
TP1 ID=TP4	ELEM=R4
TP2 ID=gnd	PIN=1
H1=1	H1=1
H2=0	H2=0
H3=0	H3=0

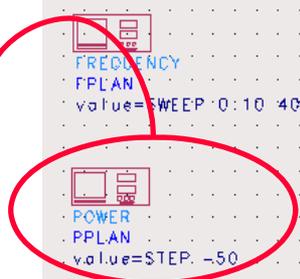
  

NH	Pout_RF	PIn	PSPEC
NH	TP1 ID=TP2	TP1 ID=TP1	PSPEC1
VALUE=5	TP2 ID=gnd	TP2 ID=gnd	TP1 ID=TP2
	ELEM=R2	ELEM=R1	TP2 ID=gnd
	H1=1	H1=1	ELEM=R2
	H2=0	H2=0	
	H3=0	H3=0	

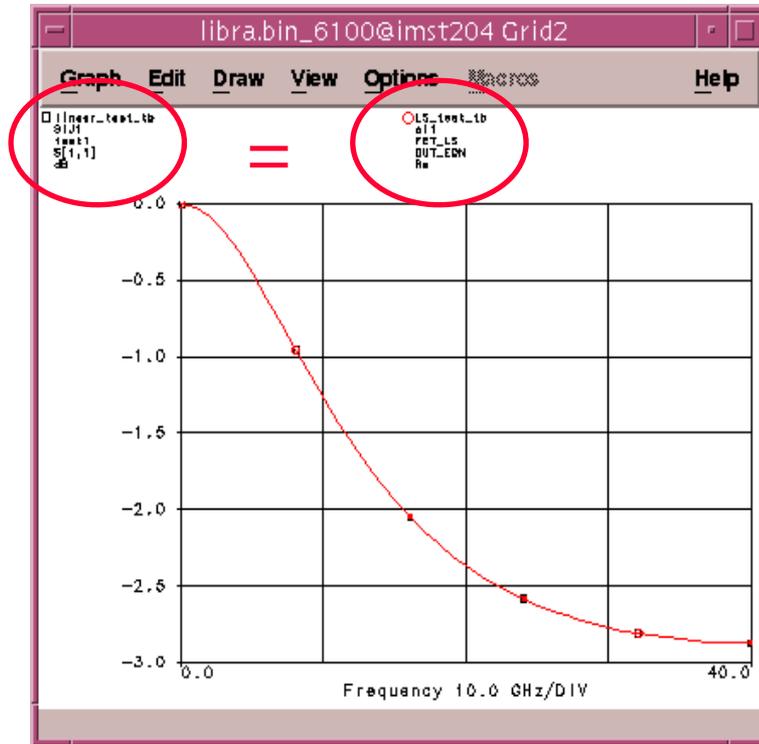
  

FREQUENCY	B1AS1	B1AS2	B1AS2
FPLAN	B1PLAN	B2PLAN	B2PLAN
value=SWEEP:0:10:40:1	value=STEP:0	value=STEP:0	value=STEP:2

Small signal  
-50 dBm

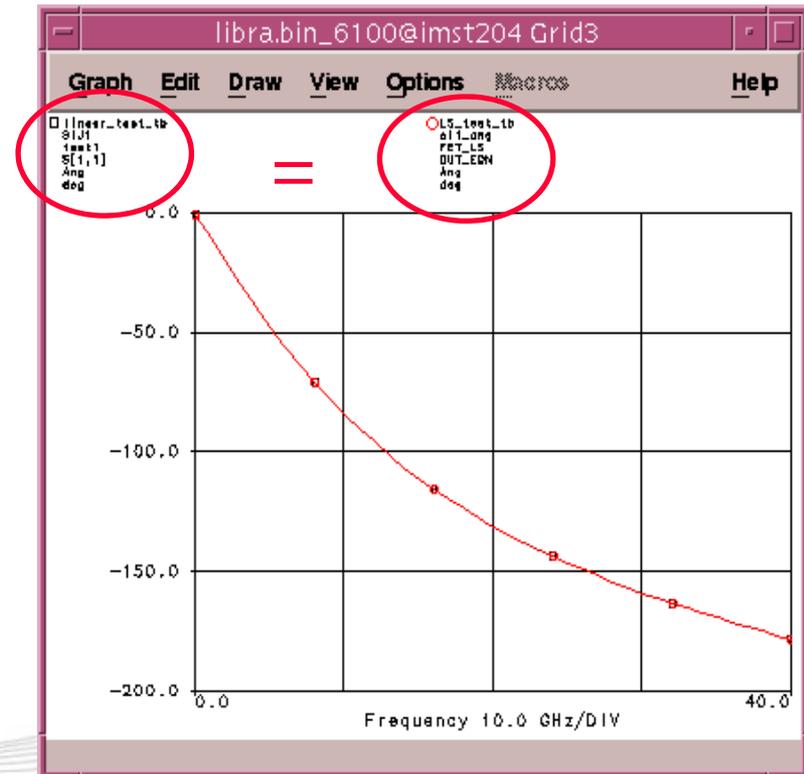


# Consistent implementation



Mag( $s_{11}$ ), simulated using  
Small signal and HB  
testbench for very low  
input power (-50 dBm)

Phase( $s_{11}$ ), simulated using  
Small signal and HB  
testbench for very low  
input power (-50 dBm)





# Needful things

Linearize exp functions

$$f(x) = \begin{cases} \exp(x) & x \leq x_0 \\ mx + b & x > x_0 \end{cases}$$

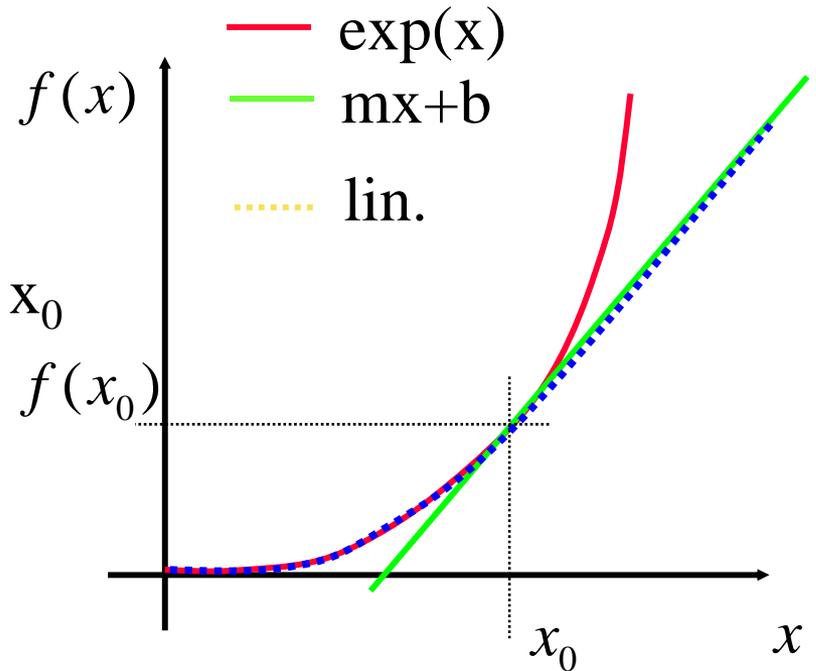
Function must be continuous at  $x_0$

$$f_1(x_0) = f_2(x_0) \quad \left. \frac{df_1}{dx} \right|_{x_0} = \left. \frac{df_2}{dx} \right|_{x_0}$$

$$\Rightarrow \exp(x_0) = mx_0 + b$$

$$m = \exp(x_0)$$

$$\Rightarrow b = \exp(x_0)(1 - x_0) \Rightarrow f_2(x) = \exp(x_0)(x + 1 - x_0)$$





# Noise sources

Thermal noise

$$\langle i_{th}^2 \rangle = \frac{4kT_0}{R} \Delta f$$

Popcorn (burst)-  
noise

$$\langle i_{burst}^2 \rangle = KB \frac{I_D^{CF}}{1 + \left( \frac{f}{f_{CF}} \right)^2} \Delta f$$

Shot-  
noise

$$\langle i_{shot}^2 \rangle = 2qI_D \Delta f$$

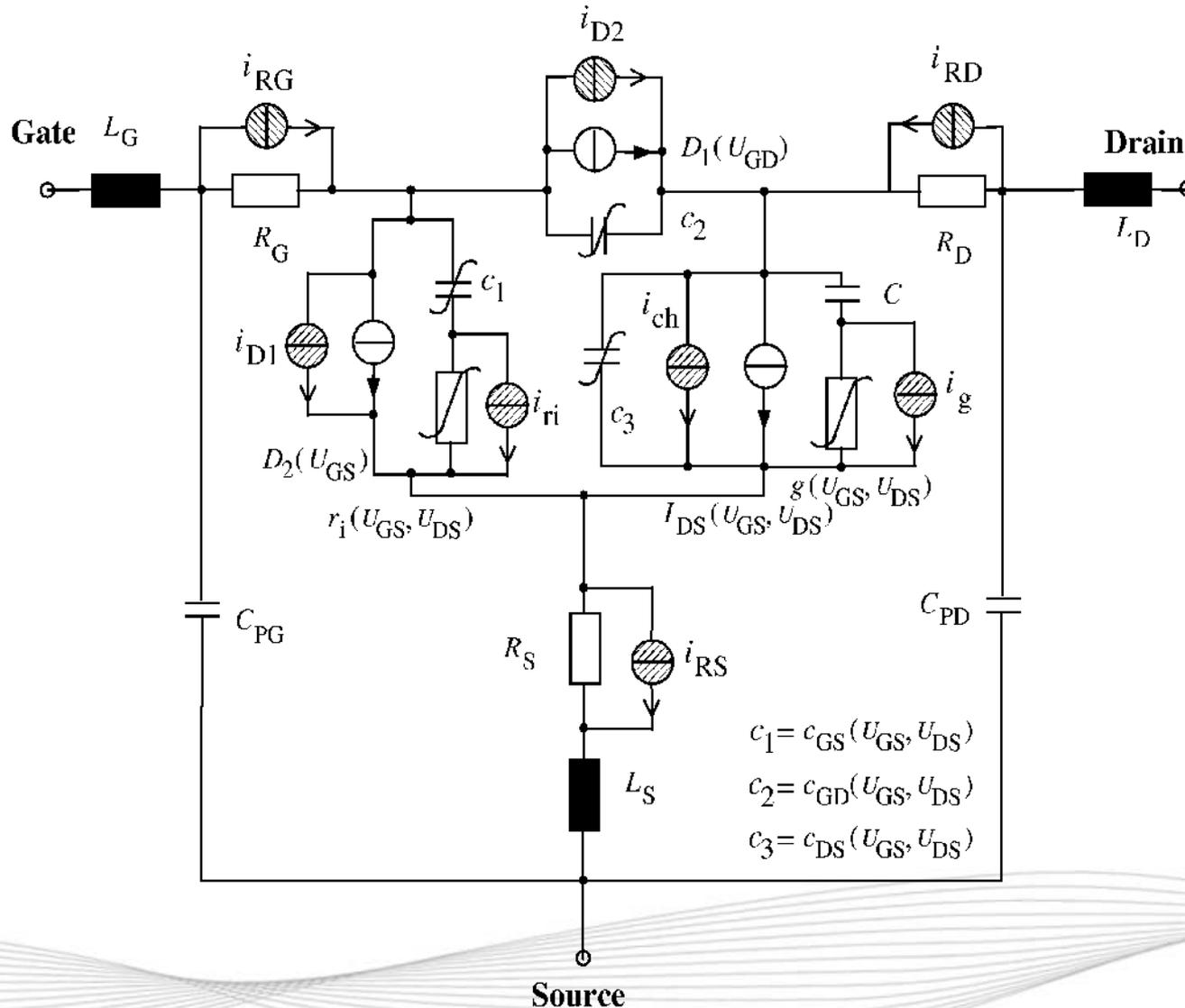
Channel noise

$$\langle i_c^2 \rangle = \frac{8kTg_m}{3} \Delta f$$

1/f (flicker)-  
noise

$$\langle i_{1/f}^2 \rangle = KF \frac{I_D^{AF}}{f^{FFE}} \Delta f$$

# Noise equivalent circuit





# Noisy 2-ports

## Transformation matrix

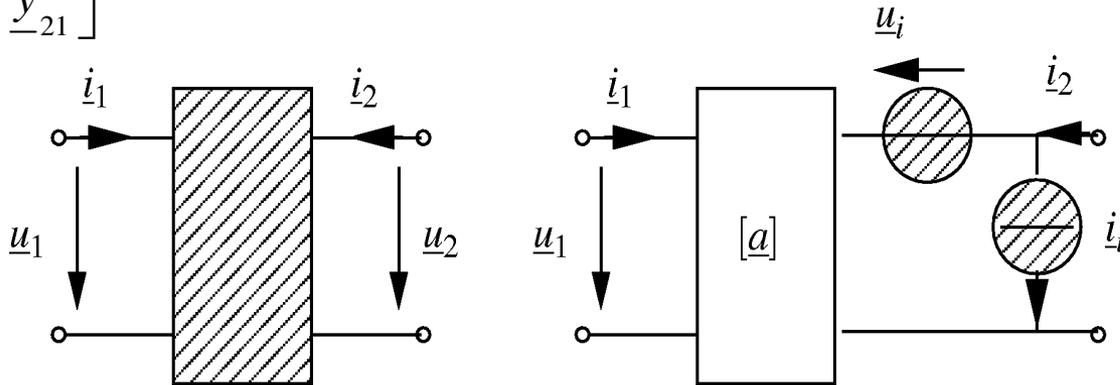
$$[T]^{(y \rightarrow a)} = \begin{bmatrix} 0 & -\frac{1}{y_{21}} \\ 1 & -\frac{y_{11}}{y_{21}} \end{bmatrix}$$

## Noise matrix

$$\begin{bmatrix} v_i^{(a)} \\ i_o^{(a)} \end{bmatrix} = [T]^{(y \rightarrow a)} \begin{bmatrix} i_i^{(y)} \\ i_o^{(y)} \end{bmatrix}$$

Diagram illustrating the noise matrix equation. The input voltage  $v_i^{(a)}$  is circled in green and labeled "input". The output current  $i_o^{(a)}$  is circled in blue and labeled "output".

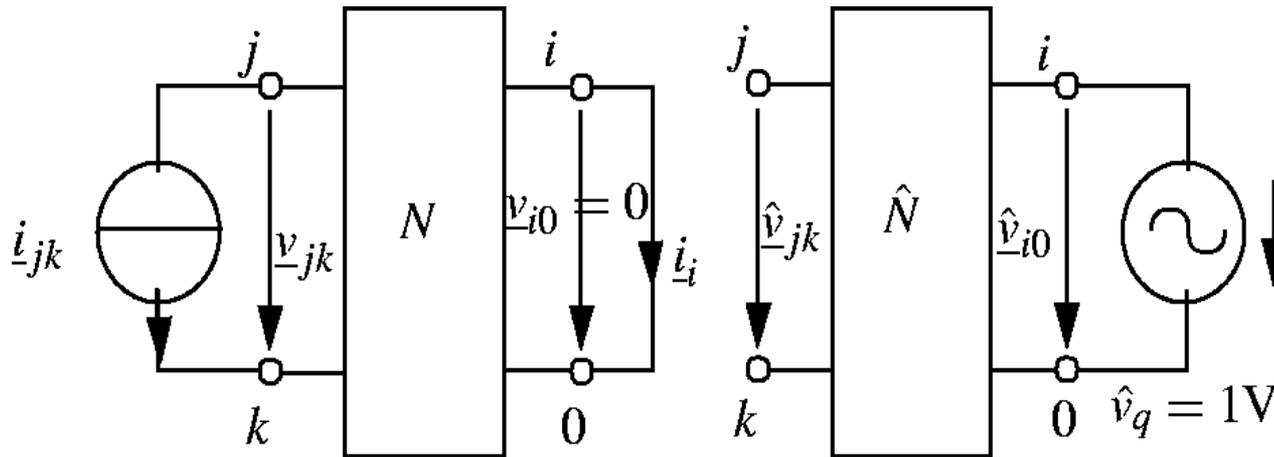
Transformation of noise sources.



## Correlation matrix, calculation of noise power

$$[C]^{(a)} = \frac{1}{4kT\Delta f} \left( \begin{bmatrix} v_i \\ i_i \end{bmatrix} \begin{bmatrix} v_i^* & i_i^* \end{bmatrix} \right)$$

# Separation of noise sources



Calculation of transformation function

**Network N**  
**Y-Matrix**

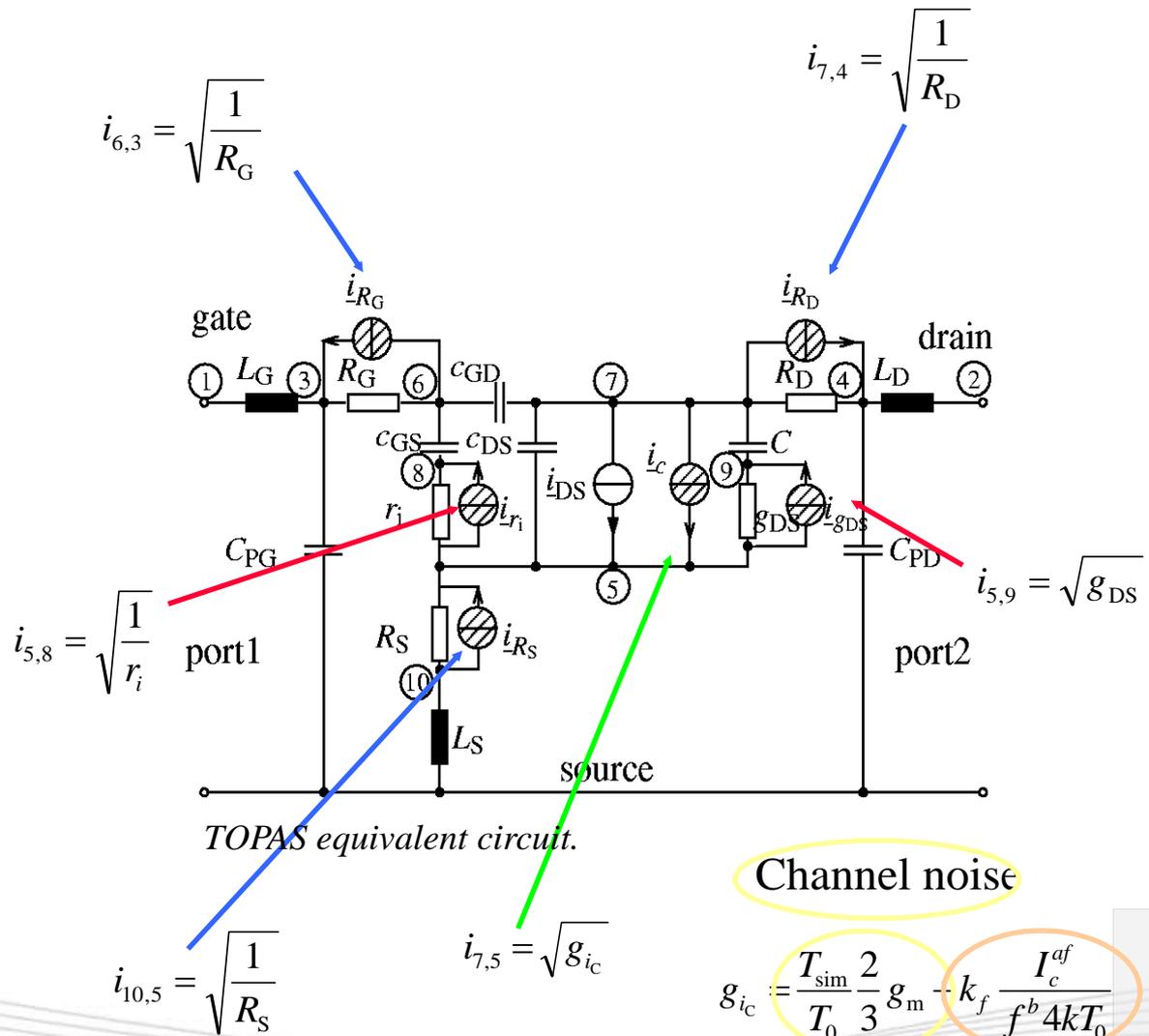
**Adjoint network**  
**transposed Y-Matrix**

**Current transforming function**

$$\alpha_{i,jk} = \frac{i_i}{i_{jk}} = -\frac{\hat{v}_{jk}}{\hat{v}_q}$$



# FET example



## Noise current matrix

$$[i_N] = \sqrt{4kT\Delta f} \cdot \begin{pmatrix} 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & i_{5,8} & i_{5,9} \\ 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & i_{6,3} & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & i_{7,4} & i_{7,5} & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & i_{10,5} & 0 & 0 & 0 & 0 & 0 \end{pmatrix}$$

Channel noise

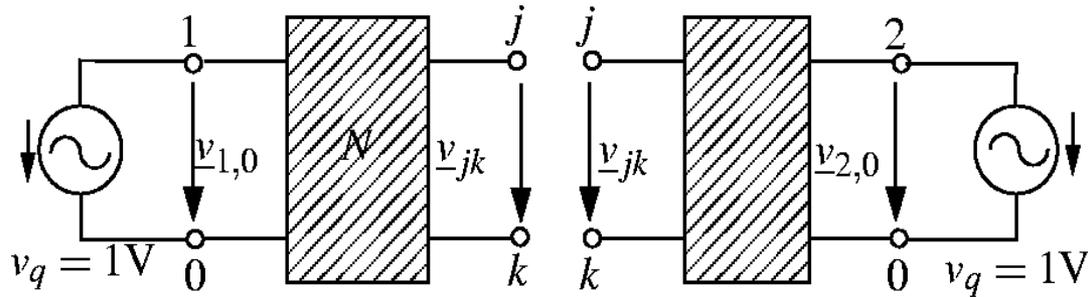
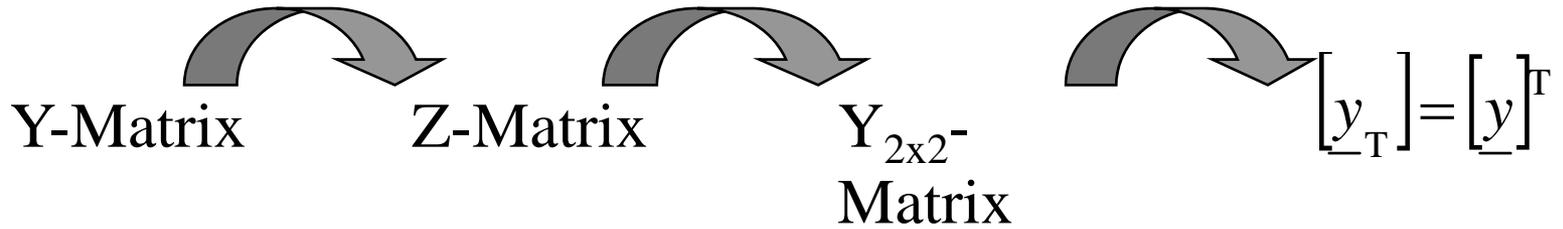
$$g_{ic} = \frac{T_{sim}}{T_0} \frac{2}{3} g_m + k_f \frac{I_c^{af}}{f^b 4kT_0}$$

1/f-noise





# Tellegen Thorem



*Tellegen Theorem for noisy n-ports*

Adjoined network for calculation of transformation function

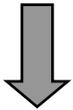
$$i_{Q_1} = v_q \cdot \underline{y}_{T,2 \times 2_{1,1}} \quad \text{and} \quad i_{Q_2} = v_q \cdot \underline{y}_{T,2 \times 2_{2,2}}$$



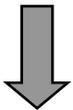
# Tellegen Theorem

$$\begin{bmatrix} i_{Q1} \\ \vdots \\ i_{Q10} \end{bmatrix} = \begin{bmatrix} y_{T_{1,1}} & \cdots & y_{T_{1,10}} \\ \vdots & \ddots & \vdots \\ y_{T_{10,1}} & \cdots & y_{T_{10,10}} \end{bmatrix} \begin{bmatrix} v_1 \\ \vdots \\ v_{10} \end{bmatrix}$$

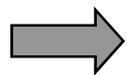
Solving the equation system for the voltages using the Gaussian algorithm



Voltage transformation factor



One single noise source at Eingang, one at output



$$[T]^{(y \rightarrow a)} = \begin{bmatrix} 0 & -\frac{1}{y_{2 \times 2_{21}}} \\ 1 & -\frac{y_{2 \times 2_{11}}}{y_{2 \times 2_{21}}} \end{bmatrix}$$



1 current source, 1 voltage source at output



# Correlation matrix

$$F = 1 - \frac{T_{\text{sim}}}{T_0} \frac{|y_{\underline{G}}|^2 C_{11}^{(a)} + C_{22}^{(a)} + 2\Re\{y_{\underline{G}} C_{12}^a\}}{g_G}$$

$$R_n = \frac{T_{\text{sim}}}{T_0} C_{11}^a$$

Korrelationsmatrix

$$[\underline{C}]^{(a)} = [\underline{T}]^{(y \rightarrow a)} [\underline{C}]^{(y)} [\underline{T}]^{(y \rightarrow a)+}$$

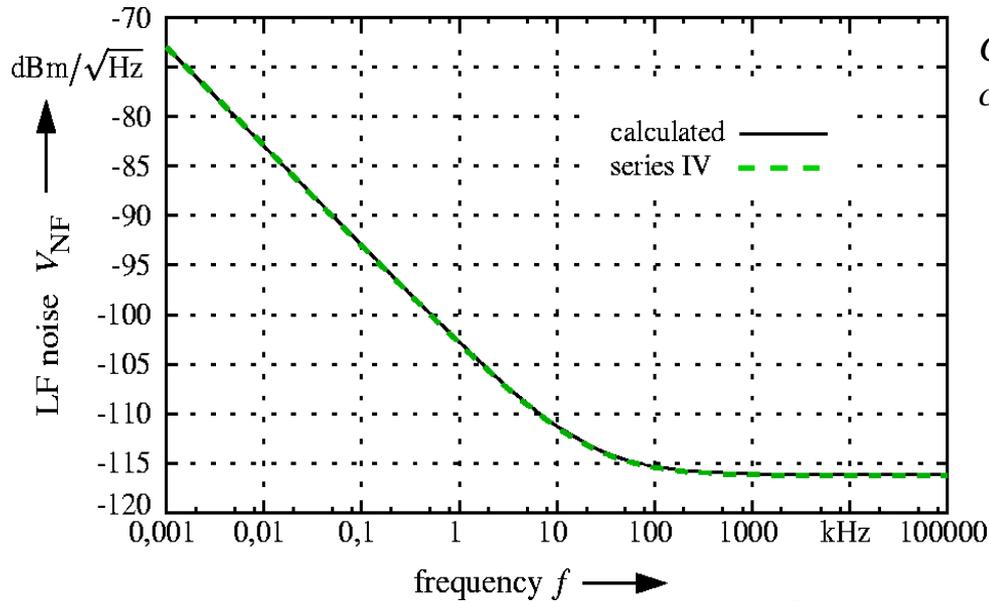
$$V_{\text{NF}} [\text{dBm}/\sqrt{\text{Hz}}] =$$

$$20 \log \left( \sqrt{\frac{T_{\text{sim}}}{T_0} \cdot i_0 i_0^* \frac{50\Omega}{50\Omega \Re(y_{\underline{2} \times \underline{2} 22}) + 1}} \cdot 1000 \right)$$

$$\Gamma_{G_{\text{opt}}} = \frac{1 - y_{\underline{G}_{\text{opt}}} Z_0}{1 + y_{\underline{G}_{\text{opt}}} Z_0}$$

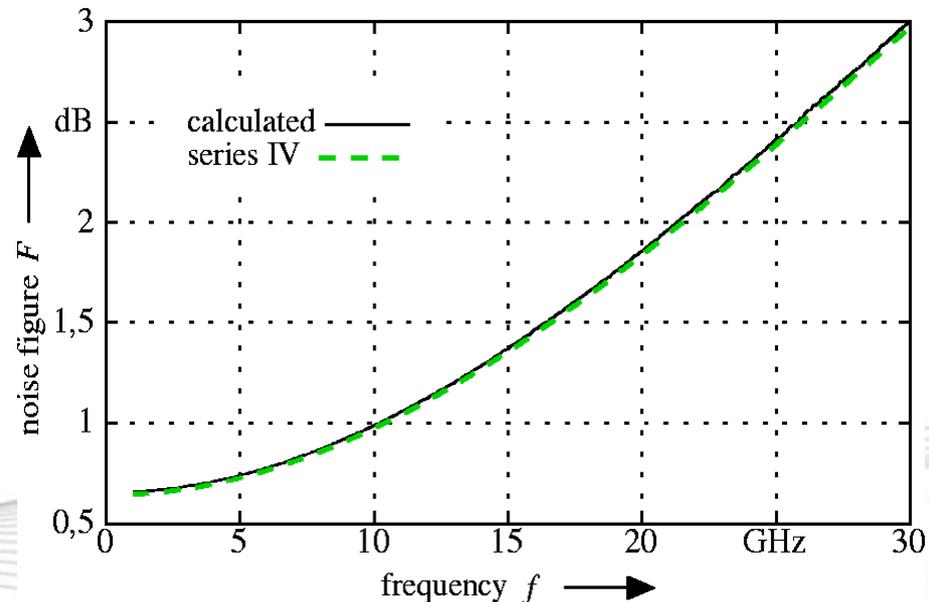


# Verifications

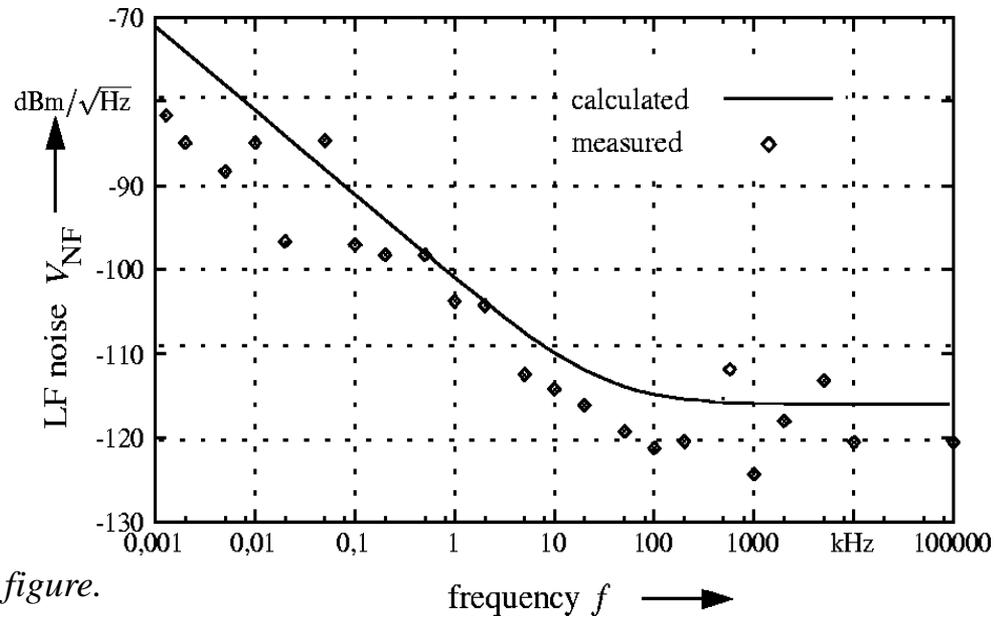


*Calculation of 1/f noise..Simulation in comparison to calculation using the proposed algorithm.*

*Calculation of noise figure NF. Comparison of simulation and calculation.*

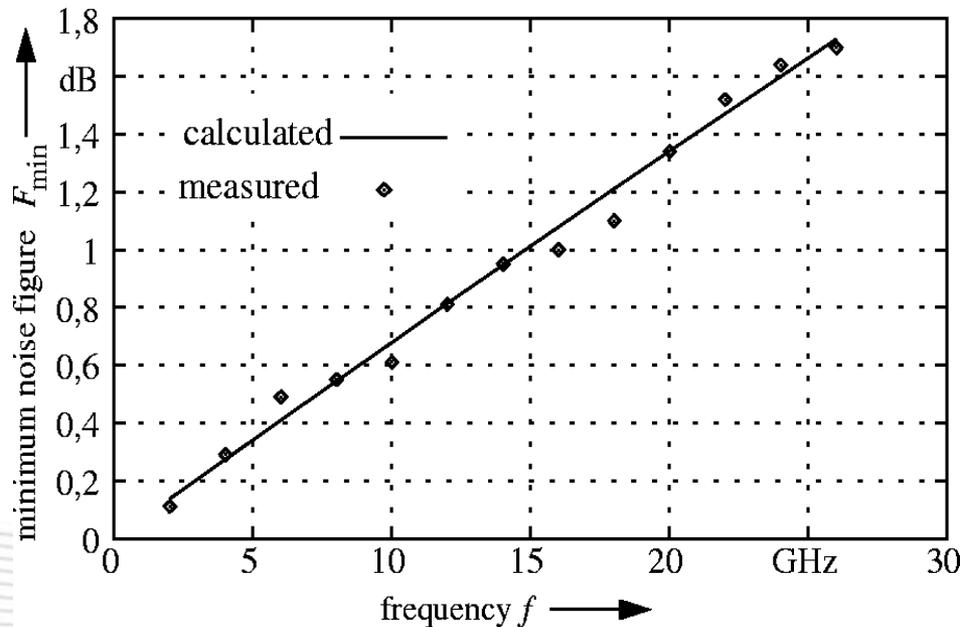


# Verifications



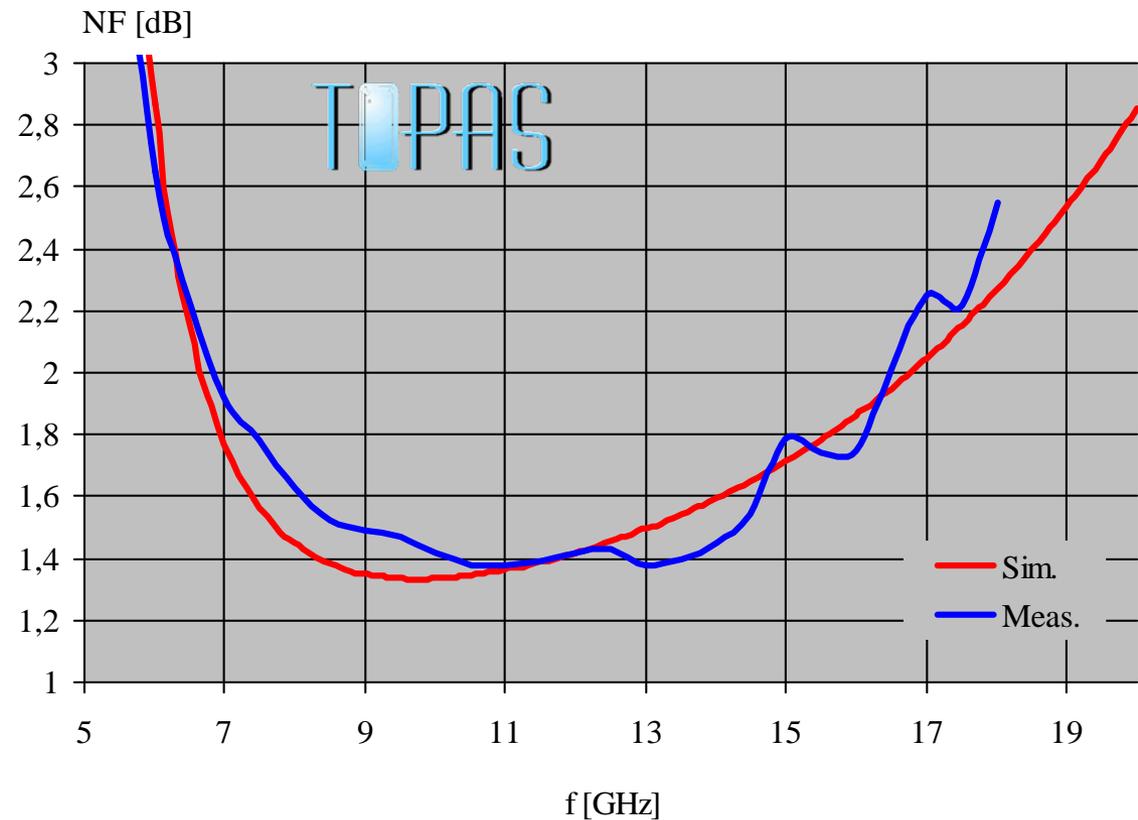
Simulation and measurement of minimum noise figure.

Simulation and measurement of 1/noise.



# Verifications

Realized LNA

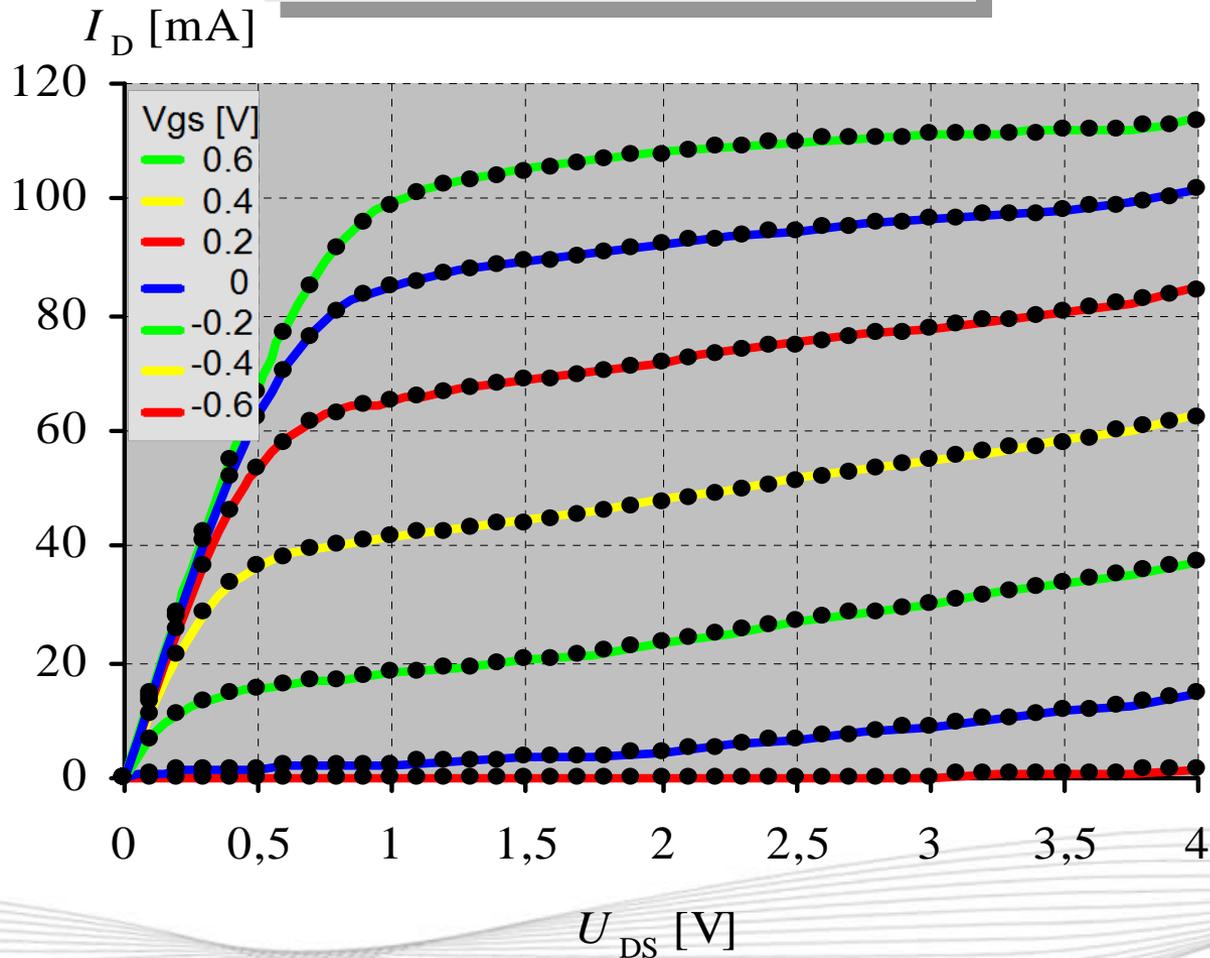


Minimum noise figure, simulation versus measurement.



# Verifications

UMS 4x50  $\mu\text{m}$   
HEMT



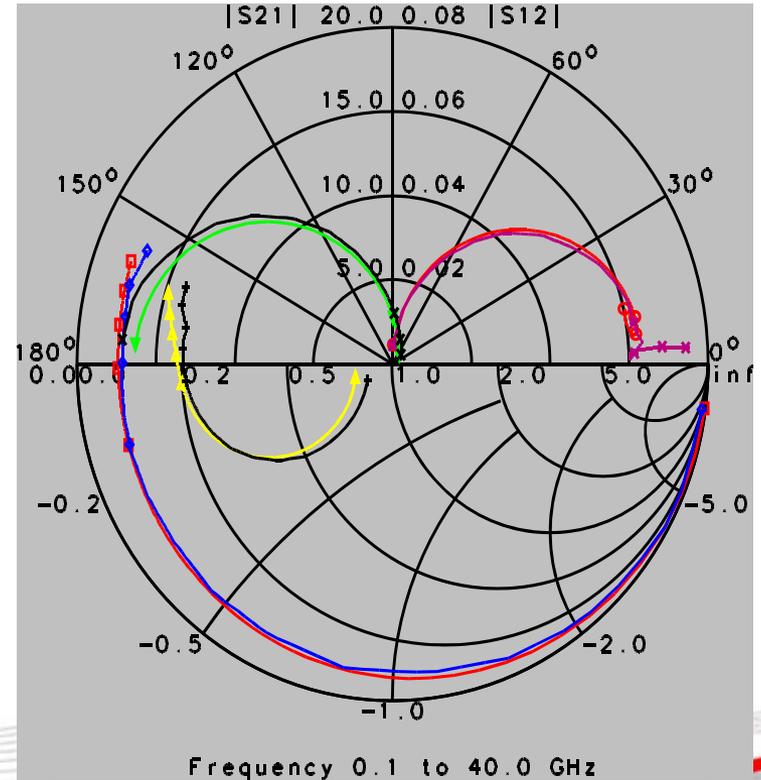
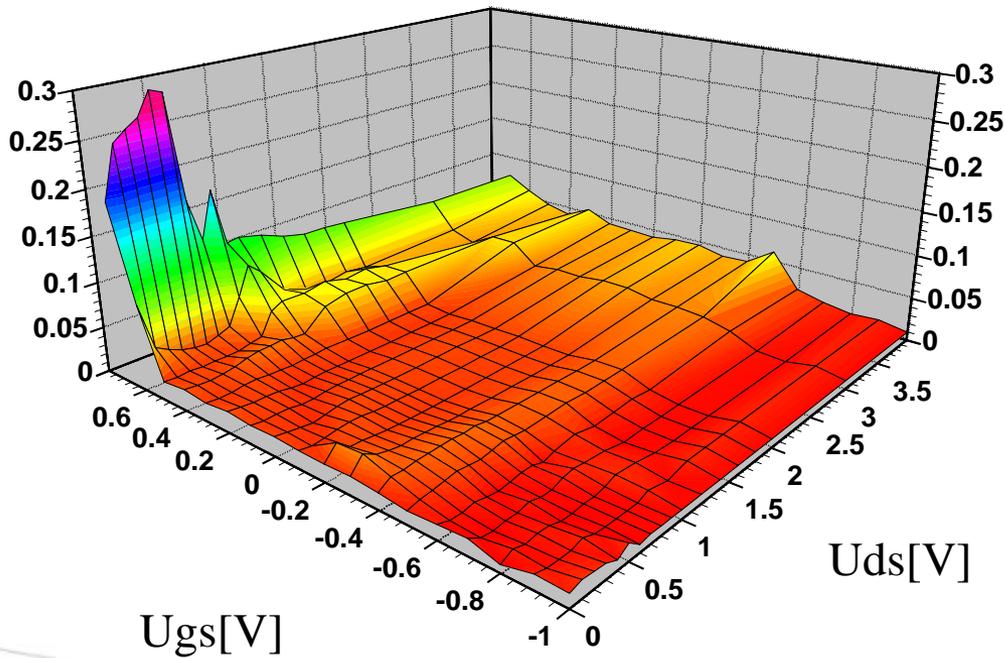


# Verifications

Deviations  
6x20  $\mu\text{m}$  HEMT

4x50  $\mu\text{m}$  ↗ 8x75  $\mu\text{m}$   
 $V_{GS} = 0 \text{ V}$ ,  $V_{DS} = 2 \text{ V}$

Fehler

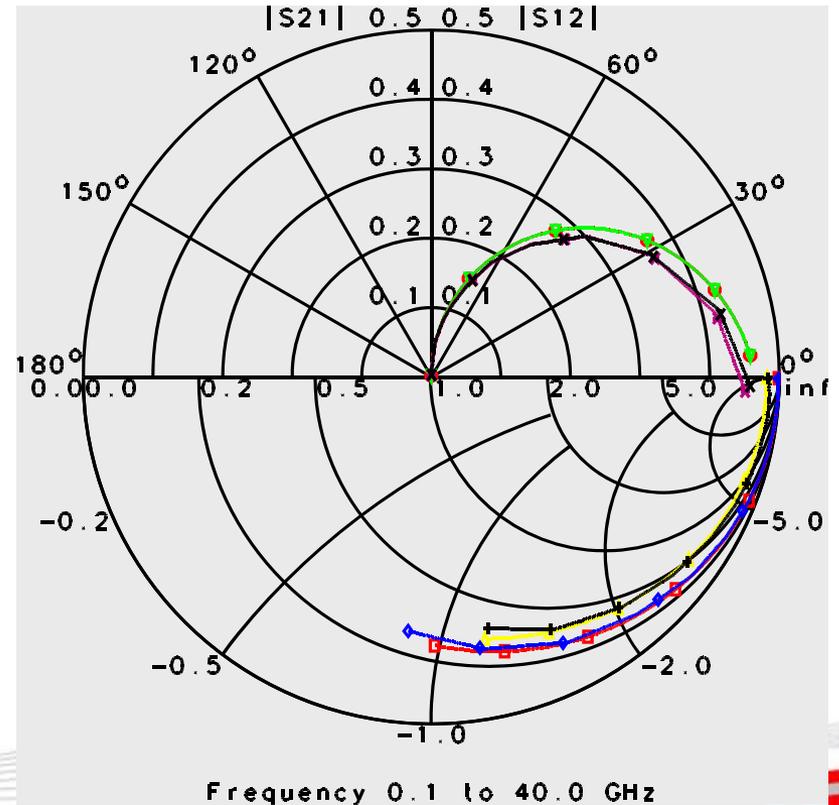
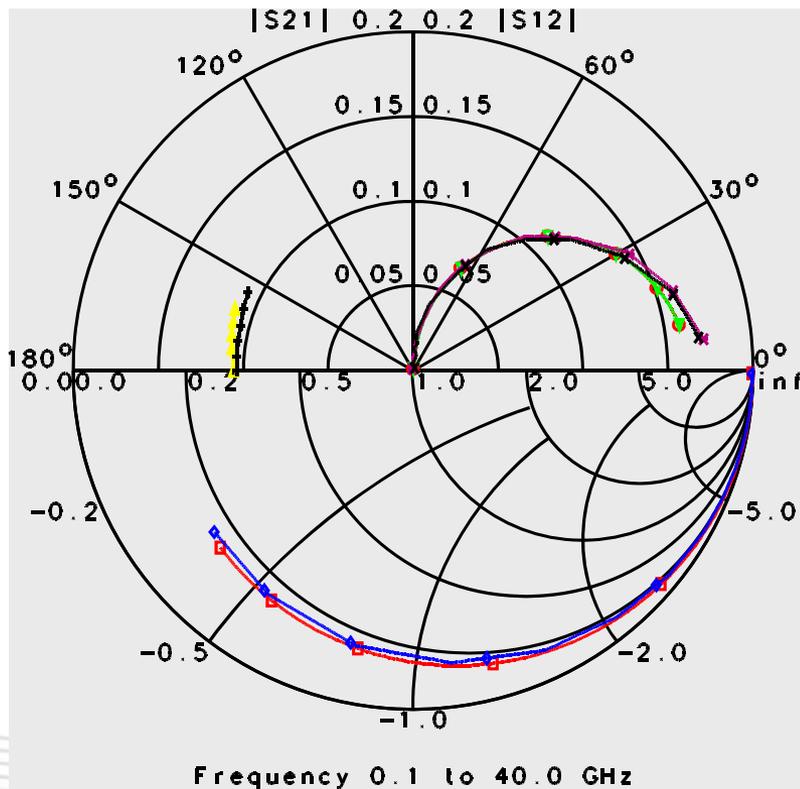




# Verifications

4x50  $\mu\text{m}$  ↗ 2x40  $\mu\text{m}$   
 $V_{GS} = 0 \text{ V}$ ,  $V_{DS} = 0 \text{ V}$

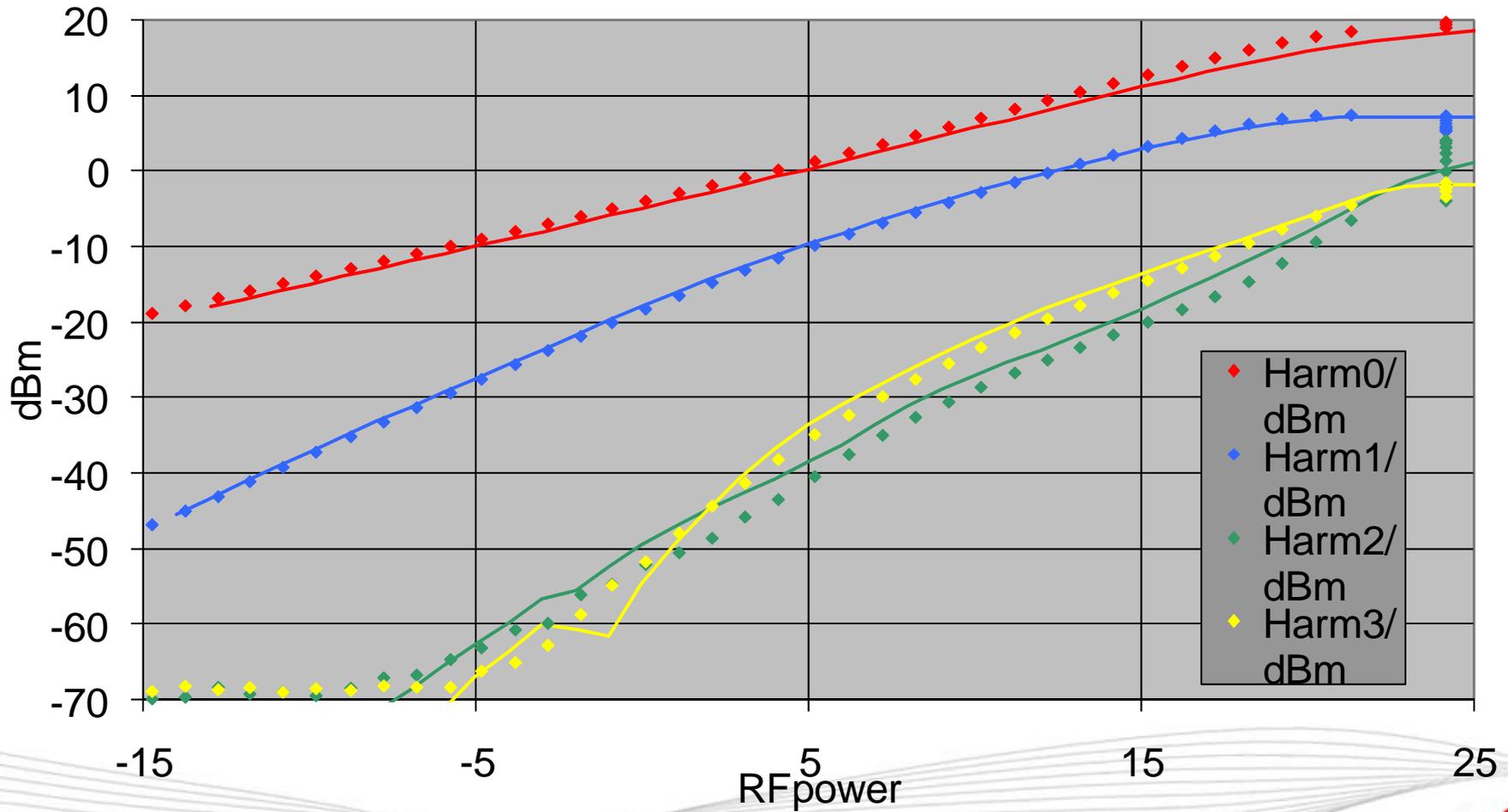
4x50  $\mu\text{m}$  ↗ 2x40  $\mu\text{m}$   
 $V_{GS} = -0.8 \text{ V}$ ,  $V_{DS} = 2 \text{ V}$





# Verifications

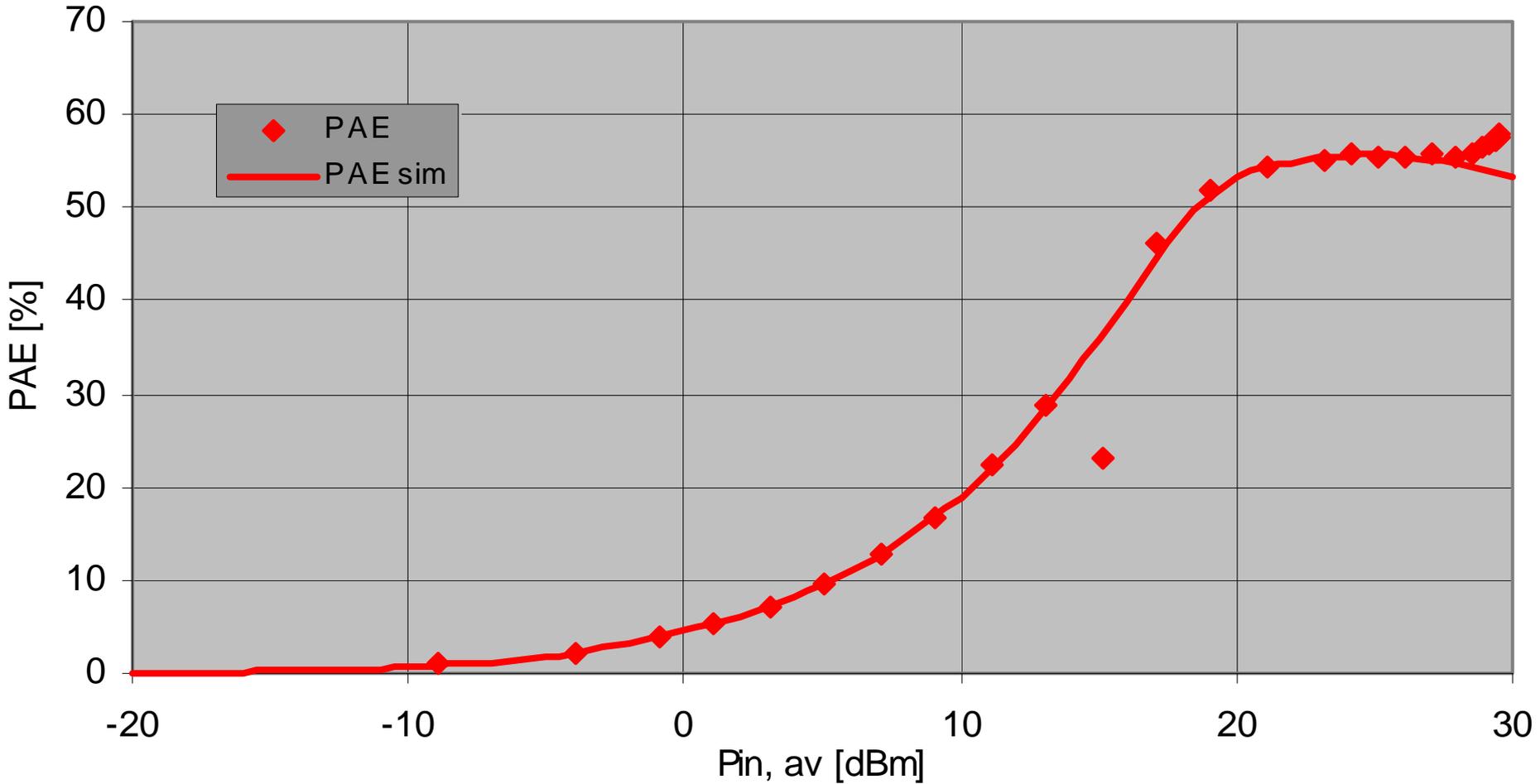
Comp 1x600 2.1 GHz , 26 V, 2.1 mA





# Verifications

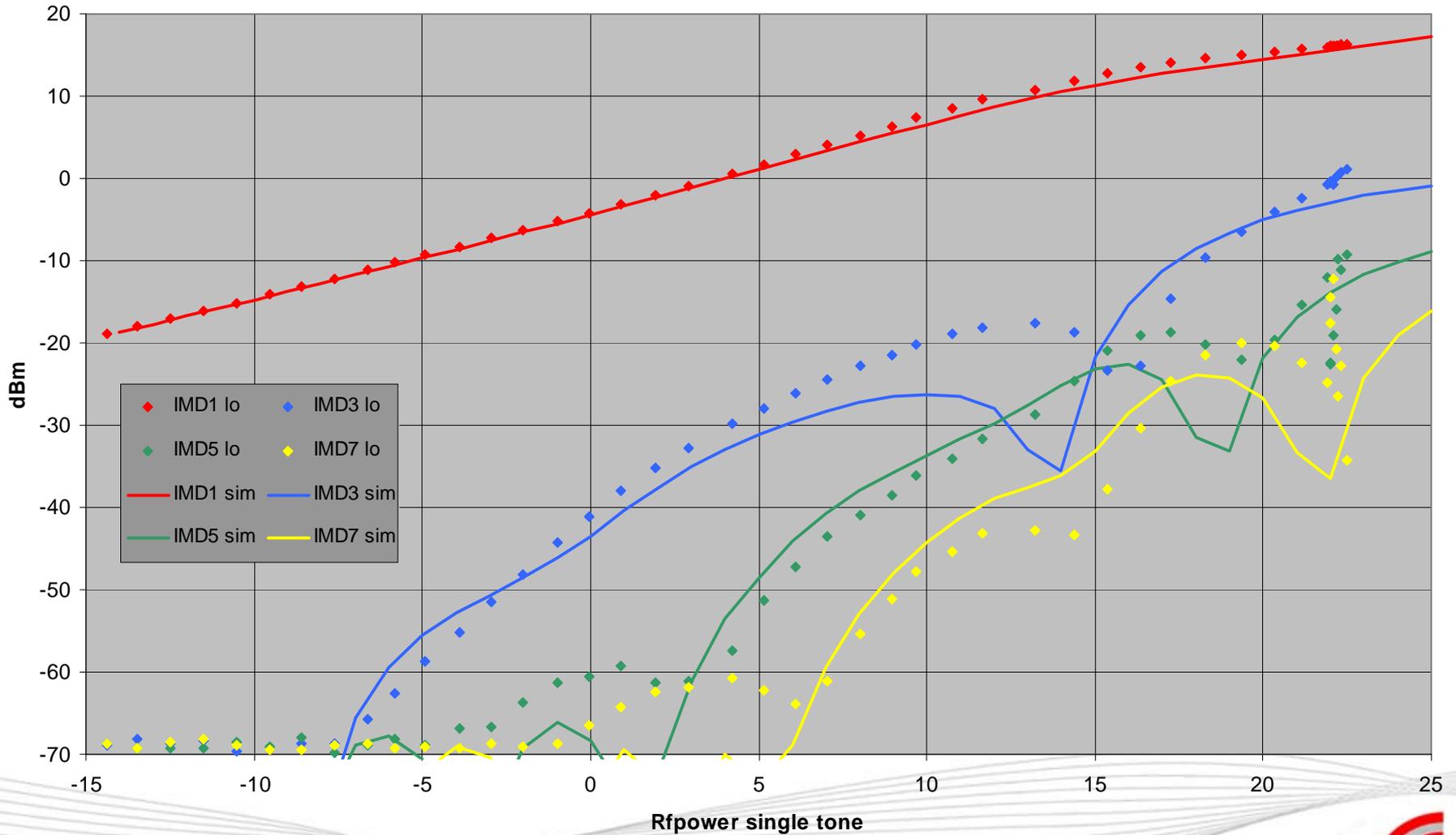
PAE, 600um LDMOS device, class B bias, matched,  $f = 2.0$  GHz





# Verifications

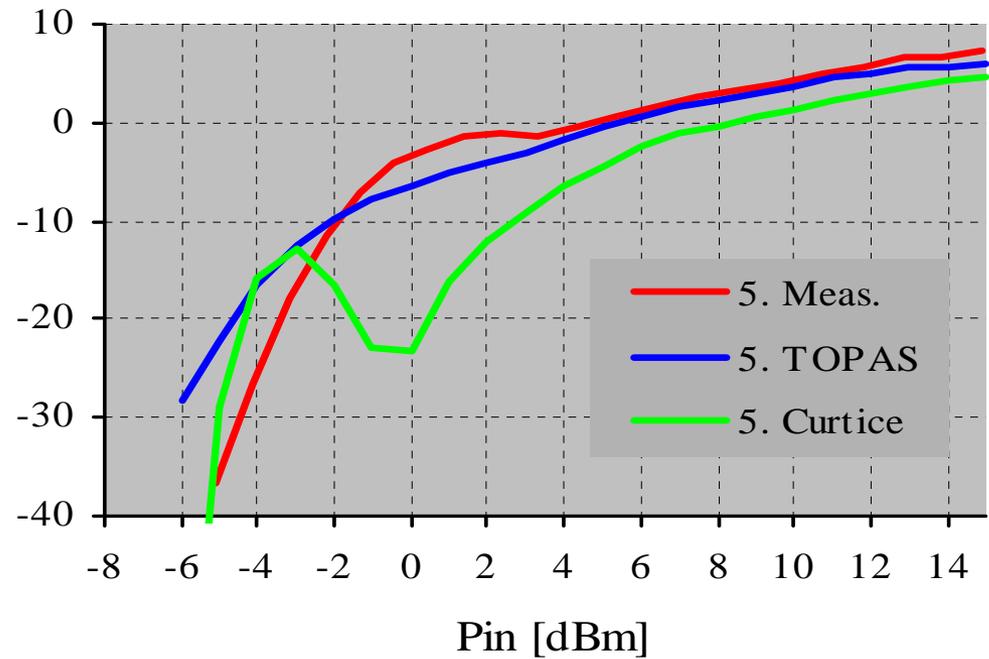
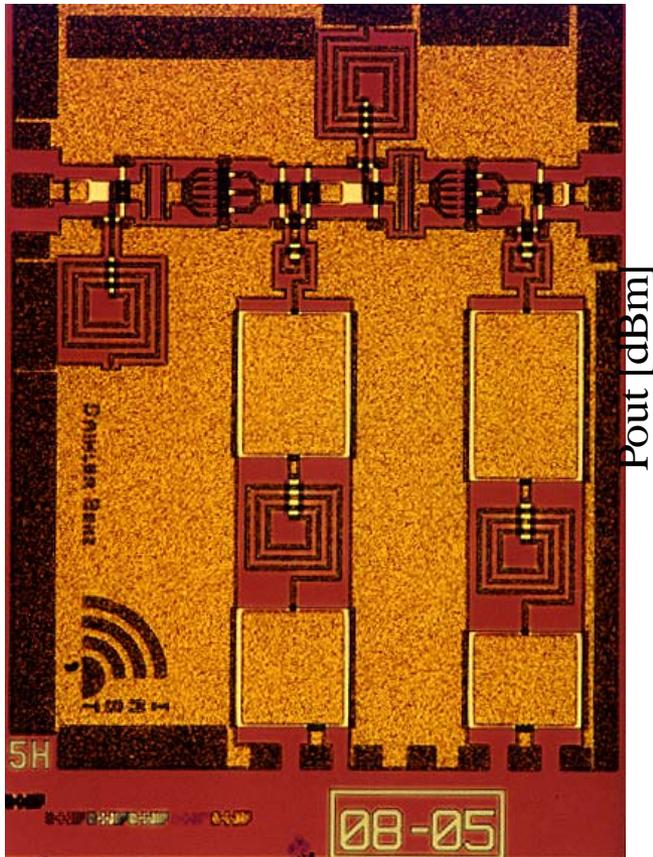
IMD 6x100 1.8 GHz, 2 MHz offset, 26 V, 2.1 mA





# Verifications

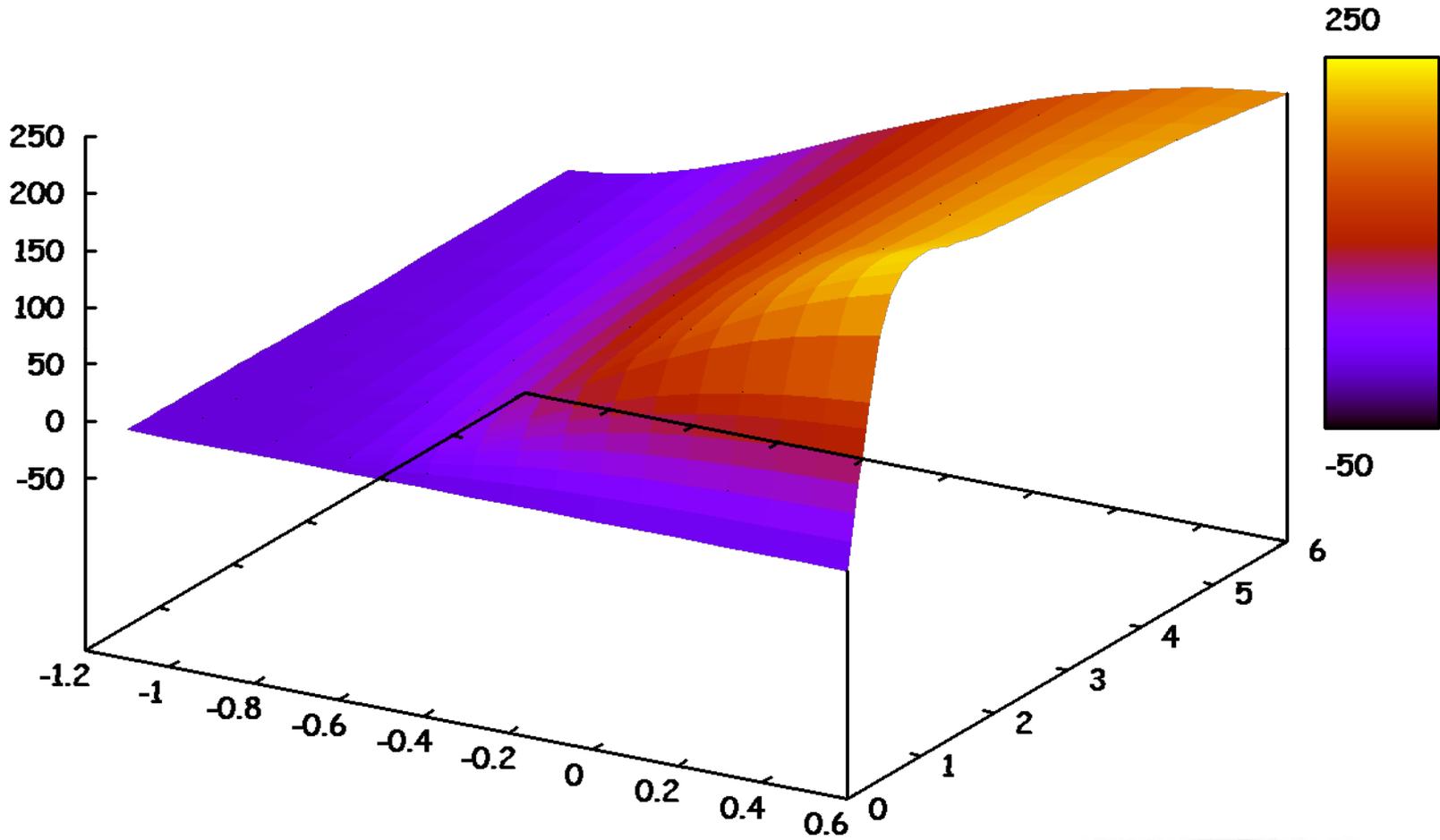
## Times 5 multiplier





# Oscillations

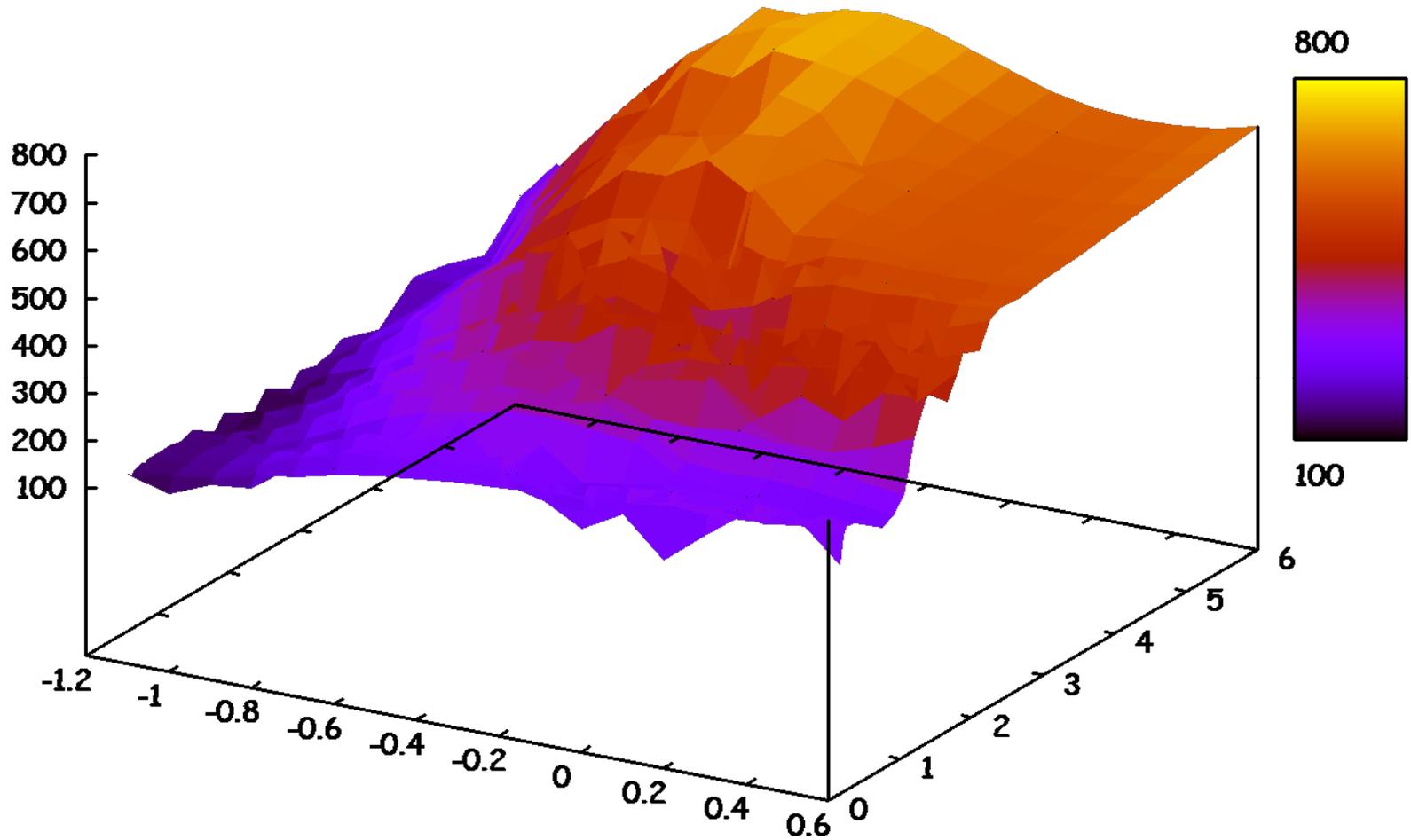
"FETplot.dc"





# Oscillations

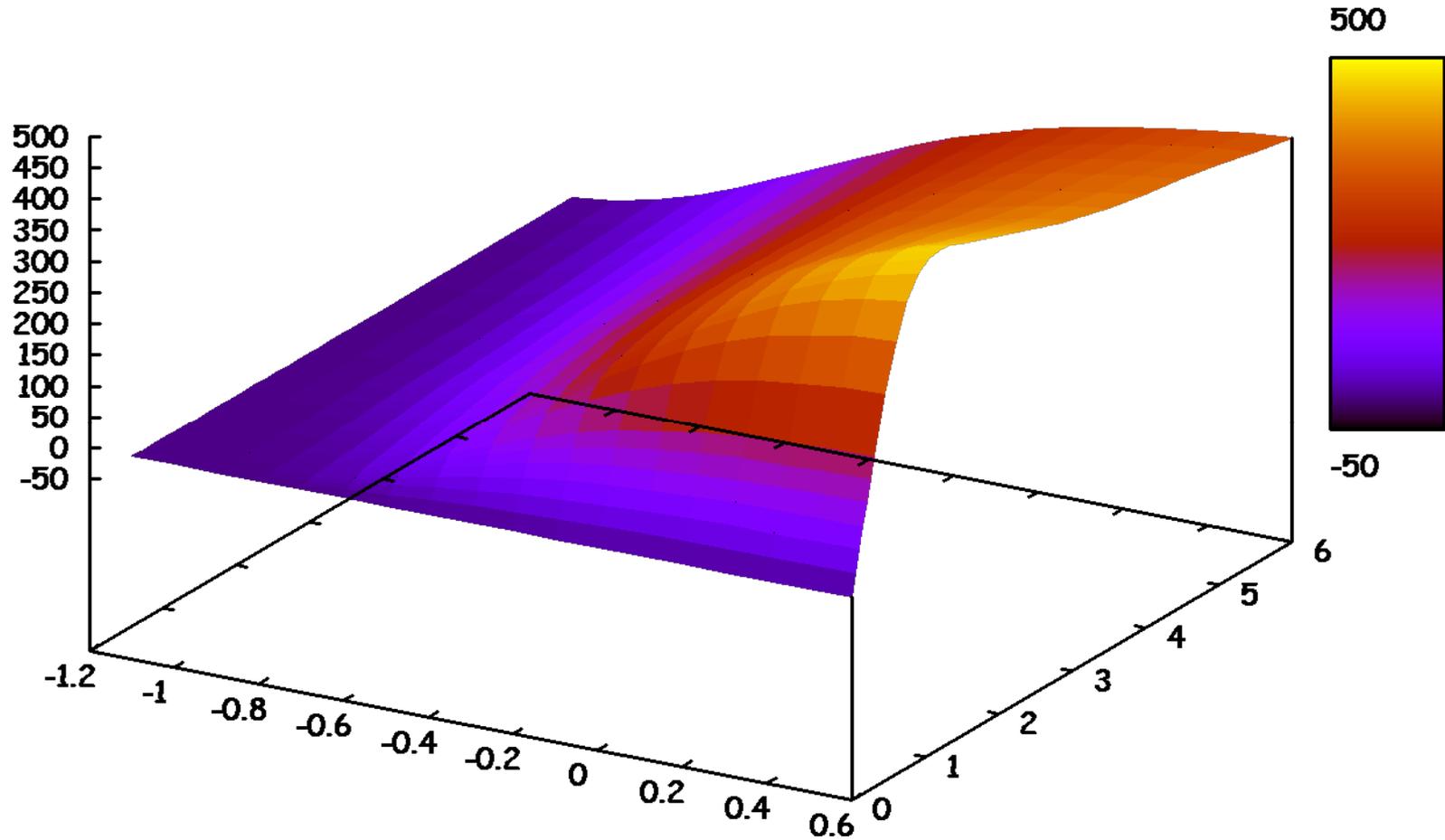
"Cgsintr.dat"





# Oscillations

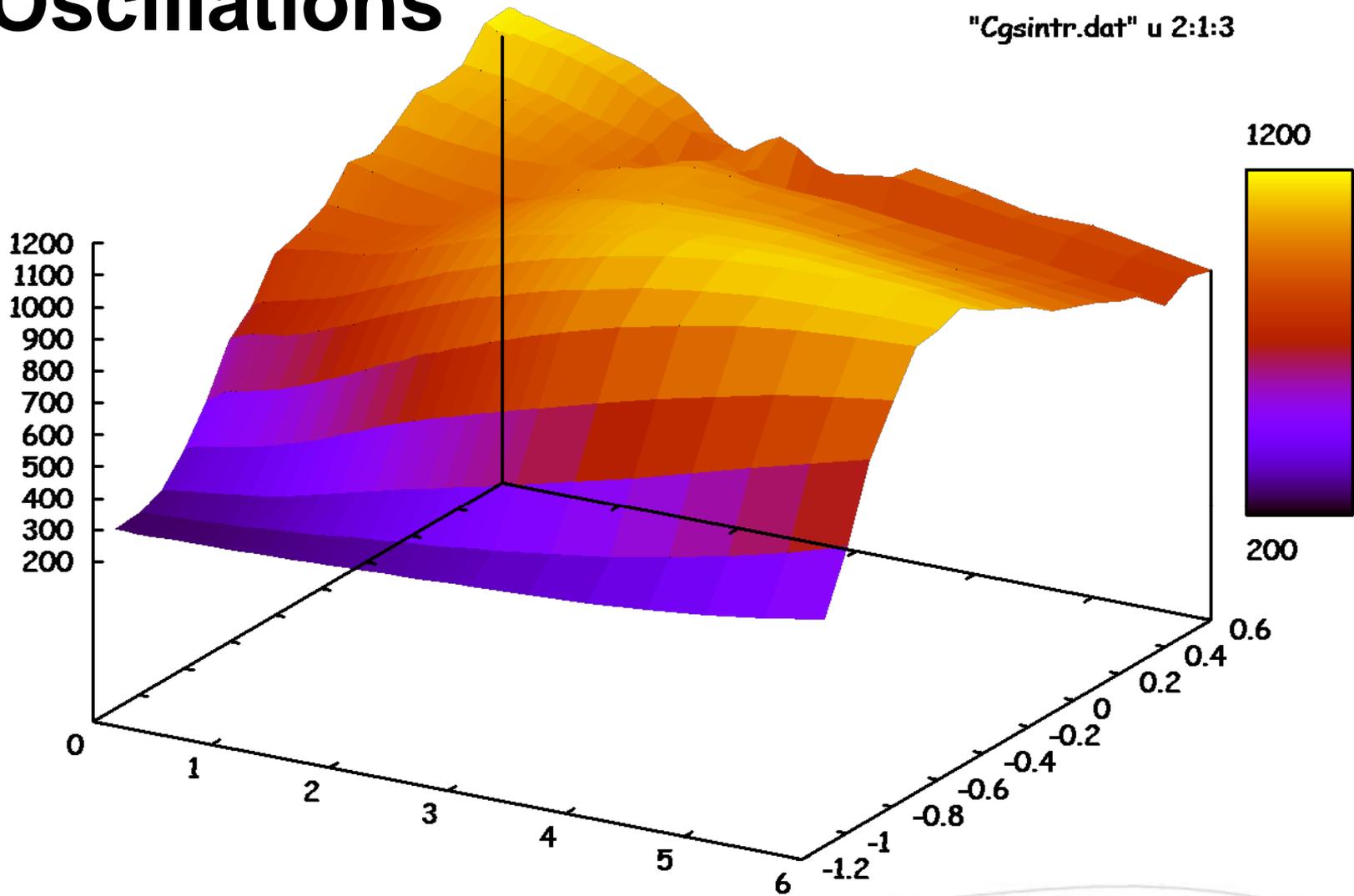
"FETplot.dc"





# Oscillations

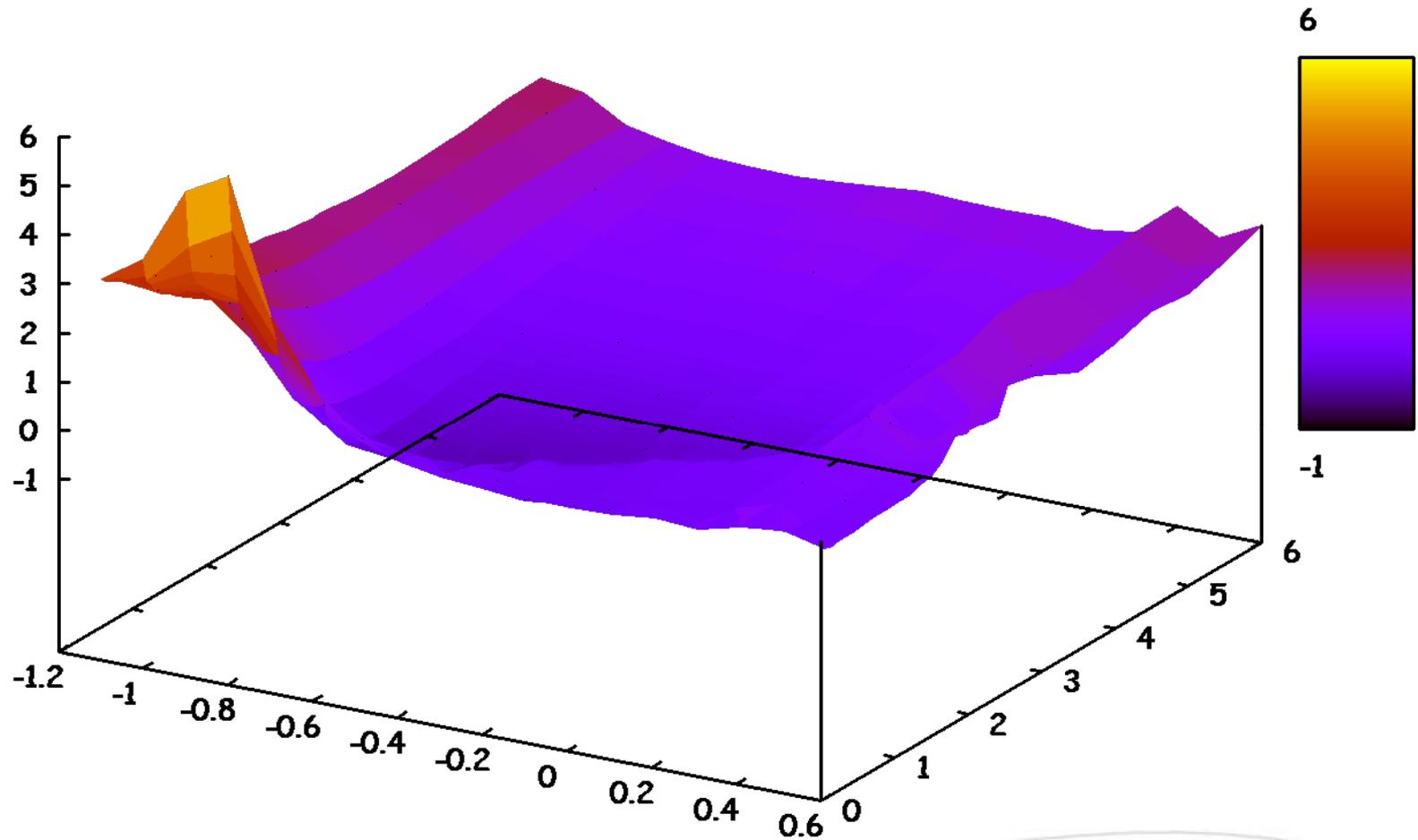
"Cgsintr.dat" u 2:1:3





# Oscillations

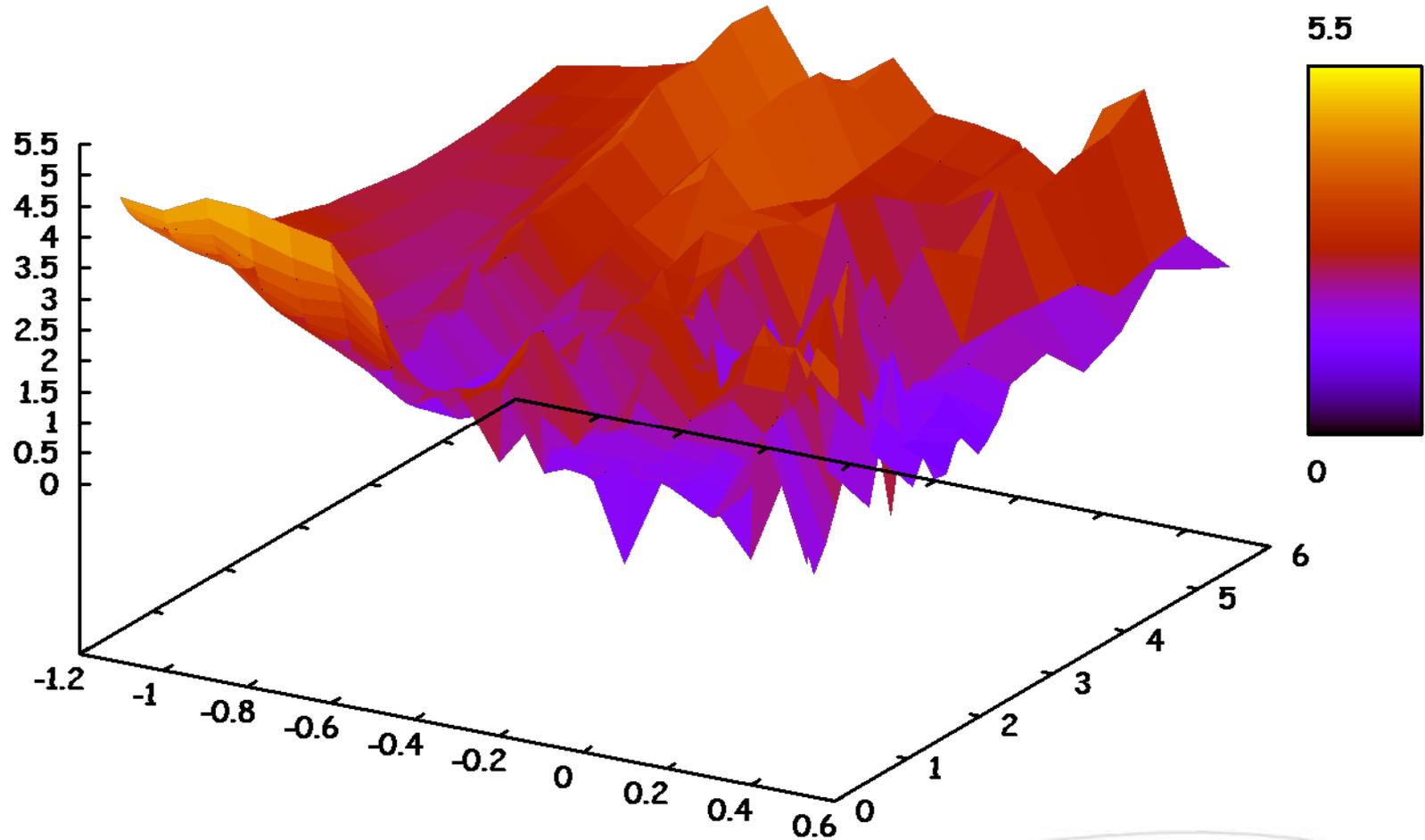
"Riintr.dat"





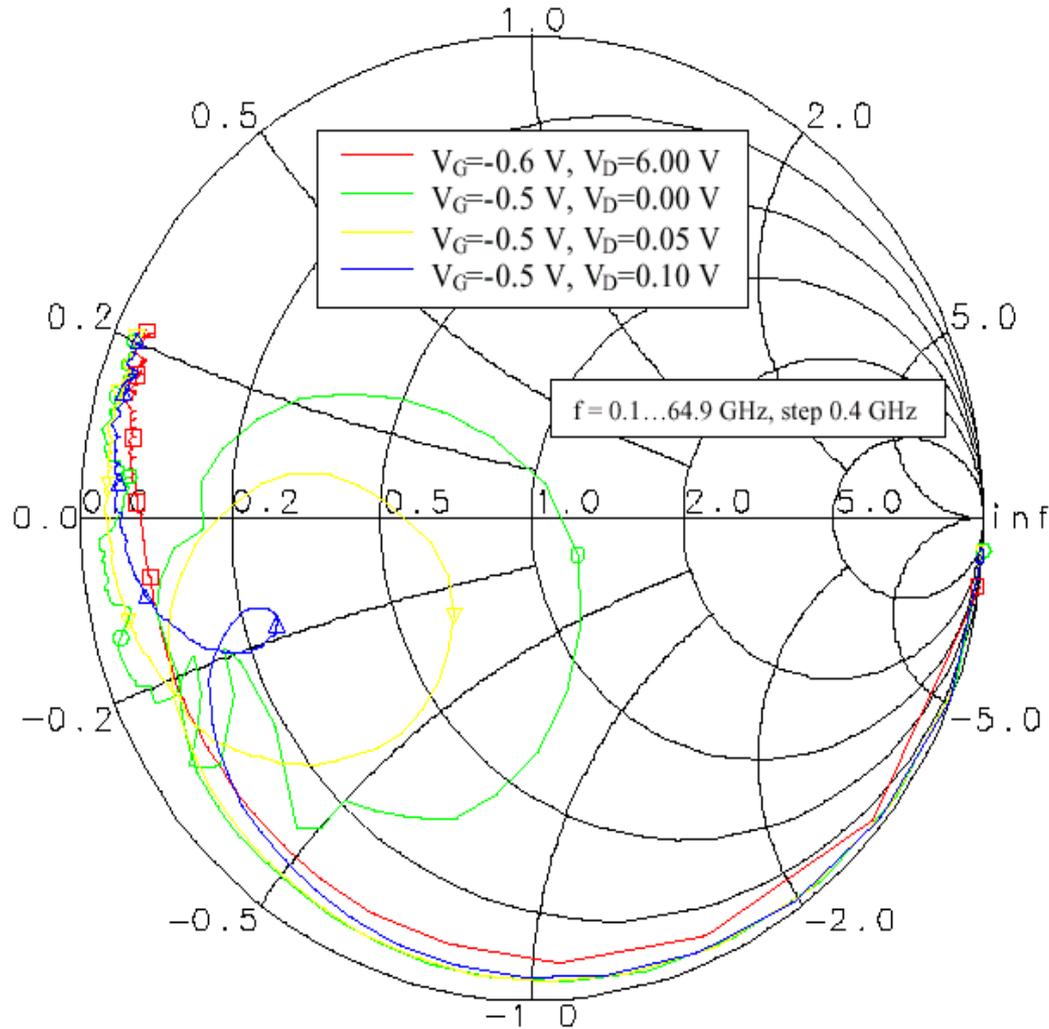
# Oscillations

"Rintr.dat"



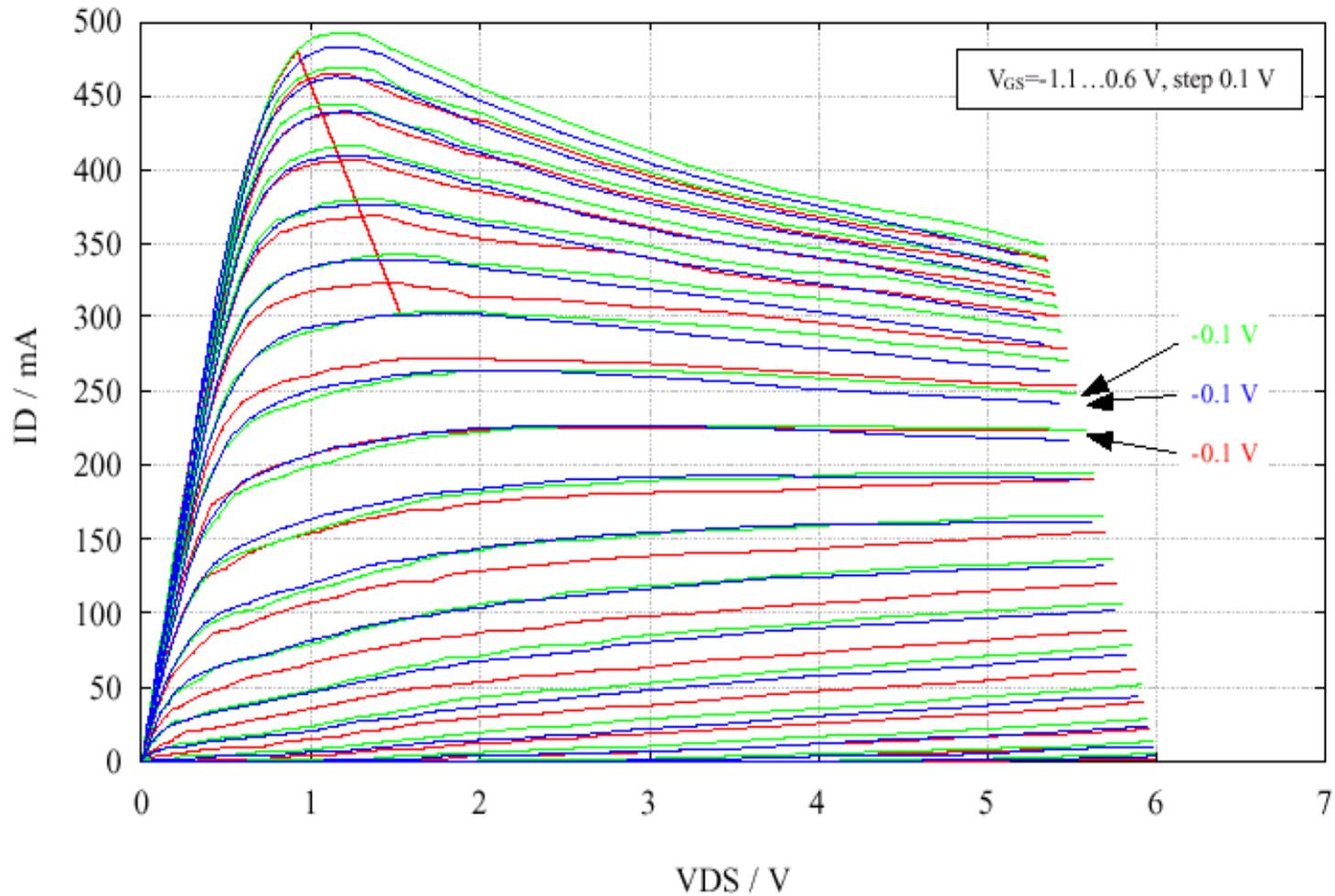


# Switching problems



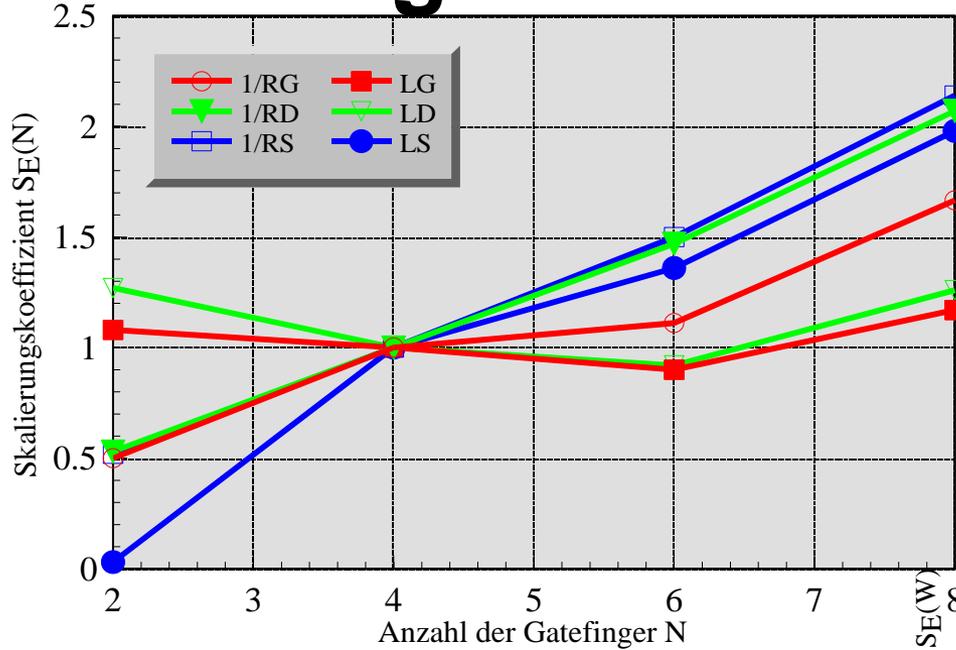


# Burn-in effects

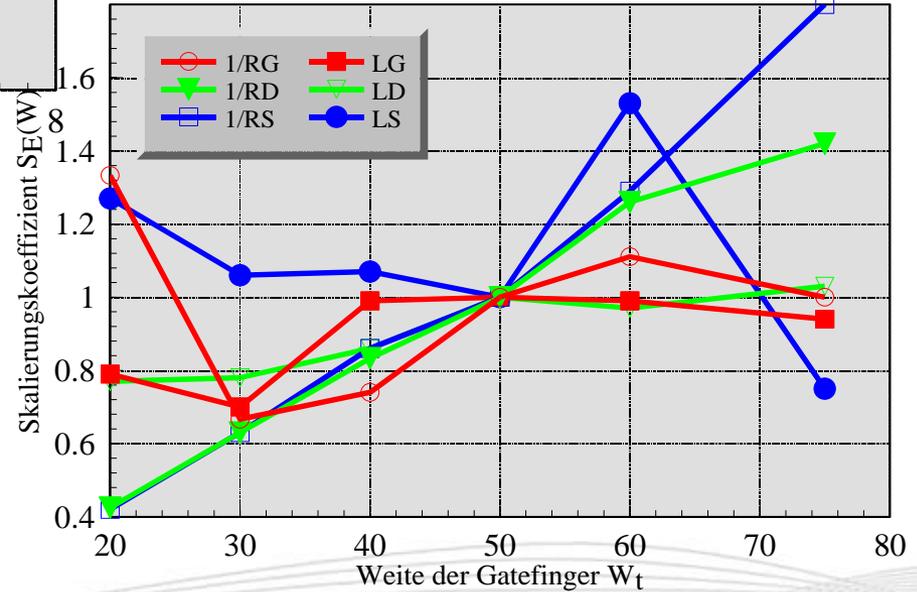
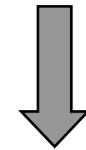




# Scaling of extrinsic elements



Variation of gate finger width



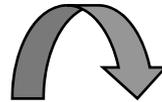
Variation of gate finger number





# Scaling of extrinsic elements

$$S_E(N) = a_{EN} \cdot N + b_{EN}$$



$$S_E(N, W_t) = S_E(N) \cdot S_E(W_t)$$

$$S_E(W_t) = a_{EW} \cdot W_t + b_{EW}$$

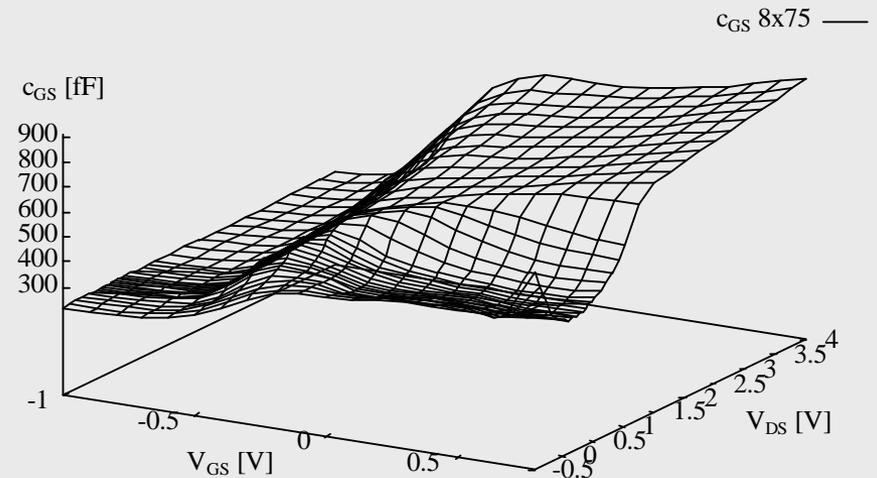
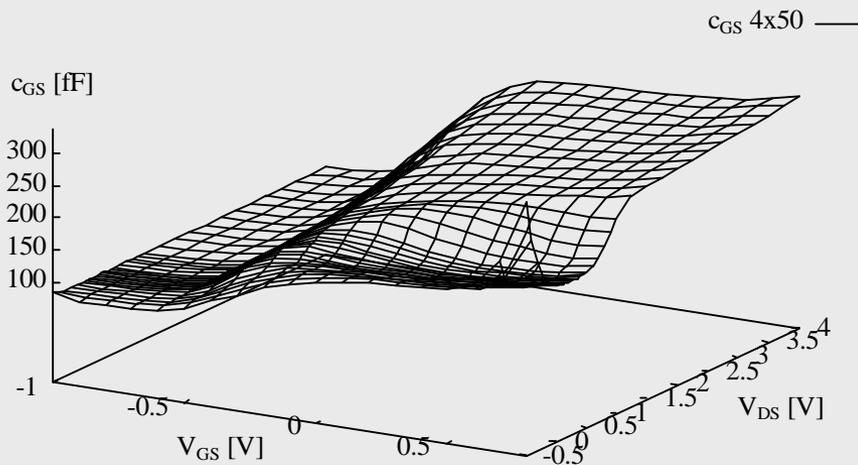
$S_E(N)$	$S_E(W)$	$a_{EN}$	$b_{EN}$	$a_{EW}$	$b_{EW}$
<b>GG</b>	<b>GG</b>	0.18	0.17	0.0	0.98
<b>GD</b>	<b>GD</b>	0.25	0.0	0.019	0.076
<b>GS</b>	<b>GS</b>	0.27	-0.04	0.024	-0.11
<b>1/LG</b>	<b>LG</b>	0.0	0.993	0.004	0.713
<b>1/LD</b>	<b>LD</b>	0.0	0.895	0.005	0.67
<b>LS</b>	<b>1/LS</b>	0.31	-0.46	0.006	0.68



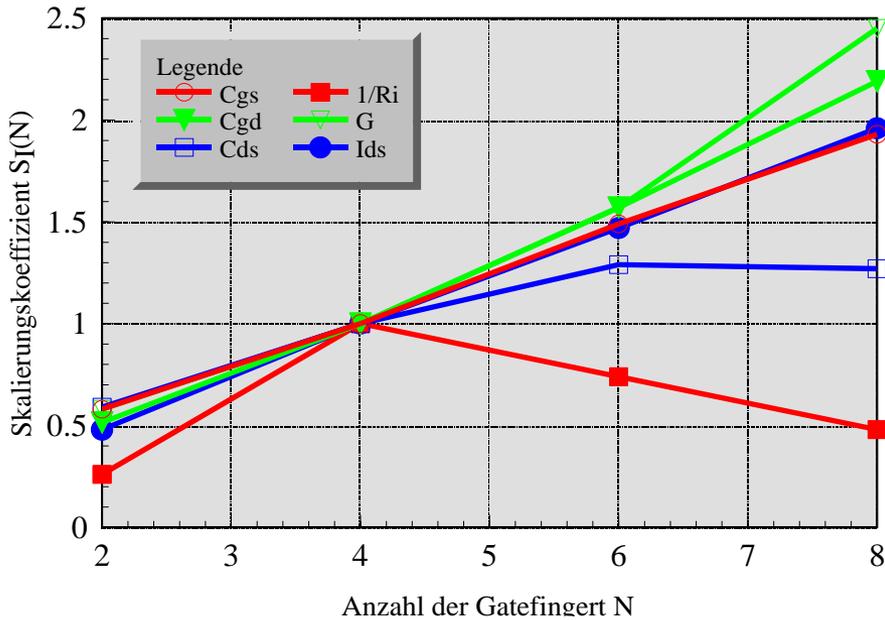
# Scaling of intrinsic elements

$$C_{old} = \frac{8 \times 75 \mu\text{m}}{4 \times 50 \mu\text{m}} = 3$$

$$C = \frac{\sum_{V_{gs}, V_{ds}} \frac{G_x(V_{GS}, V_{DS})}{G_{ref}(V_{GS}, V_{DS})}}{n_{V_{GS}, V_{DS}}}$$

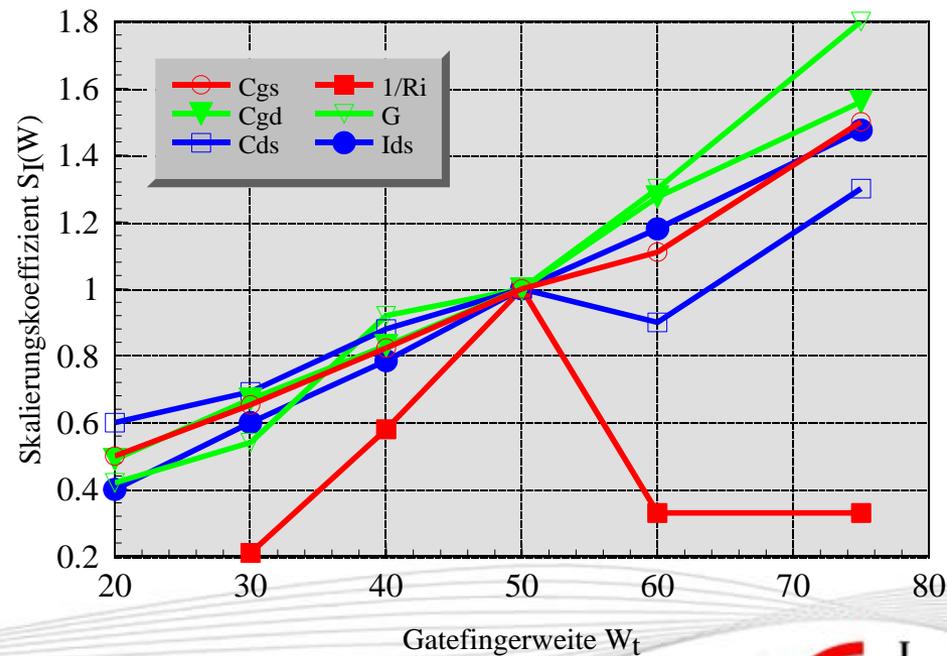


# Scaling of intrinsic elements



Variation of gate finger number

Variation of gate finger width

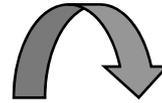




# Scaling of intrinsic elements

$$S_I(N) = a_{IN} \cdot N + b_{IN}$$

$$S_I(W) = a_{IWt} \cdot W + b_{IWt}$$



$$S_I(N, W) = S_I(N) \cdot S_I(W)$$

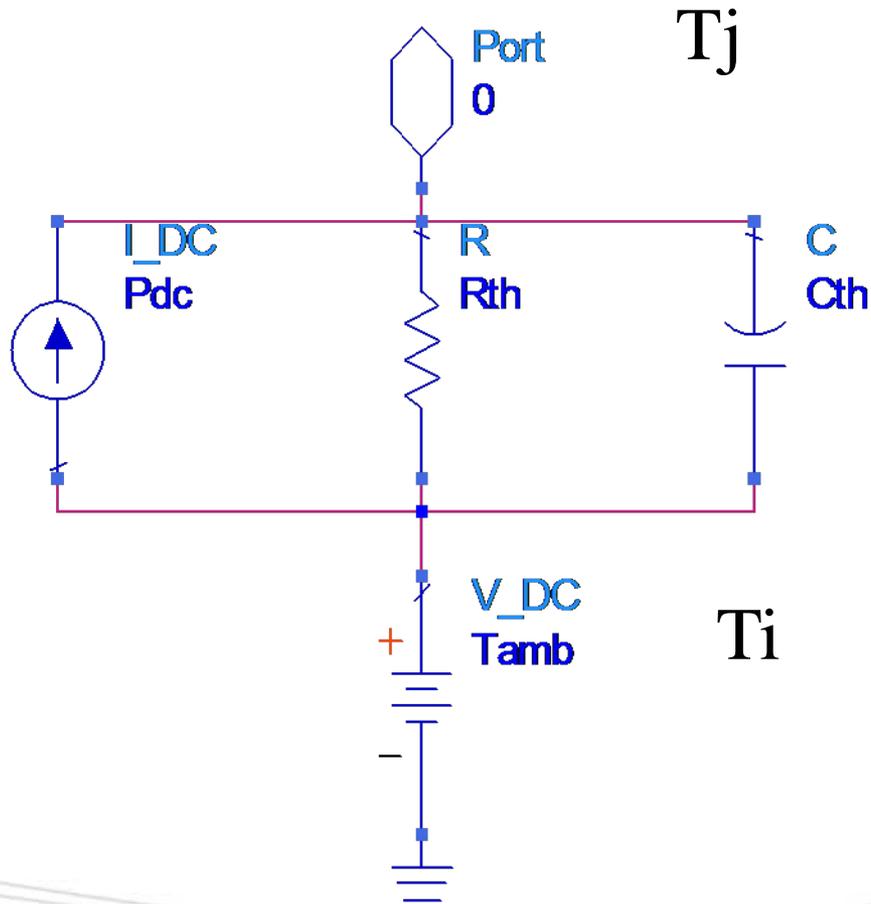
$S_I(N)$	$S_I(W)$	$a_{IN}$	$b_{IN}$	$a_{IW}$	$b_{IW}$
<b>Cgs</b>	<b>Cgs</b>	0.22	0.116	0.018	0.129
<b>Cgd</b>	<b>Cgd</b>	0.28	-0.08	0.019	0.077
<b>Cds</b>	<b>Cds</b>	0.12	0.459	0.011	0.371
<b>Gi</b>	<b>Gi</b>	0.02	0.52	-0.06	3.878
<b>G</b>	<b>G</b>	0.31	-0.14	0.025	-0.15
<b>Id</b>	<b>Id</b>	0.25	0.0	0.02	0.01

$$c_{new} = S_I(N = 4 \rightarrow N = 8) \cdot S_I(W_t = 50 \rightarrow W_t = 75)$$

$$1.93 \cdot 1.49 = 2.88$$



# Thermal model



$$C_{TH} \frac{d\Delta T}{dt} = P - \frac{\Delta T}{R_{TH}}$$

$$P = I_D V_{DS}$$

$$I_D = \frac{V_{Rd1} - V_{Rd2}}{R_D(V_{GS}, V_{DS})}$$

# 4D spline interpolation

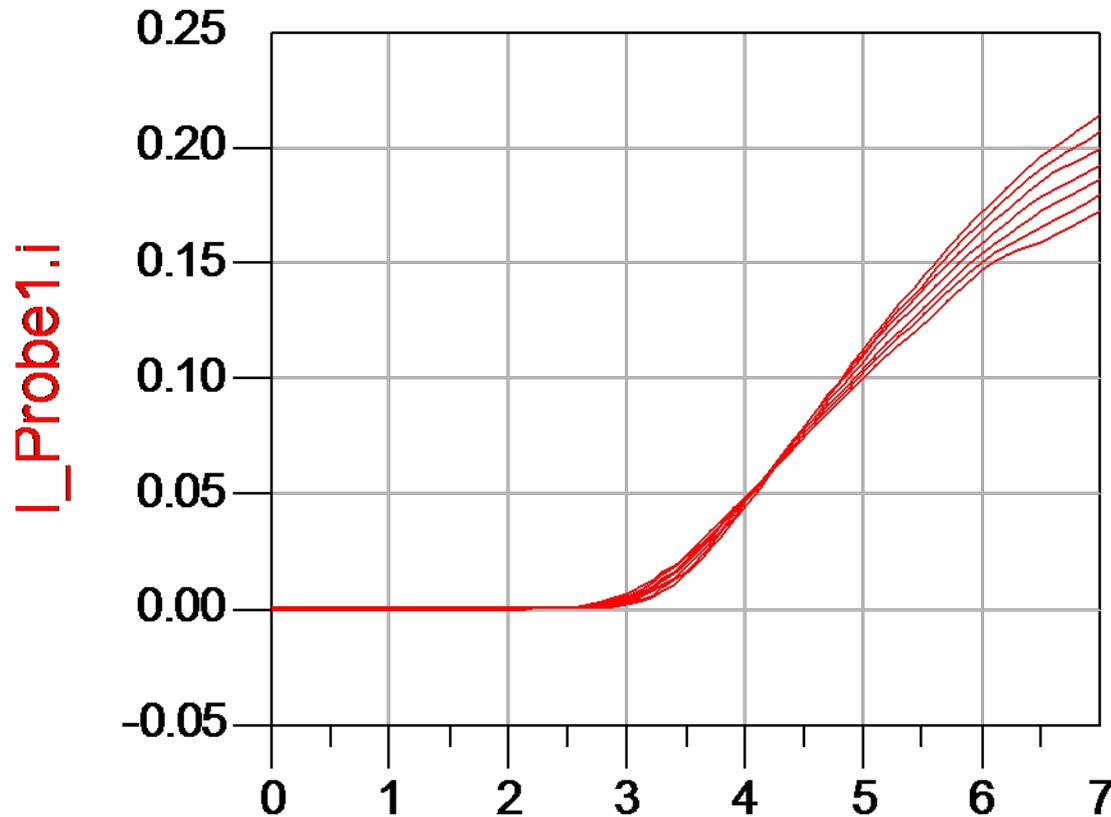
- Accurate description of  $I_D(V_{GS}, V_{DS}, T_{junc})$

$$f(\vec{x}) = \sum_{i=0}^3 \sum_{j=0}^3 \sum_{k=0}^3 a_{ijk} x_1^i x_2^j x_3^k$$

- 64 unknown values, 8 points at same time

$$f, \frac{\partial f}{\partial x_i}, \frac{\partial^2 f}{\partial x_i \partial x_j} \Big|_{i \neq j}, \frac{\partial^3 f}{\partial x_1 \partial x_2 \partial x_3}$$

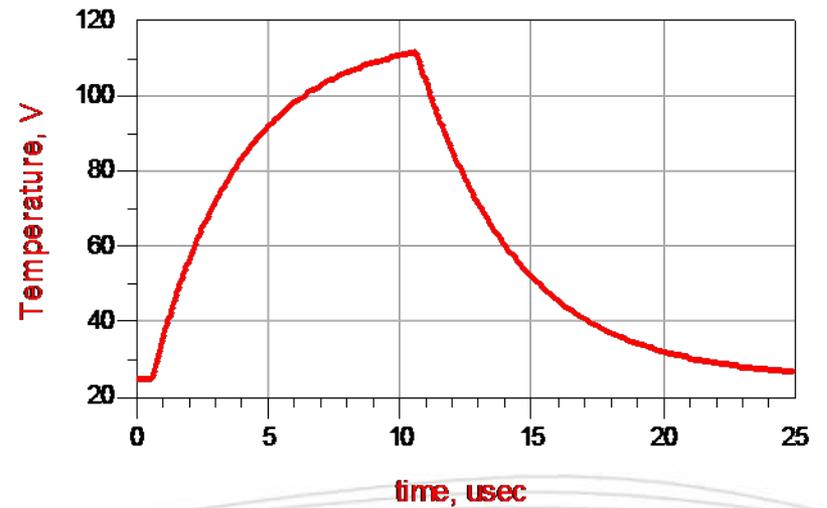
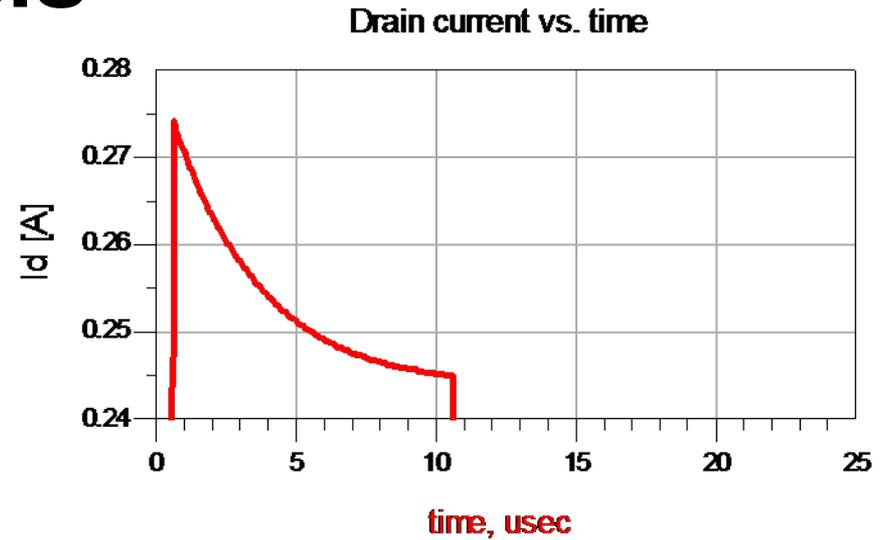
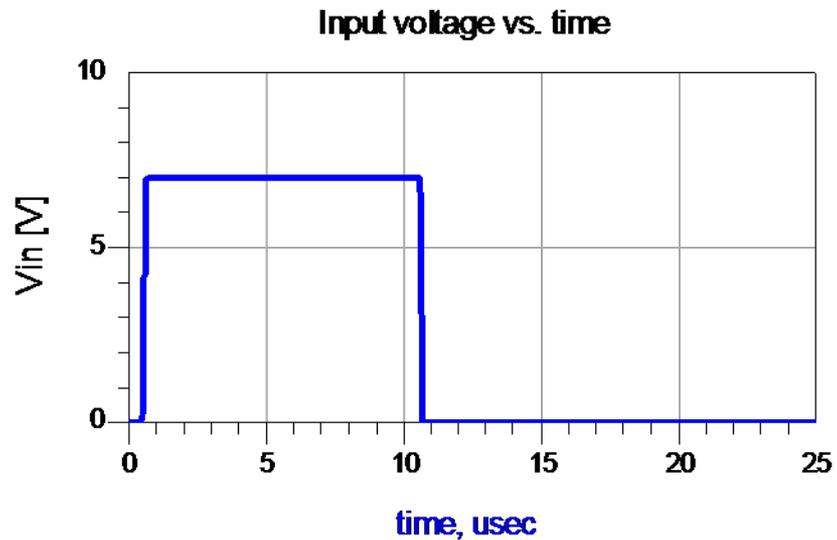
# DC verification (LDMOS example)



→ Intersection  
in one point

$V_{gs}$   
7x100  $\mu\text{m}$  device

# Transient analysis



# Rth/Cth extraction

→ Compare pulsed and CW currents at different temperatures

$$R_{TH} = \frac{T - T_{amb}}{V_{DS} I_{DS}}$$

→ Cth: Monitor current versus time

# Thank you for you attention

→ Any questions?



# Model implementation into ADS

Rüdiger Follmann



# Contents

- PN-diode, equivalent circuit and equations
- Linear part
- Non-linear part
- Linearized part
- Noise
- Interface
- Consistent implementation



# PN diode

Implementation of a pn-diode model  
into Agilent's ADS





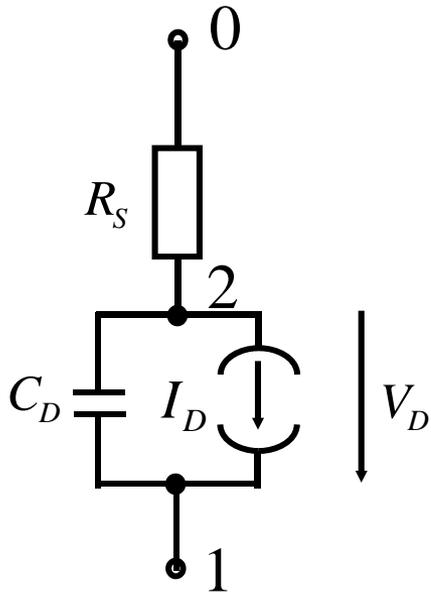
# How to start?

A non-linear model consists of the parts

- Equivalent circuit and associated equations
- Linear part containing linear elements
- Same with non-linear part
- Bias point dependent linearized part (Jacobian matrix)
- Bias dependent noise part



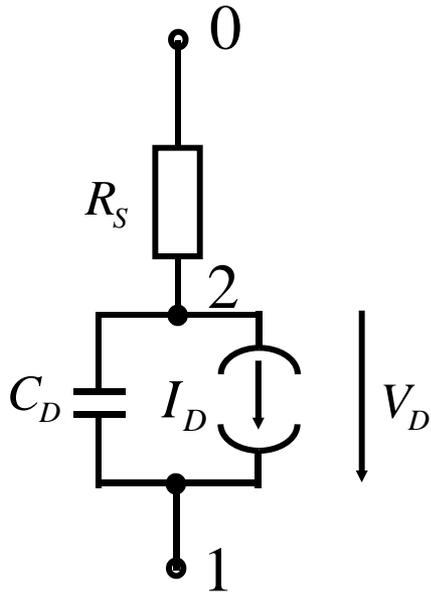
# ADS specific things



- All nodes are numbered
- Outer nodes get smallest numbers



# Equivalent circuit and equations



$$I_D(V_D) = I_S \left( e^{\frac{V_D}{V_{te}}} - 1 \right) + 10^{-12} \frac{\text{A}}{\text{V}} V_D$$

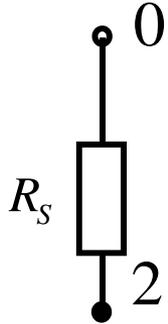
$$\frac{dI_D}{dV_D} = \frac{I_S e^{\frac{V_D}{V_{te}}}}{V_{te}} + 10^{-12} \frac{\text{A}}{\text{V}}$$

$$C_D(V_D) = TT \frac{dI_D}{dV_D} + CJO \left( 1 - \frac{V_D}{VJ} \right)^{-M}$$

$$Q_D(V_D) = \int_0^{V_D} C_D(\tilde{V}_D) d\tilde{V}_D = TT \cdot I_D + \frac{VJ \cdot CJO}{1-M} \left( 1 - \left( 1 - \frac{V_D}{VJ} \right)^{1-M} \right)$$



# Linear part



$R_s$  is the only linear element between nodes 0-2

COMPLEX  $y$ ;

```
y.real = 1/Rs; y.imag = 0.0;
```

```
status = add_y_branch(userInst, 0, 2,  
y);
```

Admittances here

nodes

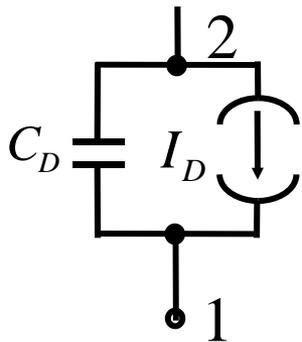
Y-matrix





# Non-linear part

- Number all nodes in order to get the voltages
- Start with outer nodes
- Use code calculates charges at each node and non-linear currents out of each node



$I_D$  and  $C_D$  are non-linear elements between nodes 1-2



# Linearized part

- Calculation of partial derivatives for non-linear elements with respect to the nodes to get capacitances and conductances for Jacobian matrix
- The linearized part does not influence the final harmonic balance solution
- The linearized part influences the convergence speed



# Noise

→ Noise part contains the bias dependent correlation parameters - normalized to  $4kT_0$

→ This part is only needed for noise analysis

## Possible noise sources:

Thermal noise  $\langle i_{th}^2 \rangle = \frac{4kT_0}{R} \Delta f$

Shot noise  $\langle i_{shot}^2 \rangle = 2qI_D \Delta f$

1/f noise  $\langle i_{1/f}^2 \rangle = KF \frac{I_D^{AF}}{f^{FFE}} \Delta f$

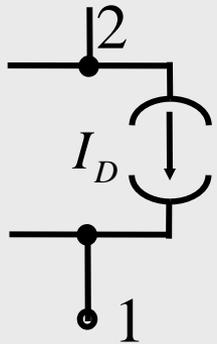
Burst or popcorn noise

$$\langle i_{burst}^2 \rangle = KB \frac{I_D^{CF}}{1 + \left( \frac{f}{f_{CF}} \right)^2} \Delta f$$



# Non-linear part

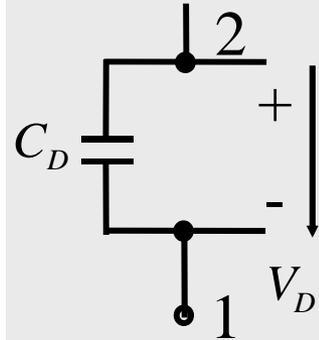
## Calculation of node currents and charges



Node 1:  $i_1 = -I_D$

Node 2:  $i_2 = +I_D$

Current from node:+, to node:-



Node 1:  $q_1 = -Q_D$

Node 2:  $q_2 = +Q_D$

	Node	i	q
		↓	↓
		↓	↓



```
status = add_nl_iq(userInst, 1, -id, -qd) &&
        add_nl_iq(userInst, 2, +id, +qd);
```





# Jacobian matrix

$$\frac{\partial I_1}{\partial V_1} = -1 \cdot \left( -\frac{dI_D}{dV_D} \right) = \frac{dI_D}{dV_D}$$

$$\frac{\partial I_1}{\partial V_2} = -\frac{dI_D}{dV_D}$$

} Real part

$$\frac{\partial I_2}{\partial V_1} = -\frac{dI_D}{dV_D}$$

$$\frac{\partial I_2}{\partial V_2} = \frac{dI_D}{dV_D}$$

$$\frac{\partial Q_1}{\partial V_1} = C_D$$

$$\frac{\partial Q_1}{\partial V_2} = -C_D$$

} Imaginary part

$$\frac{\partial Q_2}{\partial V_1} = -C_D$$

$$\frac{\partial Q_2}{\partial V_2} = C_D$$

partial derivatives

g

c

+  
-



$$V_D = V_2 - V_1$$

status =

```
add_nl_gc(userInst, 1, 1, +gd, +cd) &&
add_nl_gc(userInst, 1, 2, -gd, -cd) &&
add_nl_gc(userInst, 2, 1, -gd, -cd) &&
add_nl_gc(userInst, 2, 2, +gd, +cd);
```





# Noise

```
COMPLEX thermal, dNoise;
```

```
thermal.imag = dNoise.imag = 0.0;
```

```
thermal.real = 1.0/Rs*DEV_TEMP/NOISE_REF_TEMP;
```

Thermal noise

```
dNoise.real = 2 * CHARGE * id;
```

Shot noise

```
dNoise.real = kf * pow(id, AF)*pow(omega/TWOPI, -FFE);
```

1/f noise

```
dNoise.real /= FOUR_K_T0;
```

```
status =      add_n_branch(userInst, 0, 2, thermal) &&  
              add_n_branch(userInst, 1, 2, dNoise);
```



**Attention: All noise currents are normalized to  $4KT_0$**



# Interface

`nonlin_ele.h`

```
// name      numPars   params   compute_y   post_analysis   senior Info  
//   numExtNodes  pre_analysis  compute_n   devDef   tranDef
```

```
{"PNDIODE", 0, size(PNDIODE), PNDIODE, NULL, NULL, NULL, NULL,  
NULL, NULL, NULL}
```

`nonlin_def.h`

```
static UserNonLinDef PNDIODE =  
{  
    0,          /* numIntNodes */  
    NULL,      /* analyze_lin() */  
    sdiode_nl, /* analyze_nl() */  
    sdiode_ac, /* analyze_ac() */  
    NULL,      /* modelDef */  
    NULL      /* analyze_ac_n */  
};
```



# Interface

nonlin\_typ.h

```
PNDIODE[] =  
{ /* P-N junction diode */  
  {"AREA",  REAL_data},  
  {"IS",    REAL_data},  
  {"RS",    REAL_data},  
  {"N",     REAL_data},  
  {"TT",    REAL_data},  
  ...  
}
```

nonlin\_fun.h

```
* NON-LINEAR PN-DIODE MODEL */  
EXTERN_FUNCTION( extern boolean  pndiode_lin, (UserInstDef *userInst, double omega));  
EXTERN_FUNCTION( extern boolean  pndiode_nl,  (UserInstDef *userInst, double *vPin));  
EXTERN_FUNCTION( extern boolean  pndiode_ac,  (UserInstDef *userInst, double *vPin, double omega));  
EXTERN_FUNCTION( extern boolean  pndiode_ac_n,(UserInstDef *userInst, double *vPin, double omega));
```

# Interface

→ AEL programming language is the GUI for the simulator

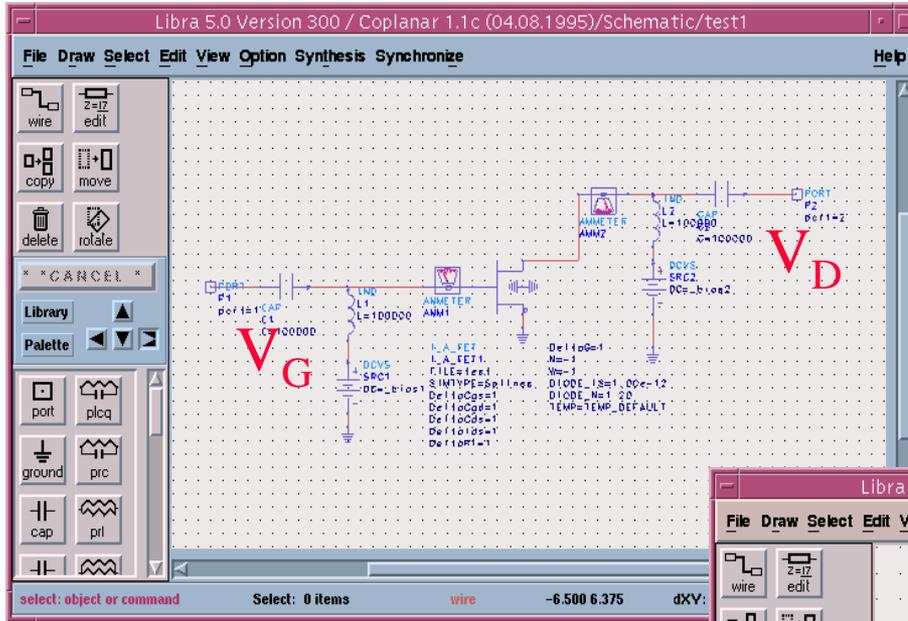


# Summary



- Different parts of a non-linear model
- Nonlinear equations and their derivatives
- Implementation into circuit simulation software
- Noise sources
- Jacobian matrix

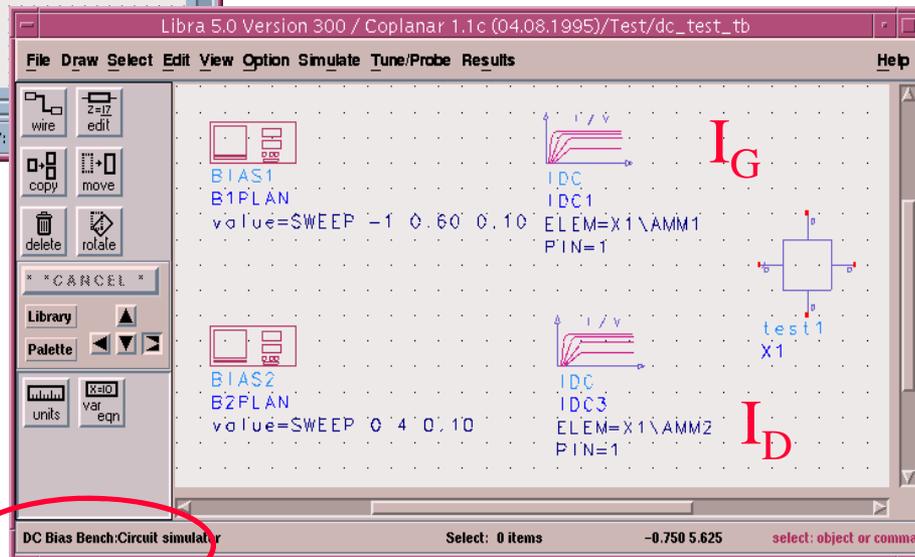
# DC tests



All tests are shown for a transistor device. They are valid for diode devices as well.

Perform a DC analysis first!

Only currents are calculated

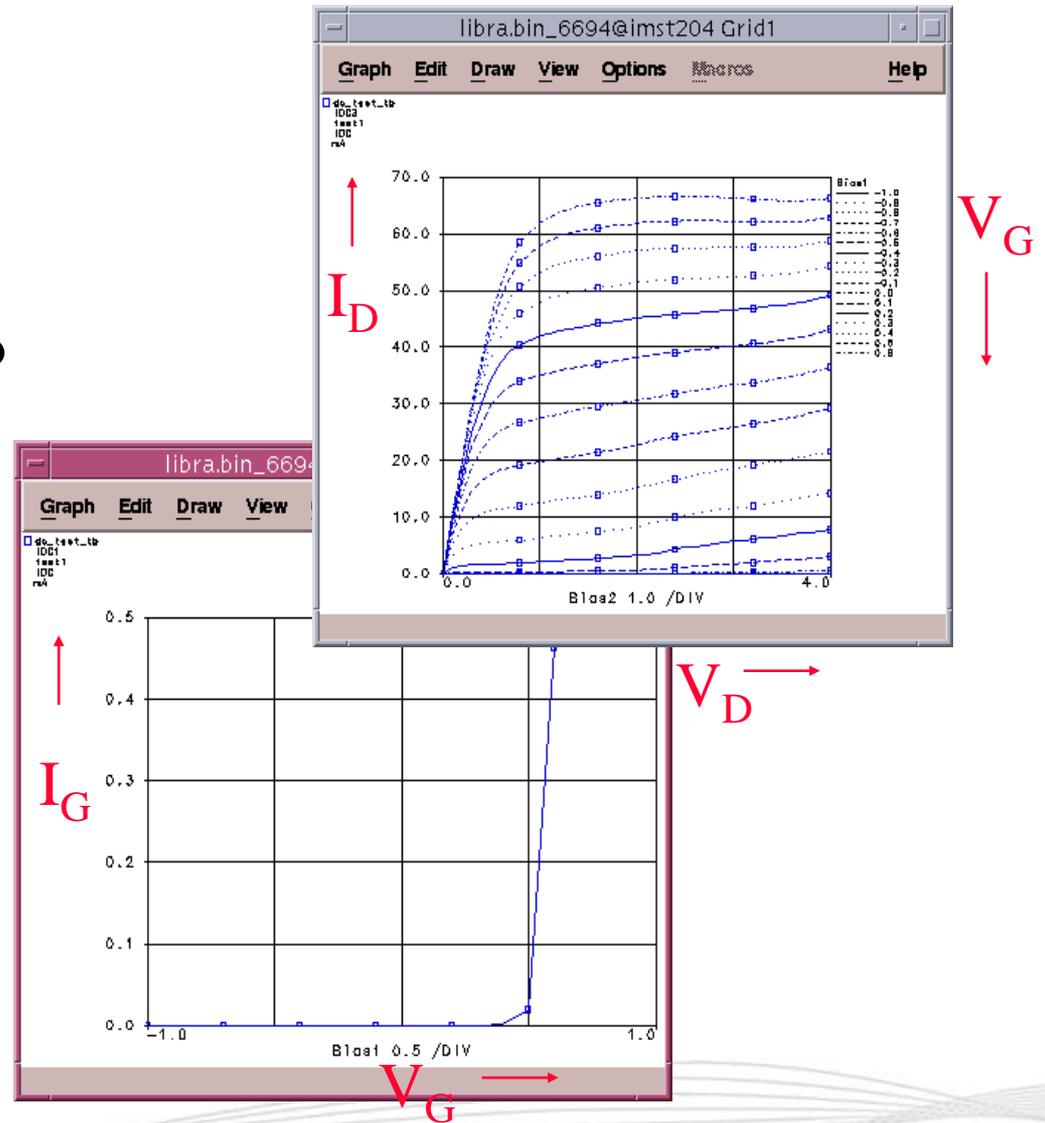


DC testbench



# DC tests

- IV output curves OK?
- IV input curves OK?
- Curves typical for element?
- Show measurements similar behaviour?

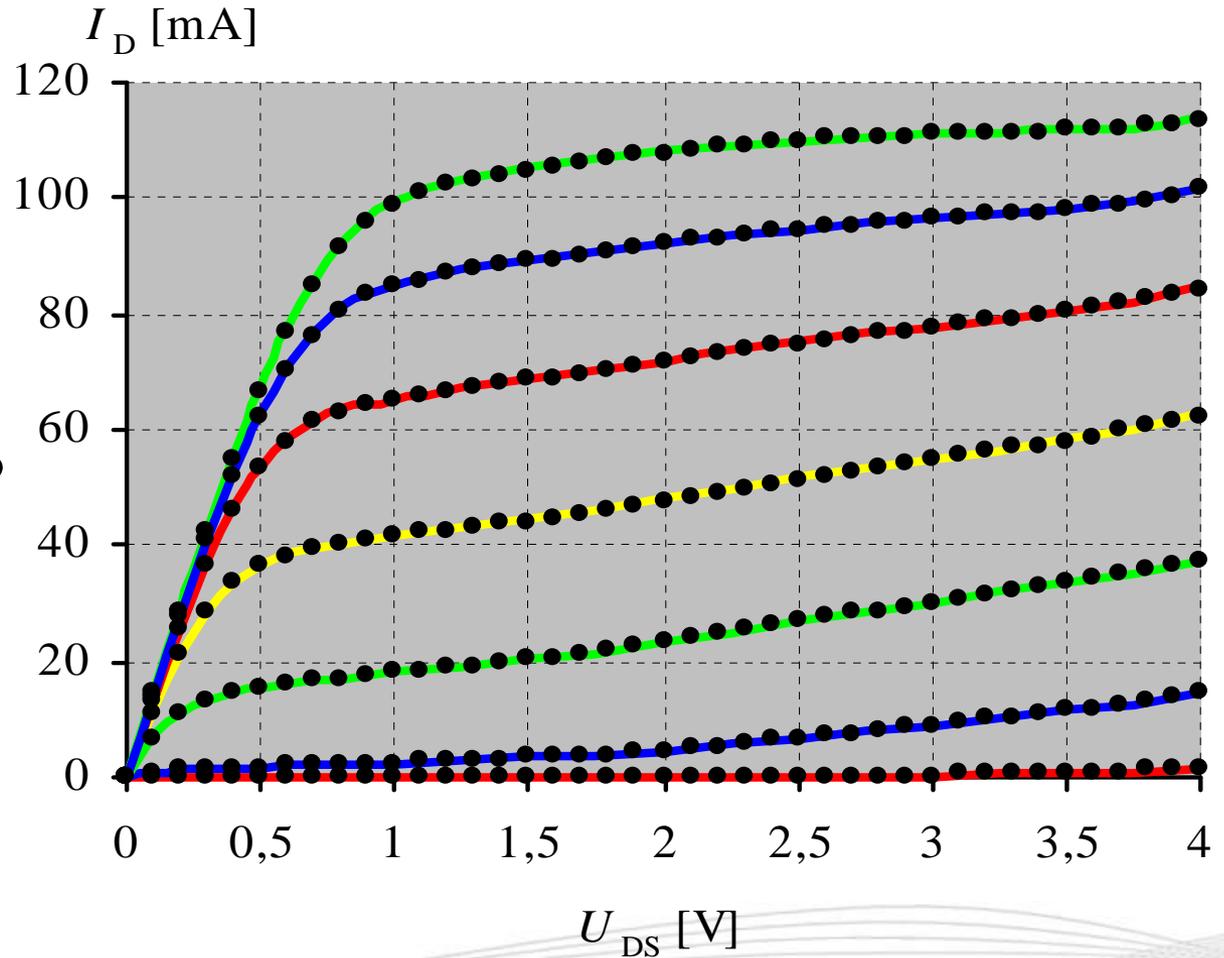




# DC tests

T4x50 $\mu\text{m}$  HEMT, simulation vs. measurements

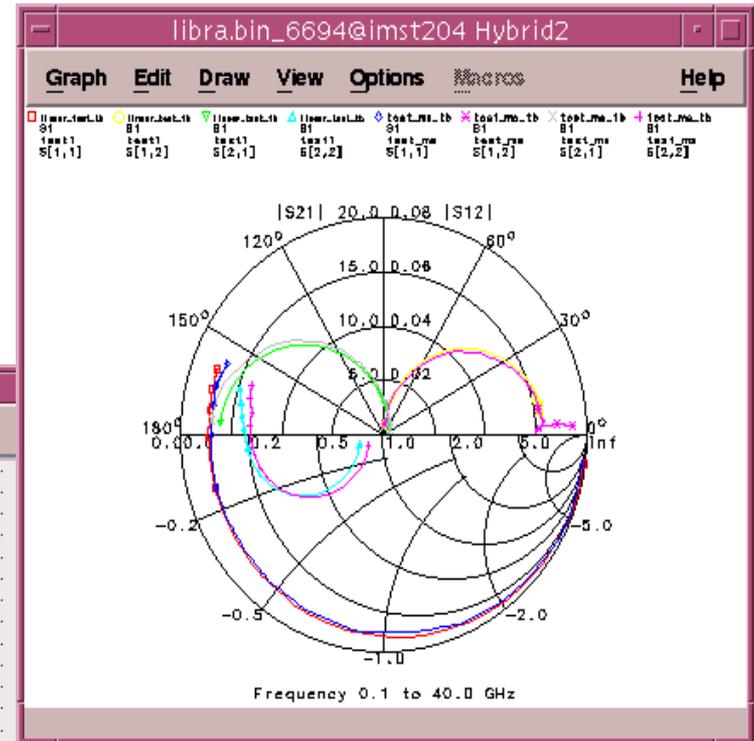
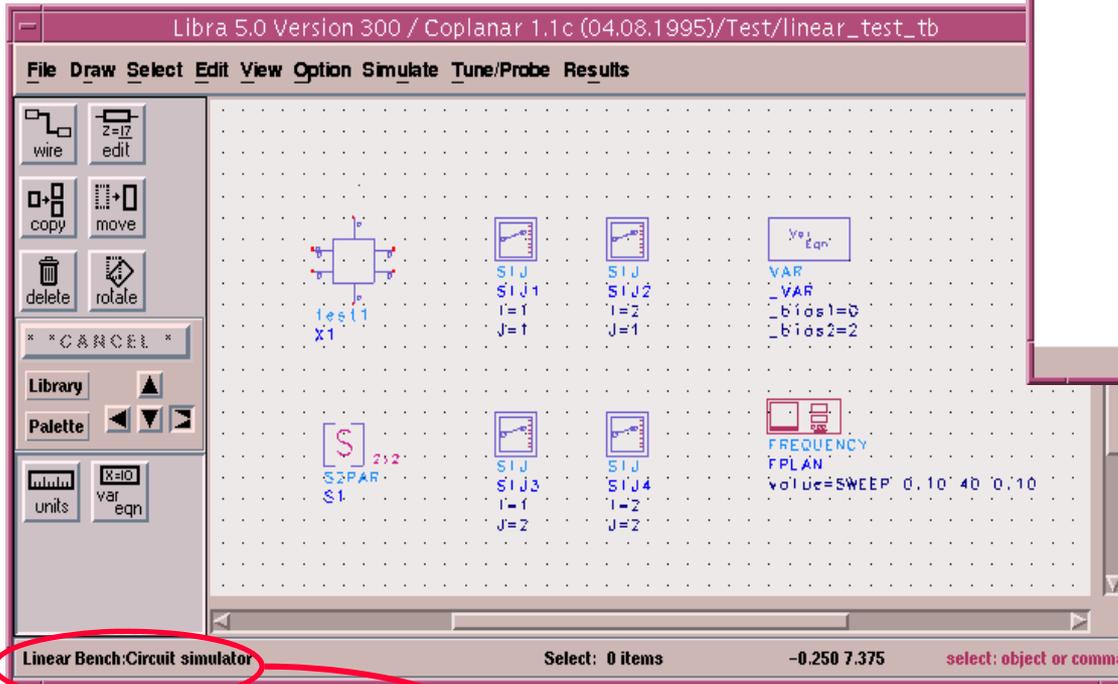
Show simulation and measurements similar behaviour?



# RF Tests

Are measured and simulated S-parameters similar ?

Transistor: Gain, pinch-off S-parameters OK?

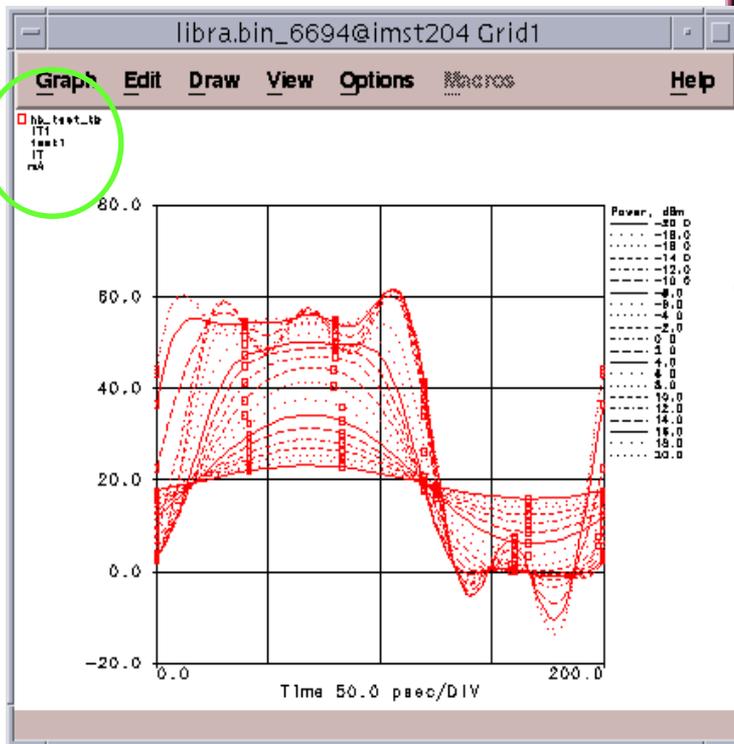
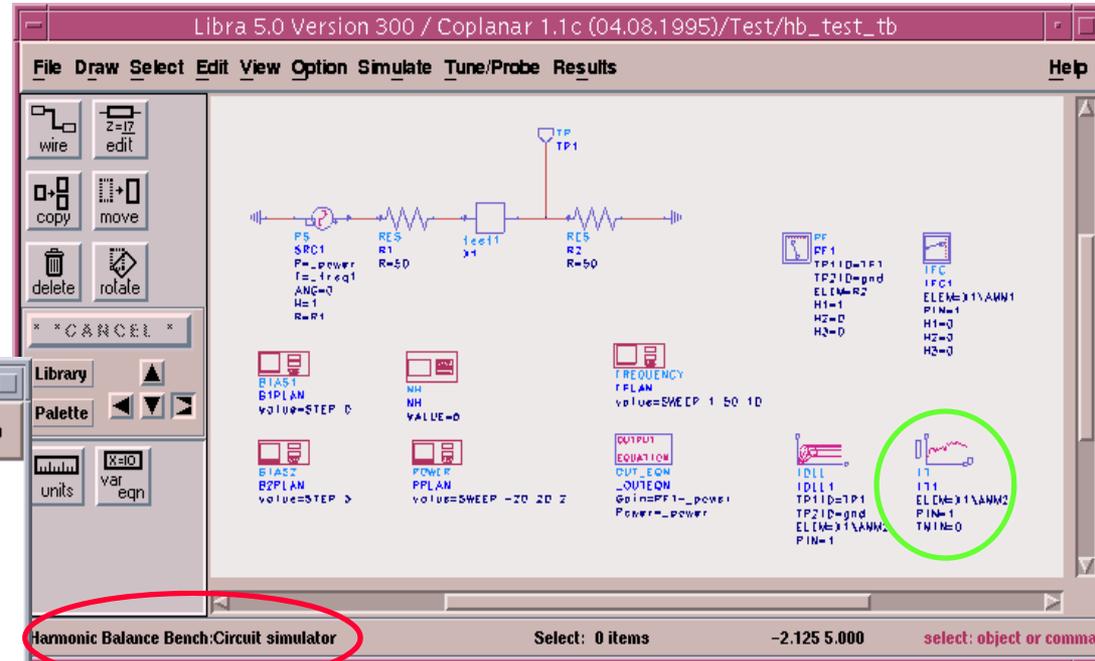


Diode: Forward and reverse S-parameters OK?

Lineares testbench

# HB tests

Simulate a power sweep



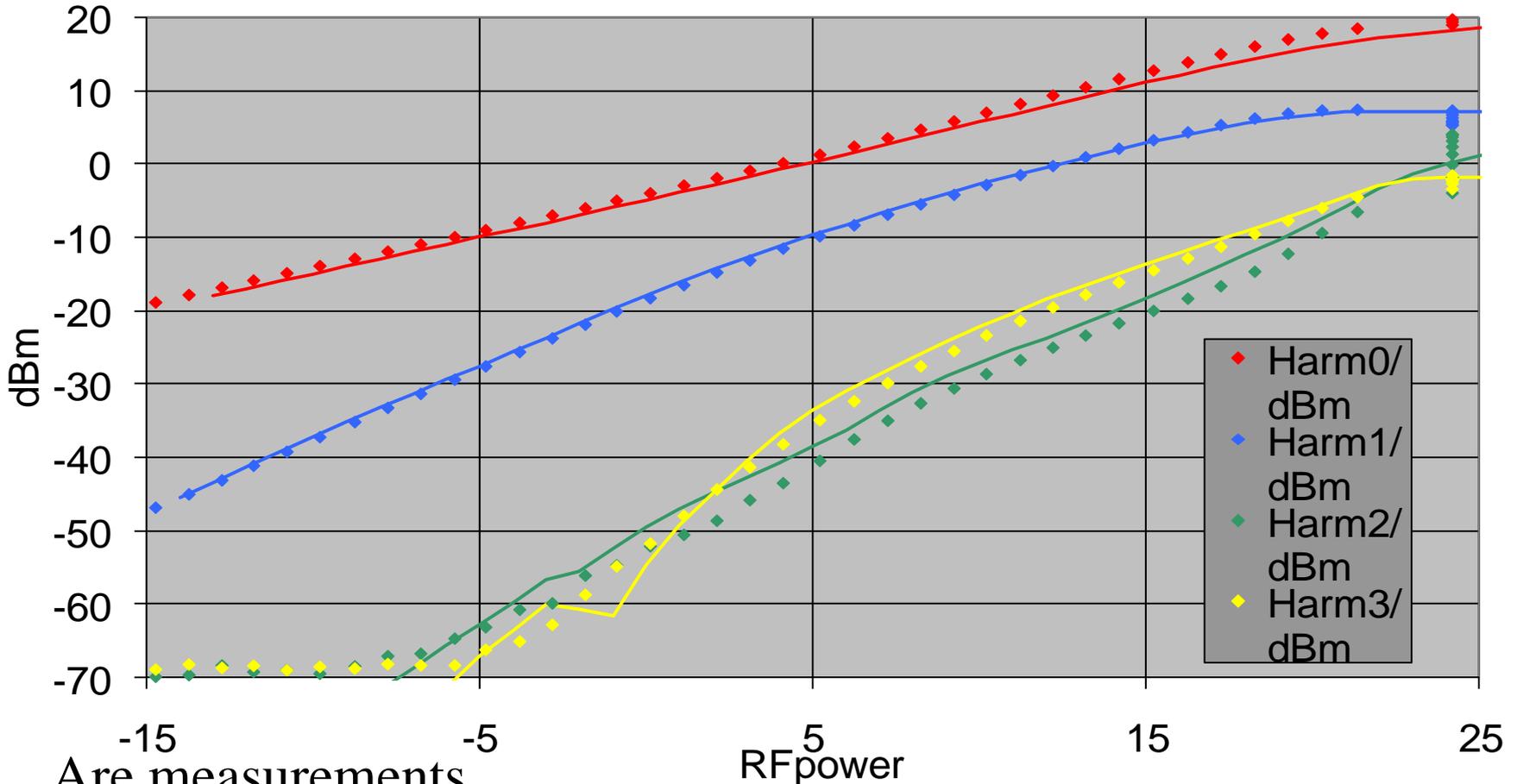
Harmonic Balance testbench

Is the behaviour as expected?  
Are the nonlinearities dominant  
for high input power



# HB tests

Comp 1x600 2.1 GHz , 26 V, 2.1 mA



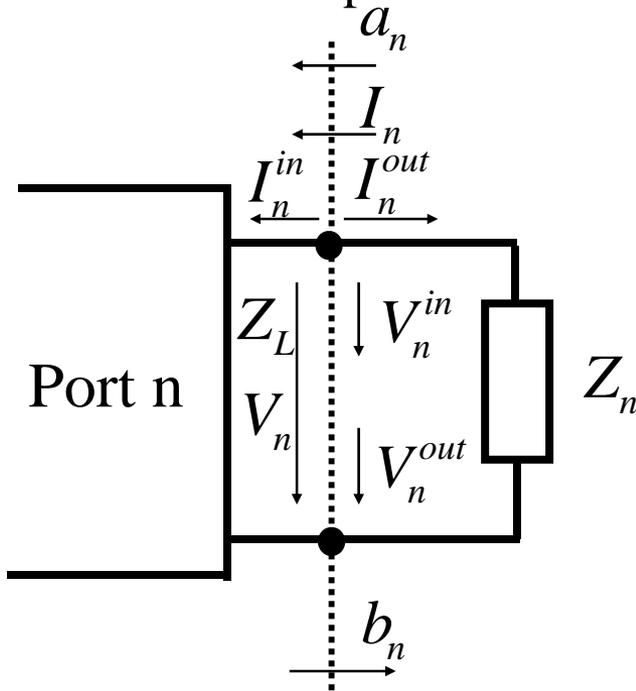
Are measurements  
and simulations  
similar ?

How good is the  
quality of the model ?



# Consistent implementation

Calculation of s-parameters using voltage and current definition



Waves in and out of port n

$$a_n = \frac{V_n^{in}}{\sqrt{Z_{Ln}}} = I_n^{in} \sqrt{Z_{Ln}}$$

$$b_n = \frac{V_n^{out}}{\sqrt{Z_{Ln}}} = I_n^{out} \sqrt{Z_{Ln}}$$

Currents and voltages

$$u_n = \frac{V_n}{\sqrt{Z_{Ln}}} = \frac{V_n^{in} + V_n^{out}}{\sqrt{Z_{Ln}}} = a_n + b_n$$

$$i_n = I_n \sqrt{Z_{Ln}} = (I_n^{in} - I_n^{out}) \sqrt{Z_{Ln}} = a_n - b_n$$

$$\Rightarrow \begin{cases} a_n = \frac{1}{2}(u_n + i_n) \\ b_n = \frac{1}{2}(u_n - i_n) \end{cases}$$

S matrix

$$\|b\| = \|s\| \cdot \|a\|$$

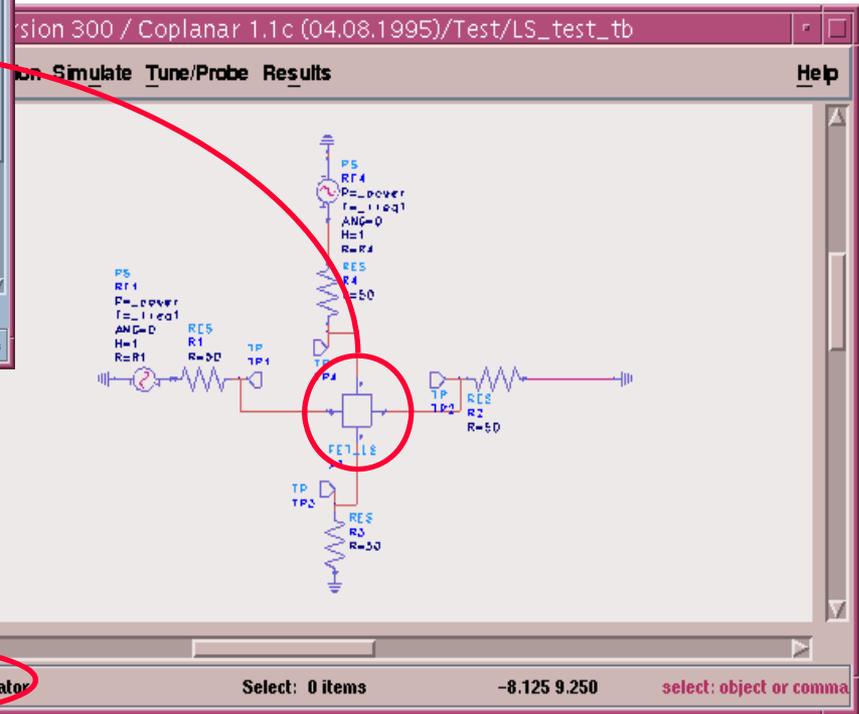
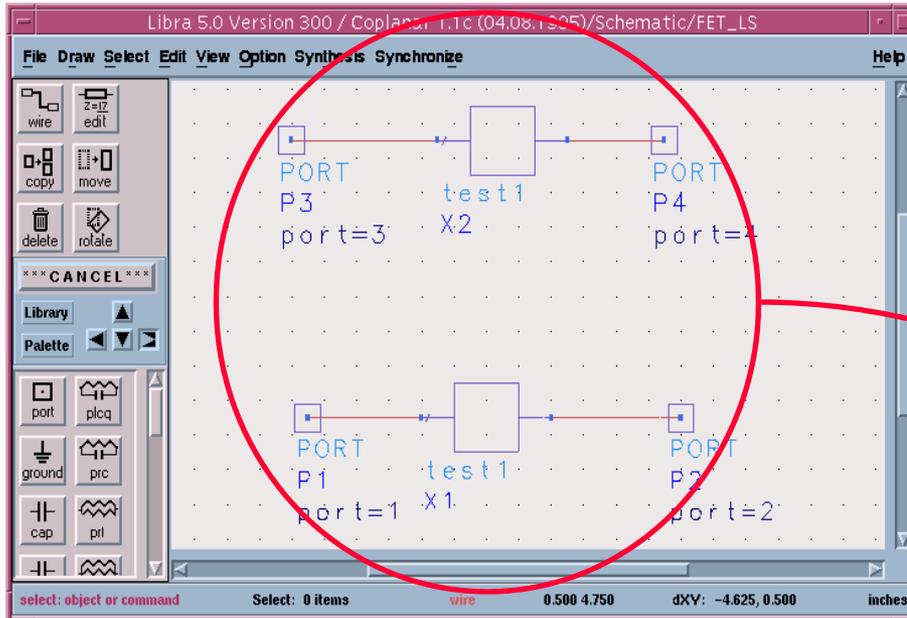
Example

$$s_{11} = \left. \frac{b_1}{a_1} \right|_{a_2=0}$$

$$s_{11,dB} = 20 \cdot \log \frac{u_1 - i_1}{u_1 + i_1}$$

# Consistent implementation

Calculation of small signal S-parameters using a large signal test bench



Harmonic balance testbench

Harmonic Balance Bench: Circuit simulator

# Consistent implementation

Calculation of small signal s-parameters using a large signal testbench

```

OUTPUT
EQUATION
OUT_EQN
_QUEQN
a11=VFC1/7.07+IFC1*7.07*1e-3
a22=VFC4/7.07+IFC4*7.07*1e-3
b11=VFC1/7.07-IFC1*7.07*1e-3
b22=VFC4/7.07-IFC4*7.07*1e-3
b21=VFC2/7.07-IFC2*7.07*1e-3
b12=VFC3/7.07-IFC3*7.07*1e-3
s11=20*log(b11/a11)
s11_ang=b11/a11
s22=20*log(b22/a22)
s22_ang=b22/a22
s21=20*log(b21/a11)
s21_ang=b21/a11
s12=20*log(b12/a22)
s12_ang=b12/a22
    
```

VFC1	IFC1	VFC2	IFC2	VFC3	IFC3
TP1 ID=TP1	ELEM=R1	TP1 ID=TP2	ELEM=R2	TP1 ID=TP3	ELEM=R3
TP2 ID=gnd	PIN=1	TP2 ID=gnd	PIN=1	TP2 ID=gnd	PIN=1
H1=1	H1=1	H1=1	H1=1	H1=1	H1=1
H2=0	H2=0	H2=0	H2=0	H2=0	H2=0
H3=0	H3=0	H3=0	H3=0	H3=0	H3=0

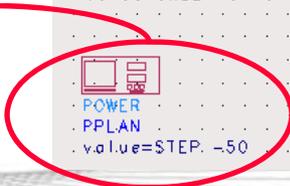
VFC4	IFC4
TP1 ID=TP4	ELEM=R4
TP2 ID=gnd	PIN=1
H1=1	H1=1
H2=0	H2=0
H3=0	H3=0

NH	P <sub>out_RF</sub>	P <sub>in</sub>	PSPEC1
NH	TP1 ID=TP2	TP1 ID=TP1	TP1 ID=TP2
VALUE=5	TP2 ID=gnd	TP2 ID=gnd	TP2 ID=gnd
	ELEM=R2	ELEM=R1	ELEM=R2
	H1=1	H1=1	
	H2=0	H2=0	
	H3=0	H3=0	

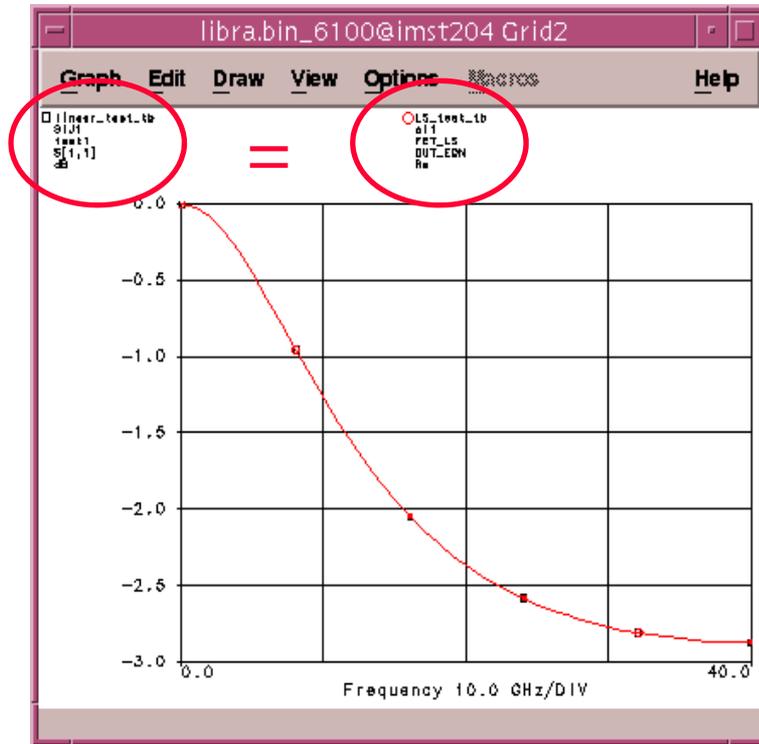
  

FREQUENCY	PPLAN	B1AS1
FPLAN	value=SWEEP: 0:10:40:1	B1PLAN
		value=STEP: 0
		B2AS2
		B2PLAN
		value=STEP: 2

Small signal!  
-50 dBm

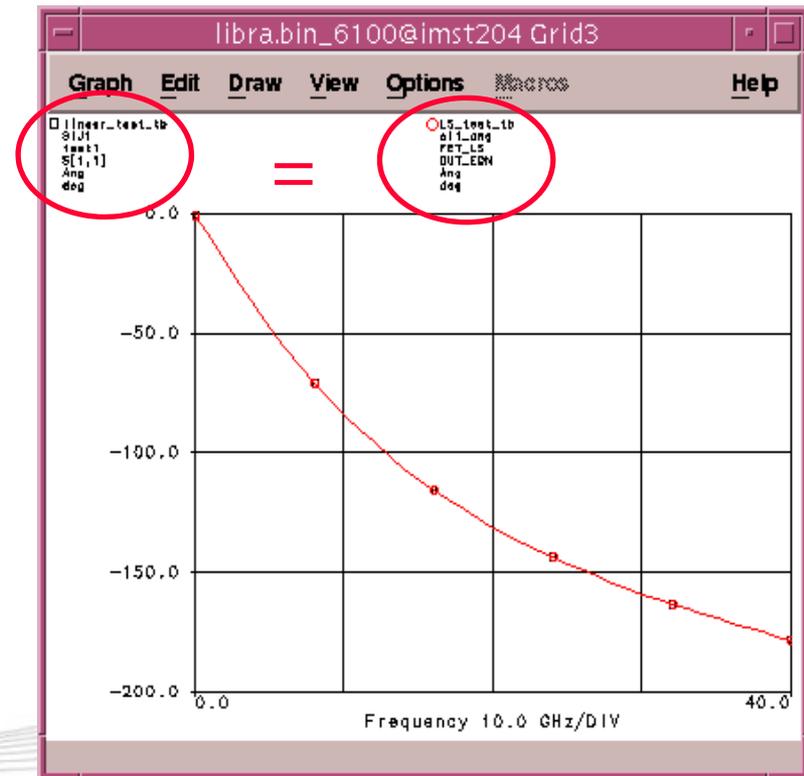


# Consistent implementation



Mag( $s_{11}$ ), simulated using  
Small signal and large signal  
testbench for very low  
input power (-50 dBm)

Phase( $s_{11}$ ), simulated using  
Small signal and large signal  
testbench for very low  
input power (-50 dBm)





# Needful things

Linearize  $\exp()$  function for better conversion and avoid errors such as numerical overflows

$$f(x) = \begin{cases} \exp(x) & x \leq x_0 \\ mx + b & x > x_0 \end{cases}$$

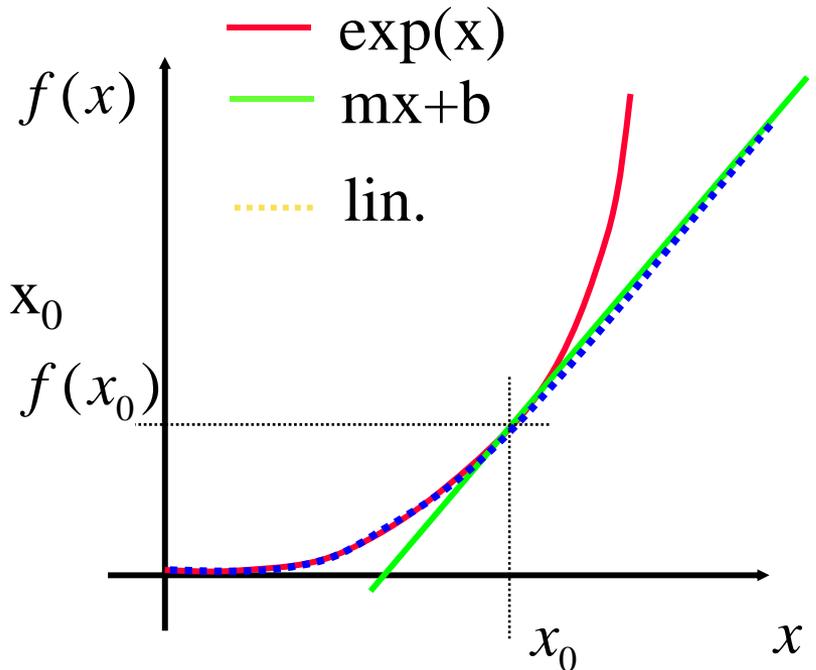
Function must be continuous at  $x_0$

$$f_1(x_0) = f_2(x_0) \quad \left. \frac{df_1}{dx} \right|_{x_0} = \left. \frac{df_2}{dx} \right|_{x_0}$$

$$\Rightarrow \exp(x_0) = mx_0 + b$$

$$m = \exp(x_0)$$

$$\Rightarrow b = \exp(x_0)(1 - x_0) \Rightarrow f_2(x) = \exp(x_0)(x + 1 - x_0)$$





# Summary

- Perform different tests (DC, RF, harmonic balance)
- Typical results for a FET
- Calculation of small signal s-parameters using a large signal testbench
- Linearization of functions



Foundries, MMICs, systems

Rüdiger Follmann



# Content

- MMIC foundries
- Designs and trends
- Examples

# MMIC foundries

## Foundries



IMST is a UMS  
certified design house



## Memberships



MOSIS



# GaAs in principal

- 3,4 and 6 inch production
- Target markets: High power and linearity, low noise, broad band
- Specials available (e.g. E/D mode or HBT and pHEMT on same wafer)
- Frequencies up to 100 GHz
- Radiation hard

# GaAs foundries

→ OMMIC, France

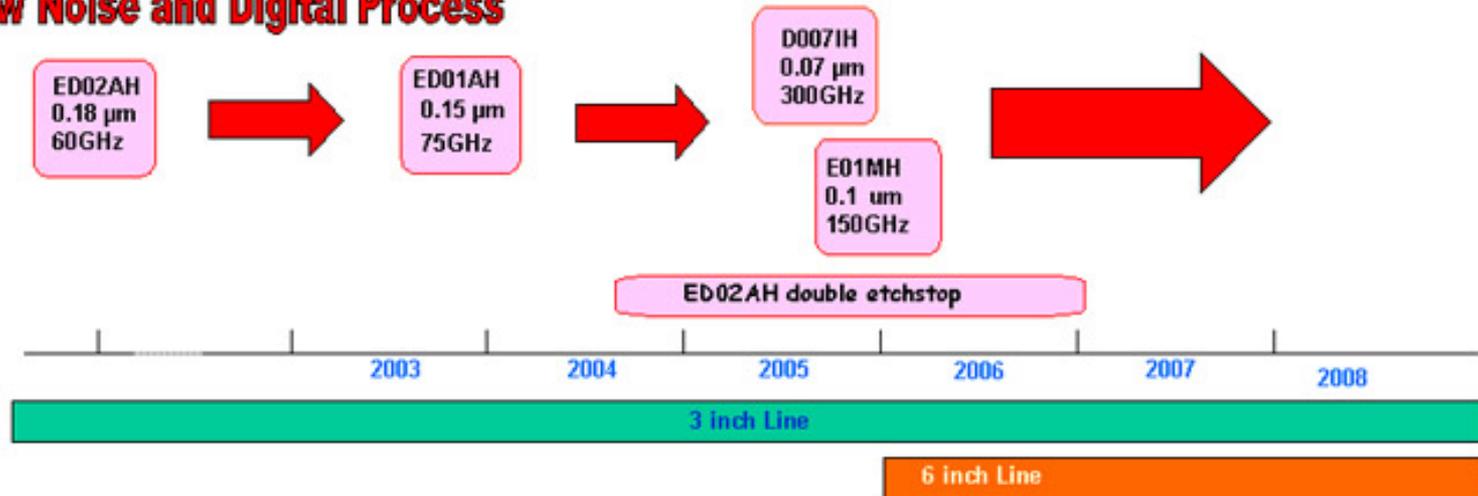
## Power Process



## InP HBT



## Low Noise and Digital Process



# GaAs foundries

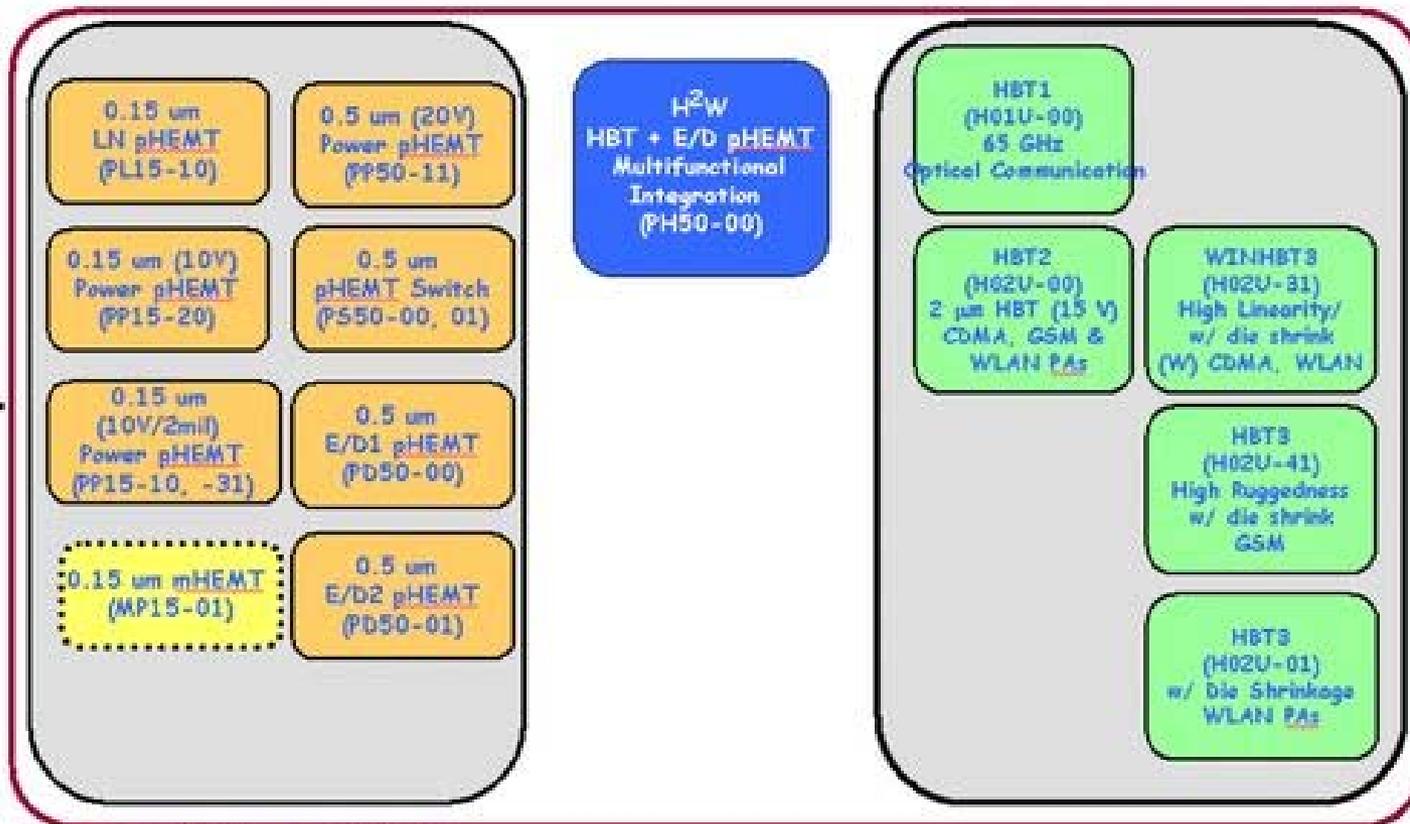
→ UMS, France (+ USA)



# WIN, Taiwan

→ WIN, Taiwan

## Technology Roadmap - In Production



• Process qualified and model ready.

• Conditional Release

# GaN

- 4 inch to 6 inch wafers
- Several foundries (TriQuint, UMS, Cree, Sandia and others)
- Very high power possible
- Defense market, radar, telecommunication
- Single transistor devices available, very first MMICs launched (IMS 2008, Cree)
- „Reliability“ problems
- Frequencies up to 20 GHz and higher (100 GHz)

# State-of-the-art

→ HRL examples

## GaN HFET MMIC Power Amplifiers

GaN POWER AMPLIFIERS

Part Number	Function	Frequency (GHz)	Gain (dB)	P1dB (dBm)	Psat (dBm)	Application Note
<a href="#">PA3C-76</a>	High Power Amplifier	71-76	15	24	26	<a href="#">X</a>
<a href="#">PA3C-86</a>	High Power Amplifier	81-86	13	24	26	<a href="#">X</a>
<a href="#">PA3C-96</a>	High Power Amplifier	91-96	12	23.5	25.5	<a href="#">X</a>

<http://www.hrl.com/media/gan/gan.html>

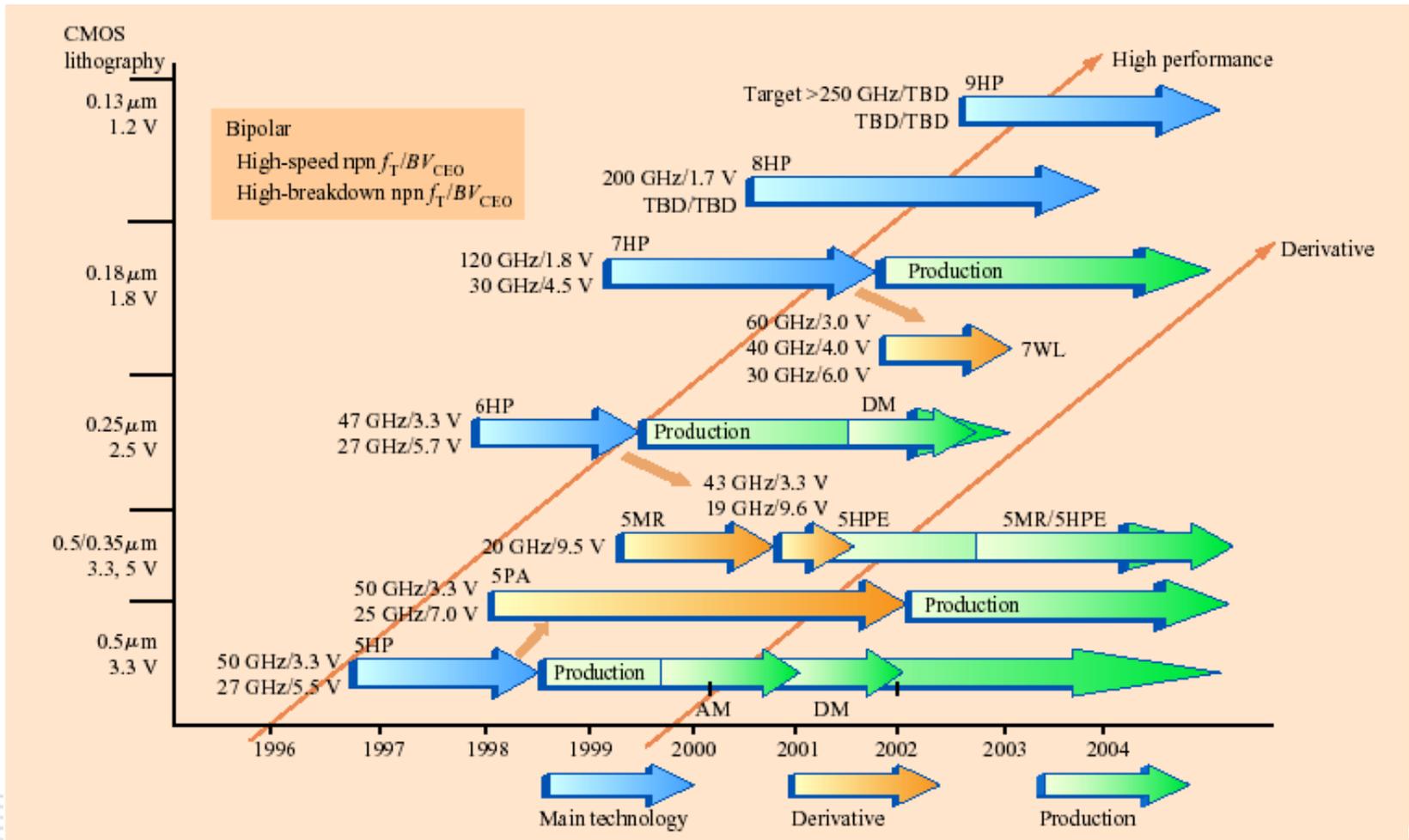
<http://kiss.caltech.edu/mmic2008/presentations/micovic.pdf>

# Si(Ge)

- 8 inch production
- Combination of CMOS logic, ECL and BiCMOS
- Frequencies up to 100 GHz
- Complete transceiver chips possible (e.g. 60 GHz)
- Well known foundries e.g. IBM (8HP)
- Si LDMOS for high power

# SiGe

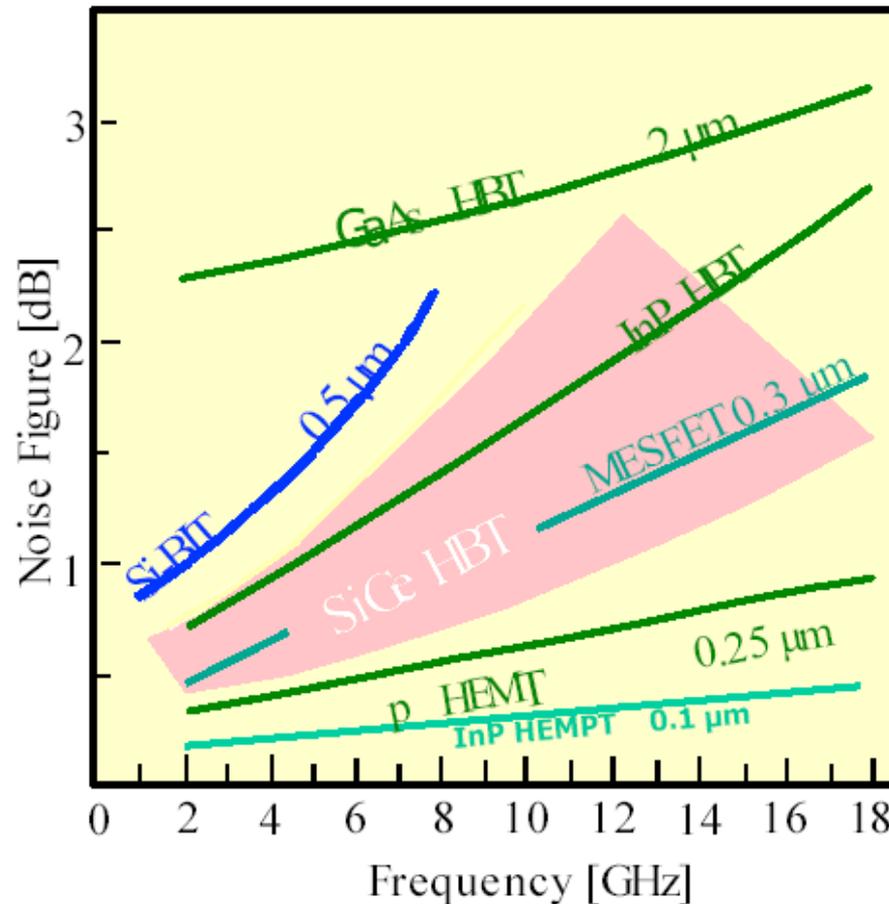
## → IBM roadmap



# Trade-offs

→ Noise figure

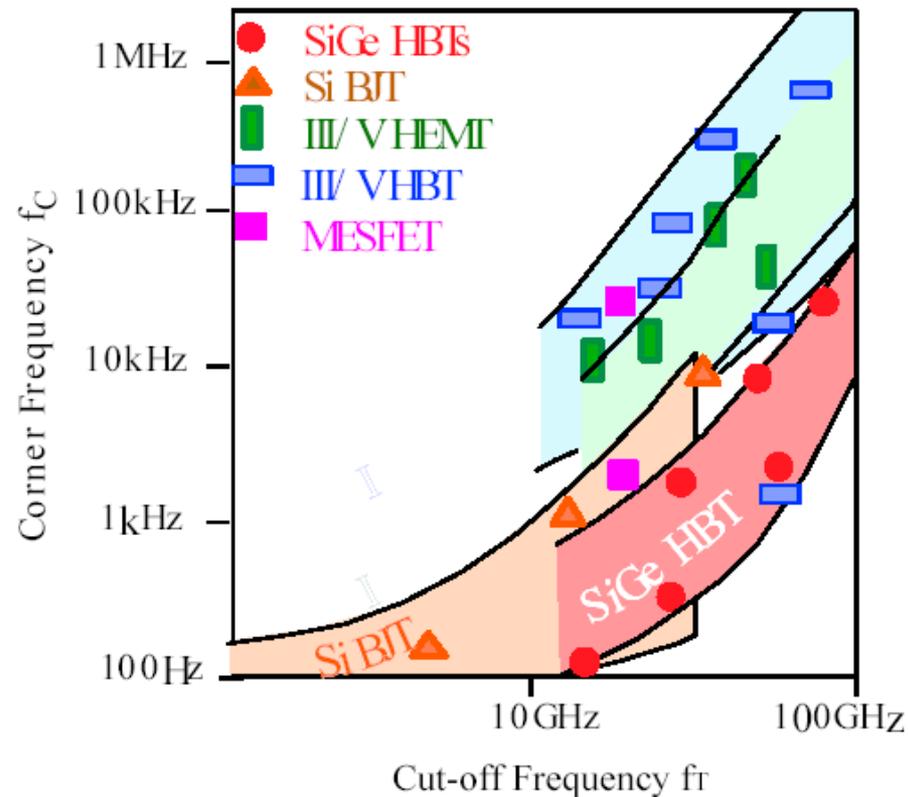
*Noise Figure Comparison of SiGe, Si & GaAs Technologies*



# Trade-offs

→ 1/f noise

*Low Frequency Phase Noise of SiGe, Si & GaAs Technologies*



# Trade-offs

→ Costs

Item	GaAs		SiGe		Units
	FET	HBT	HBT	BiCMOS	
Feature Size	0.5	2.0	0.5	0.5	μm
Starting Material	200	600	200	200	\$
Mask steps	12	14	28	32	
Photo cost	1200	1400	2800	3200	\$
Raw cost	1400	2000	3000	3400	\$
Wafer Diameter	100	100	200	200	mm
Yield	80	70	95	95	%
Cost/mm <sup>2</sup>	0.22	0.36	0.10	0.11	\$/mm <sup>2</sup>

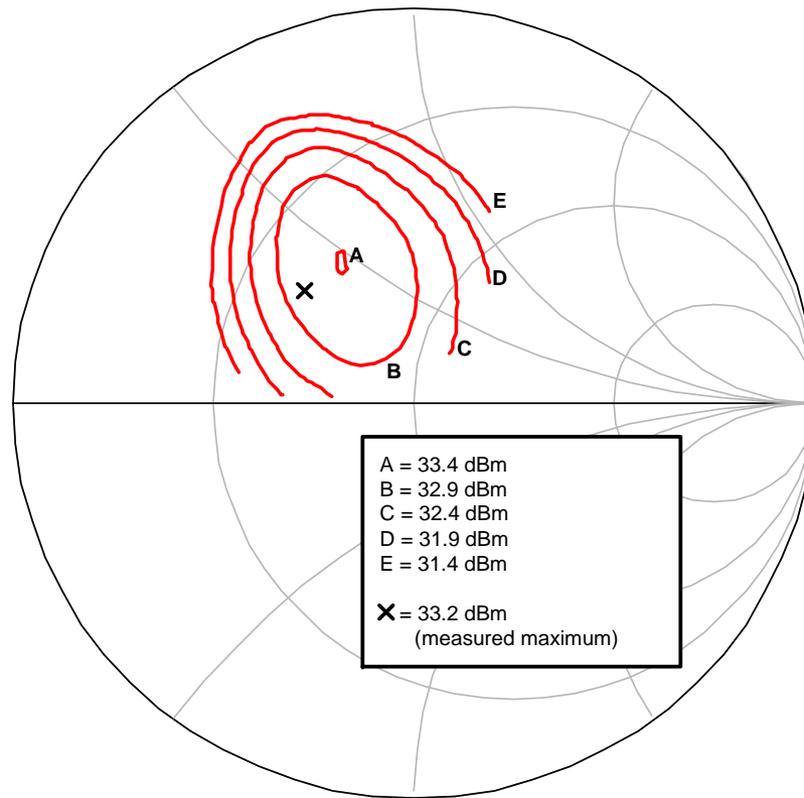
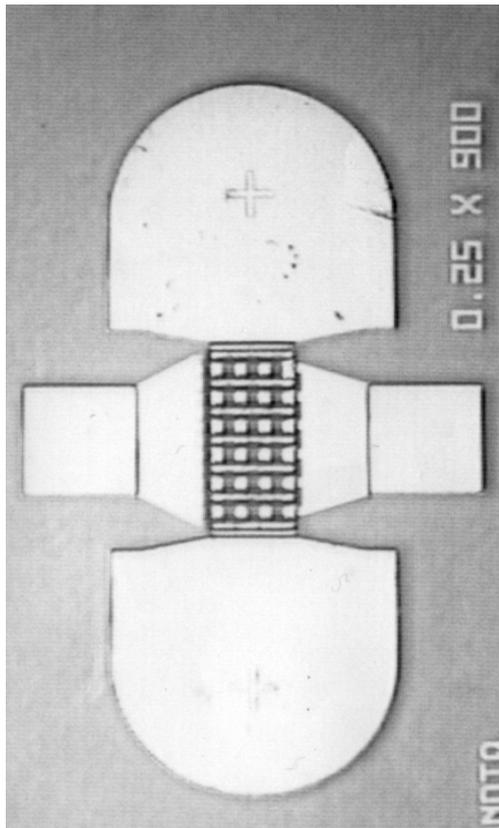
# Trade-offs

→ Power and linearity

Technology	Price/Watt	Power Density	Supply Voltage	Linearity	Frequency	PAE
Si BJT	Low Cost	Medium	26 V	Poor	<2 GHz	Low
SiGe BJT	Low Cost	Medium	<20 V	Good	>2 GHz	High
Si LDMOS	Low Cost	Low	26 V	Very Good	<3 GHz	Medium
GaAs MESFET	Competitive	Medium	12 V	Good	>2 GHz	Medium
GaAs pHEMT	Medium	Medium	8 V to 12 V	Very Good	>2 GHz	High
GaAs HBT	Competitive	High	8 V to 26 V	Good	>2 GHz	High
SiC MESFET	Competitive	Very High	48 V	Good	>4 GHz	Medium
GaN HEMT	N/A	Very High	48 V	Promising	>12 GHz	High

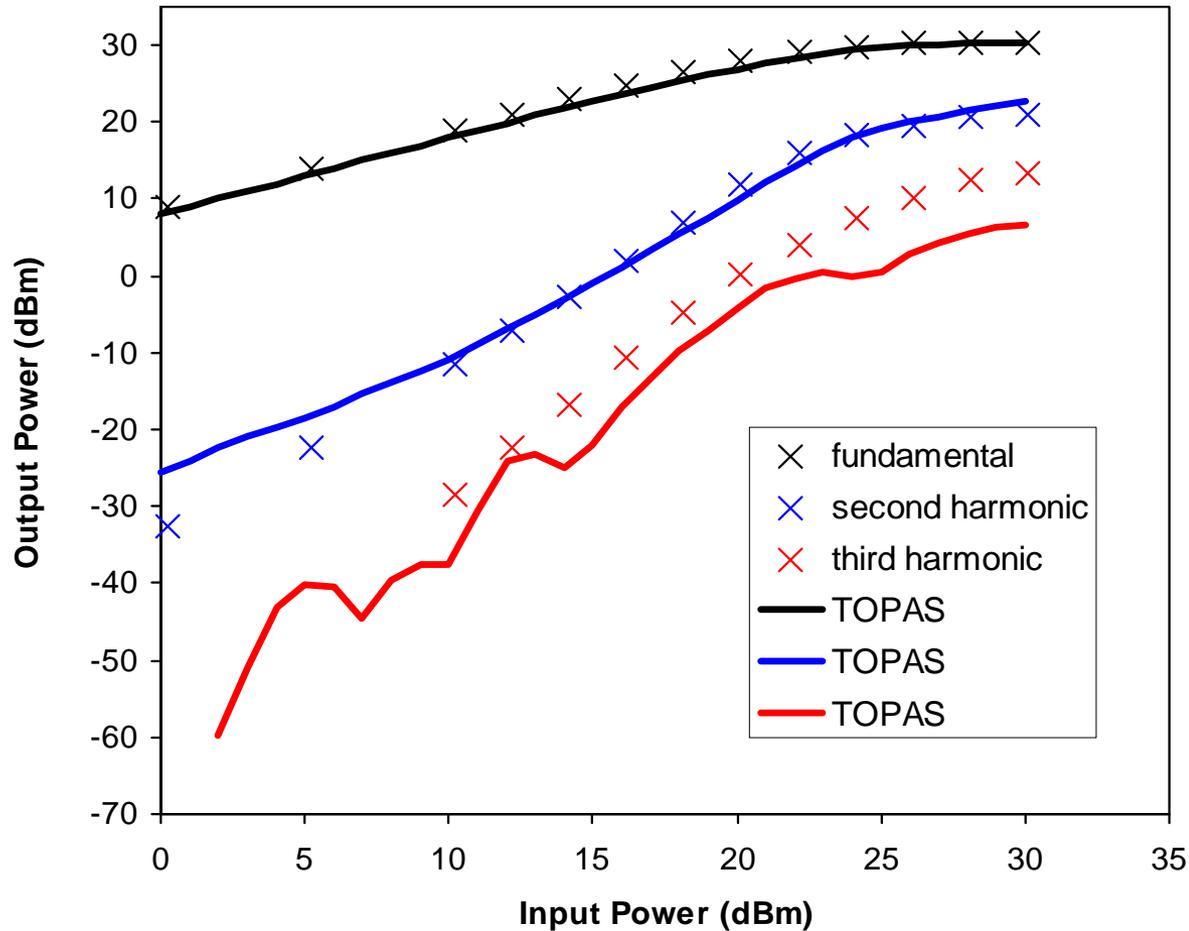
# GaN devices

→ Non-linear model and measurement



# GaN devices

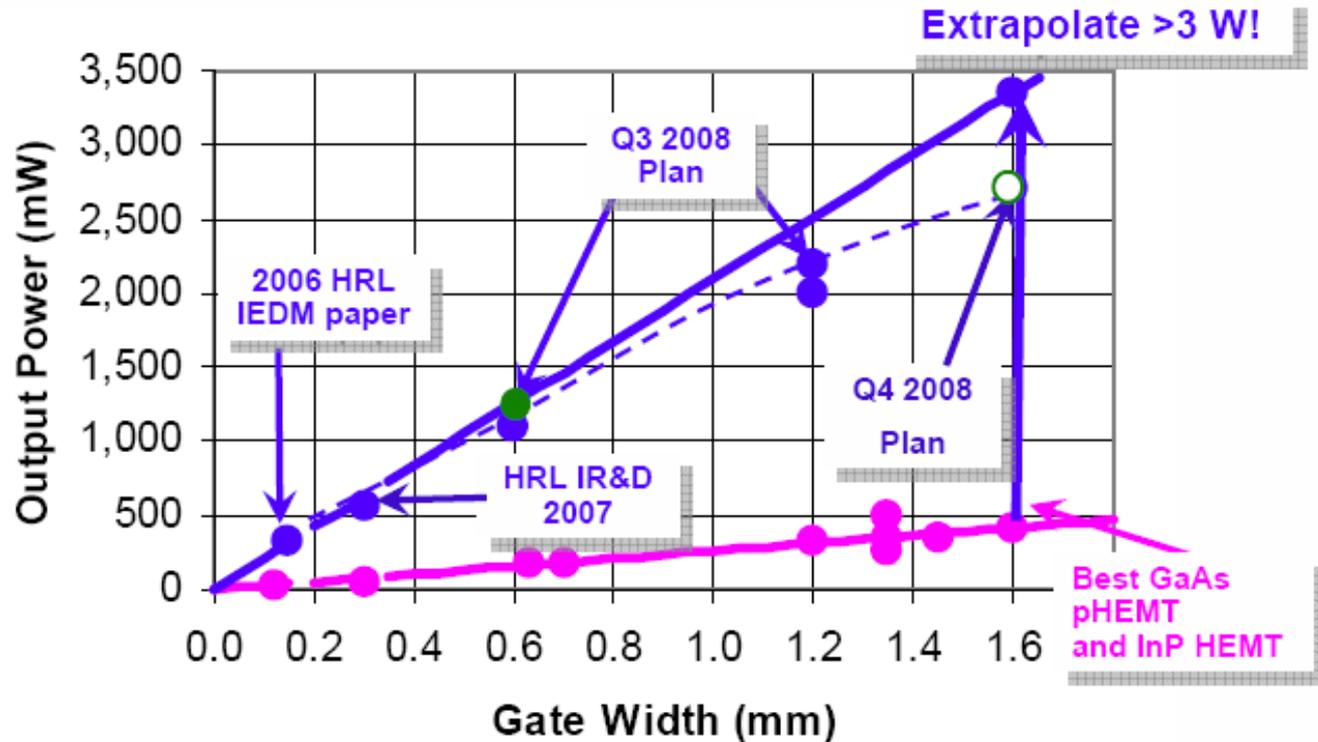
→ Model verification



# GaN mmwave power



## HRL W-band GaN Roadmap



**Disruptive W-band GaN Power MMICs**  
**8X higher power density than mmW GaAs pHEMT**



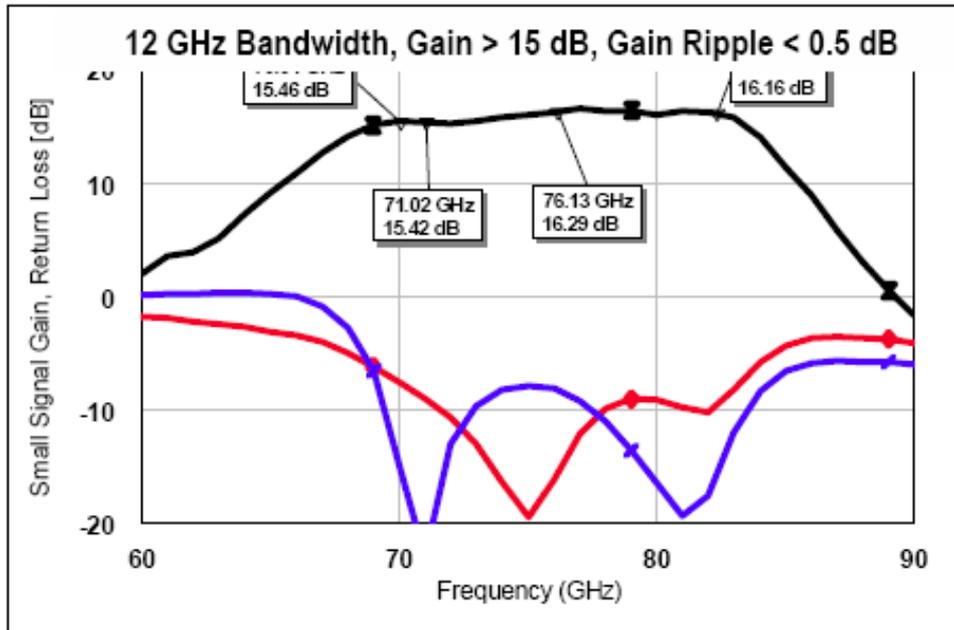
# GaN mmwave PA



## 500 mW 70 GHz GaN MMIC PA



70 GHz MMIC Chip Layout  
Size 3.4 mm x 1.3 mm  
Operating Voltage = 15 V  
Measured Gain > 15 dB



Measured small signal gain of 70 GHz 500 mW GaN MMIC PA.

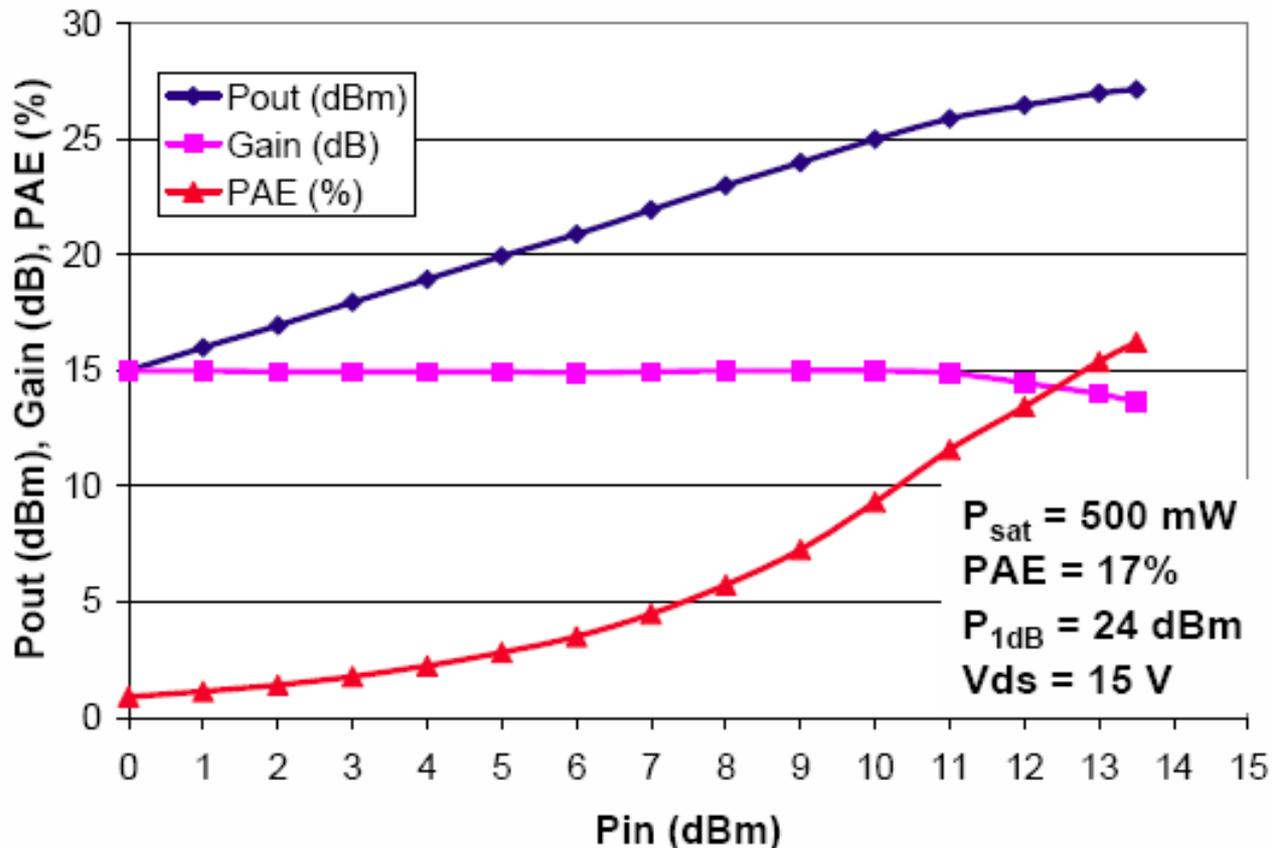
**Performance meets design goal.**



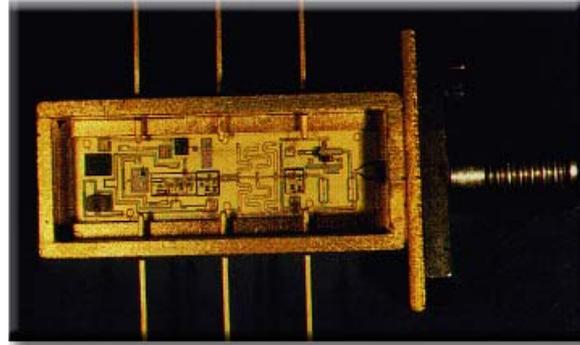
# GaN mmwave PA



Output power of 70 GHz MMIC measured at a frequency of 76 GHz

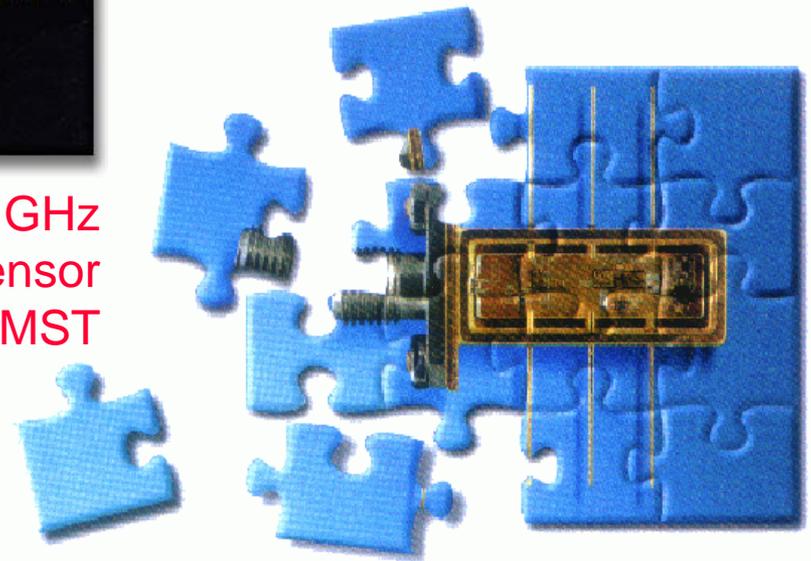


# Integrated coplanar 24 GHz sensor



Many pieces – one solution  
M5-Service.

World's 1<sup>st</sup> 24 GHz  
coplanar sensor  
designed at IMST



Rosemount 24 GHz level sensor

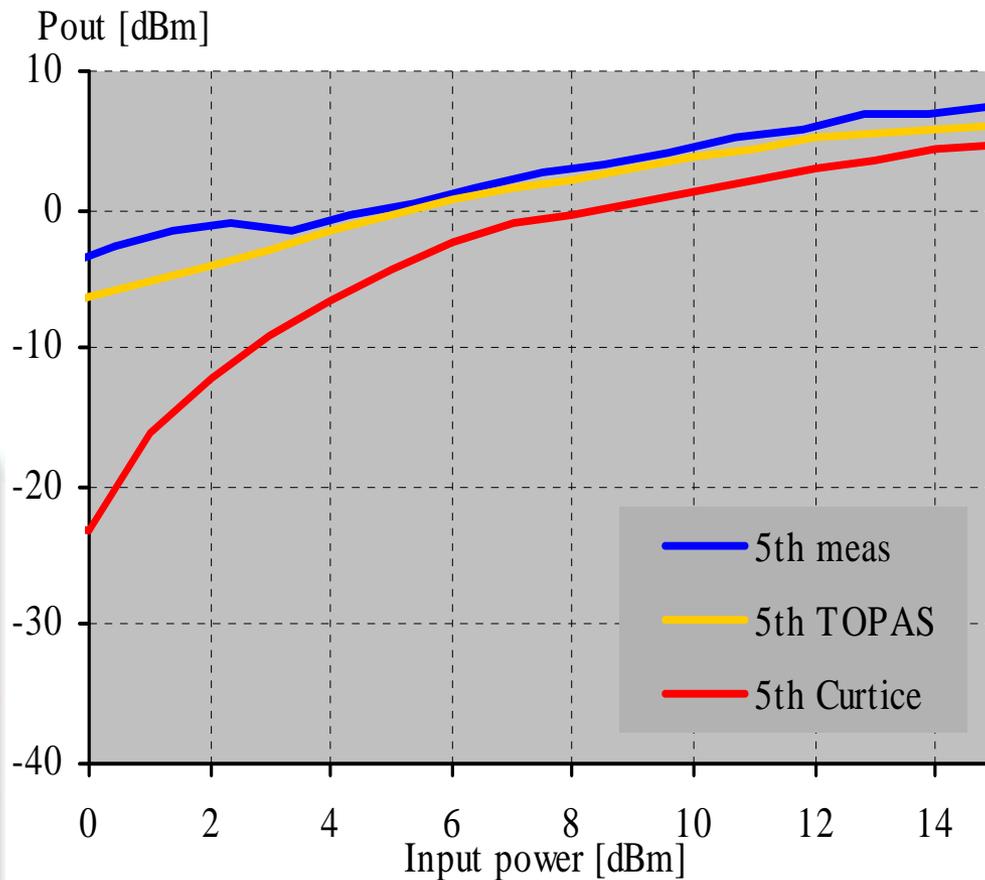
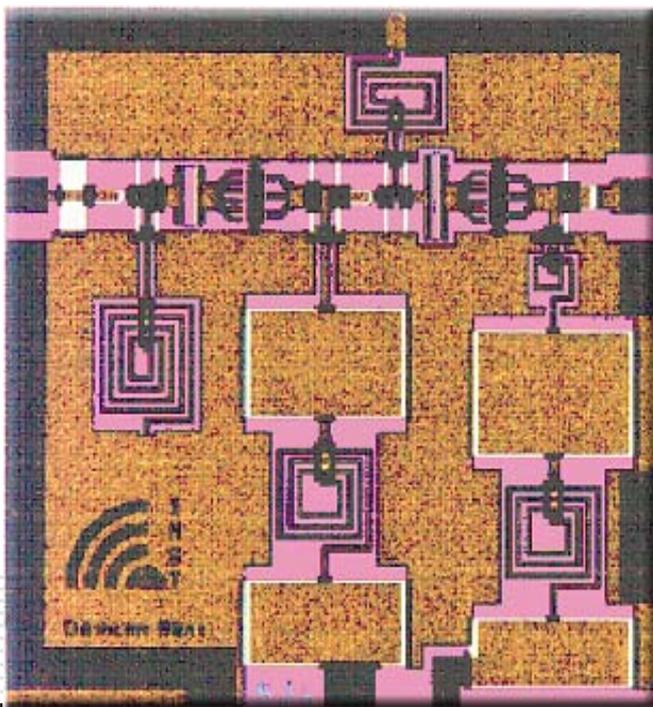


M5 Service is our understanding  
of a comprehensive service in

Microwave / Millimeterwave  
Module Engineering and  
Manufacturing.

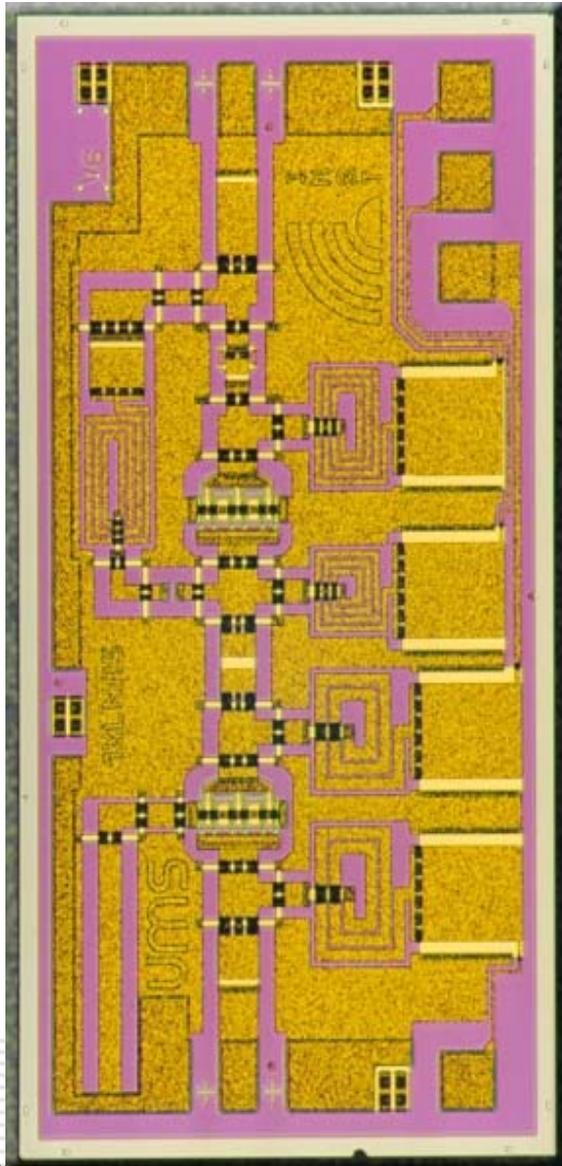
# Integrated GaAs circuits – 24 GHz sensor

Simulated using  
**TOPAS**

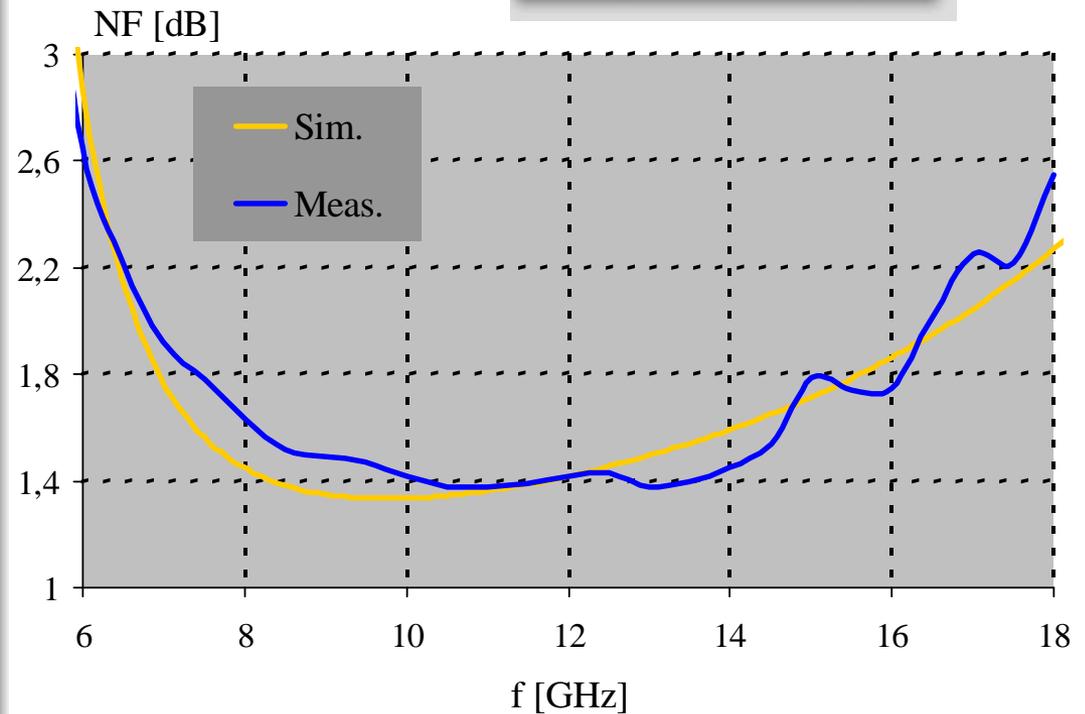


Frequency times 5 multiplier

# GaAs circuits – 10 GHz LNA



Simulated  
using



Low noise amplifier

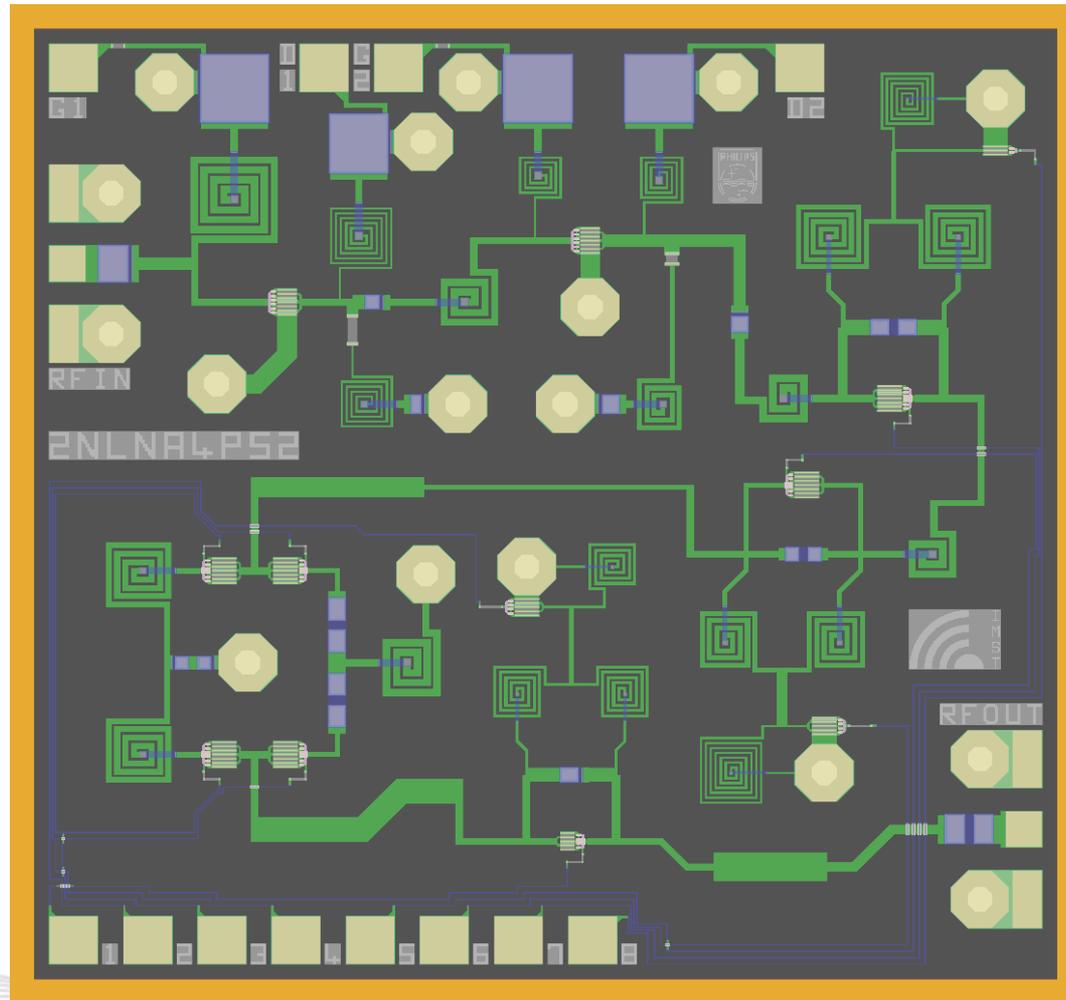
# Core Chip Design : 2NLNA4PS2

## Specifications:

- Ku-band core chip including the 2-stage LNA and the 4-bit phase shifter
- Technology: OMMIC - ED02AH
- LNA bias supply:  $V_{G1,2} = -0.2 \text{ V}$ ,  $V_{D1,2} = 2.0 \text{ V}$ ,  $I_{D1} = 28.2 \text{ mA}$ ,  $I_{D2} = 29.0 \text{ mA}$
- PS control voltages:  $V_C = 0 \text{ V} / -2 \text{ V}$
- $f = 10.7 \dots 12.7 \text{ GHz}$
- $S_{11} \leq -13.3 \text{ dB}$  (all states)
- $S_{22} \leq -11.6 \text{ dB}$  (all states)
- $S_{21} = 13.2 \dots 14.4 \text{ dB}$  (all states)
- RMS amplitude error = 0.4 dB
- RMS phase error = 2.6 °
- $A = 2.17 \times 2.05 \text{ mm}^2 = 4.45 \text{ mm}^2$ 
  - ⇒ including half dicing street
  - ⇒ including DC pads (#8) for the PS control (not necessary if using the DC control circuit)
  - ⇒ excluding DC control circuit (serial to parallel converter + buffers)

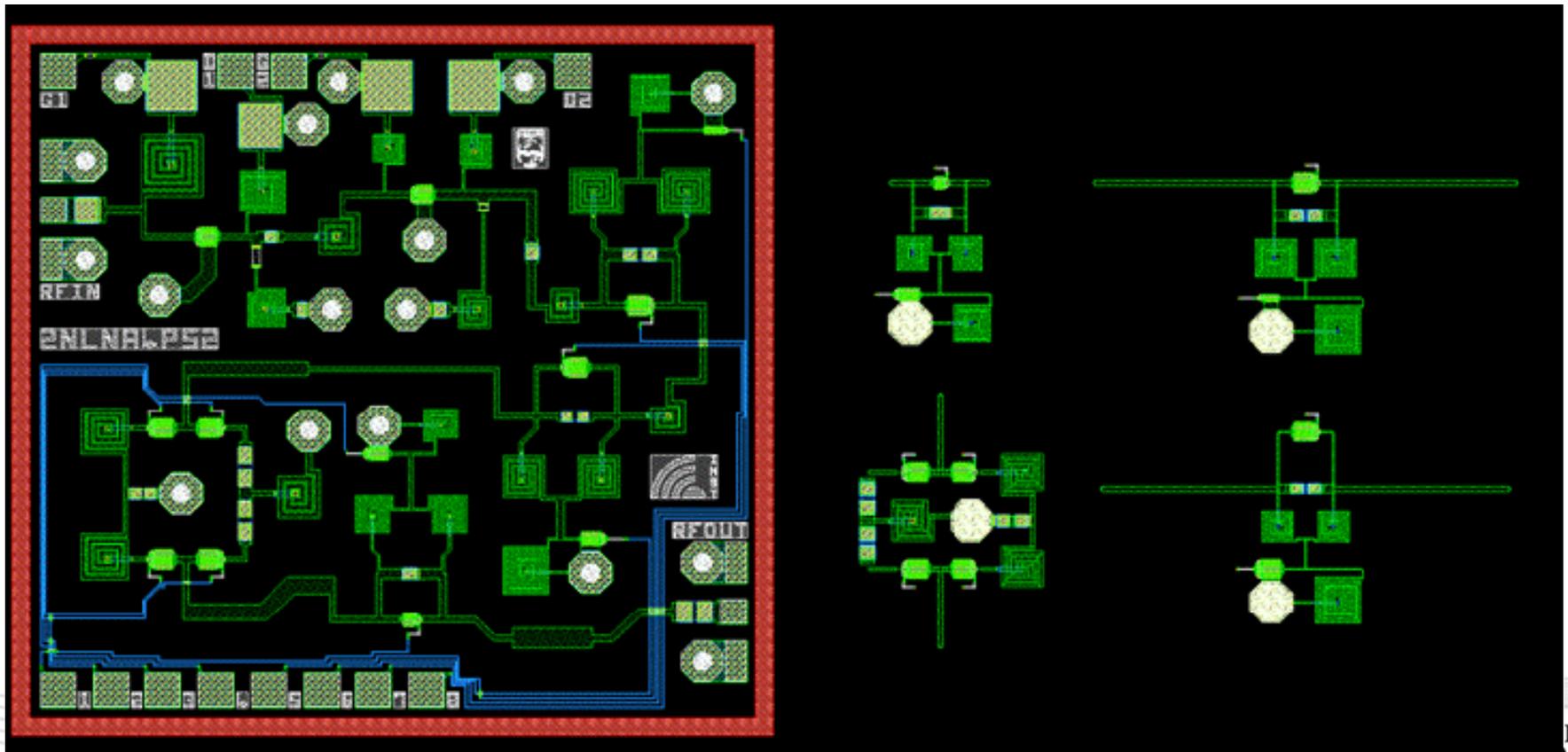
# Core Chip Design : 2NLNA4PS2

Layout:

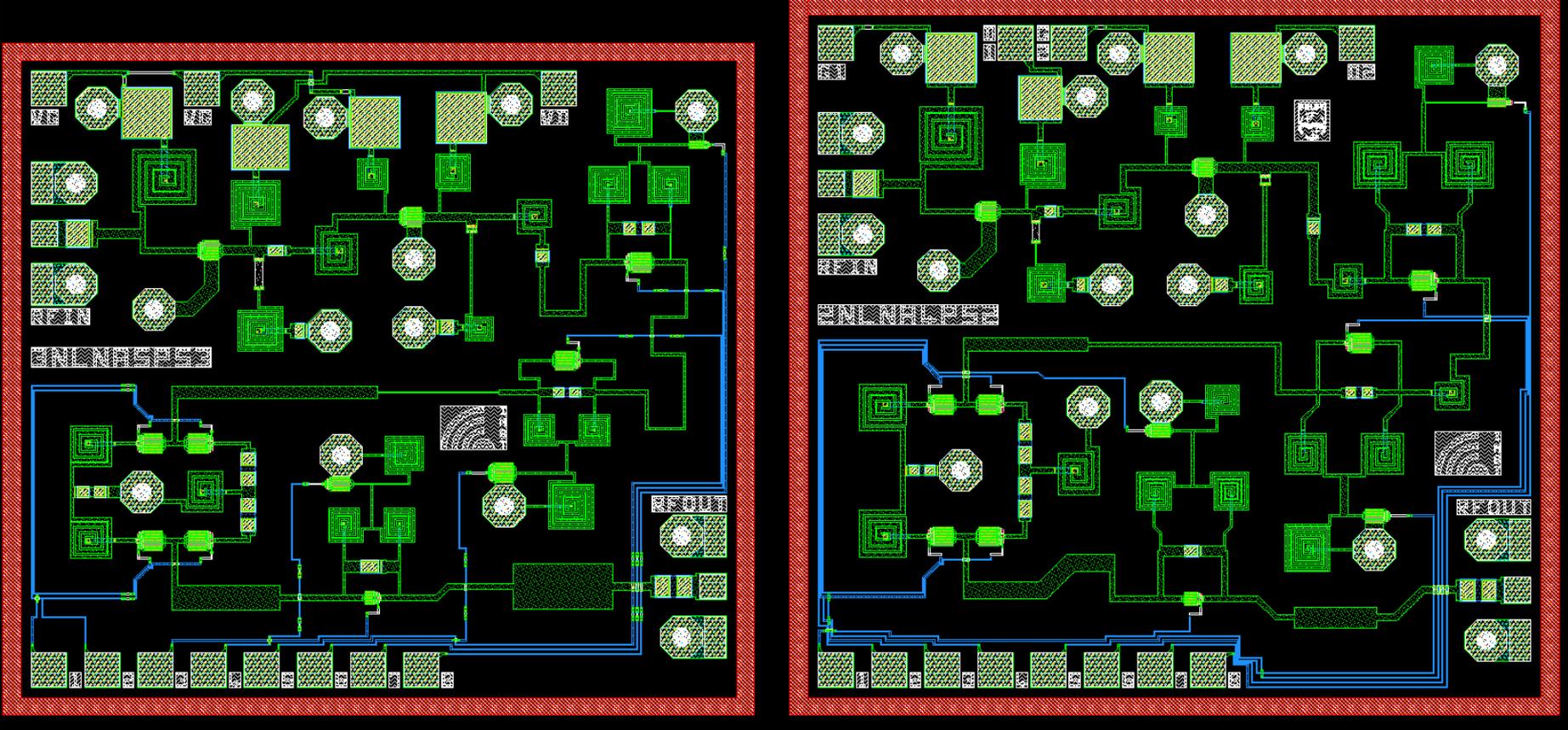


# Momentum simulation

→ Higher integration possible

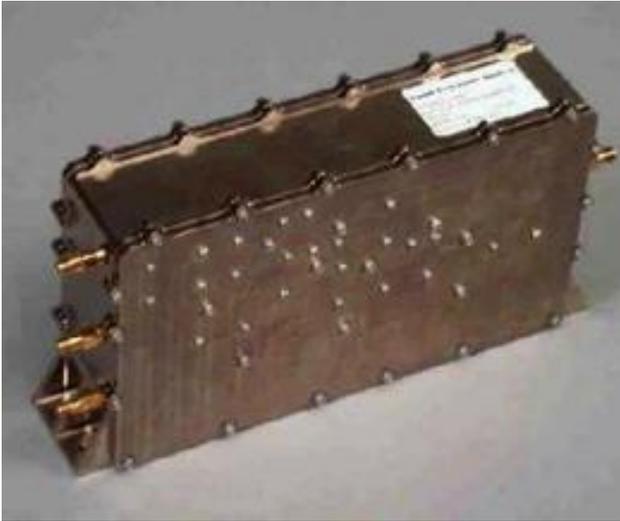


# Size reduction



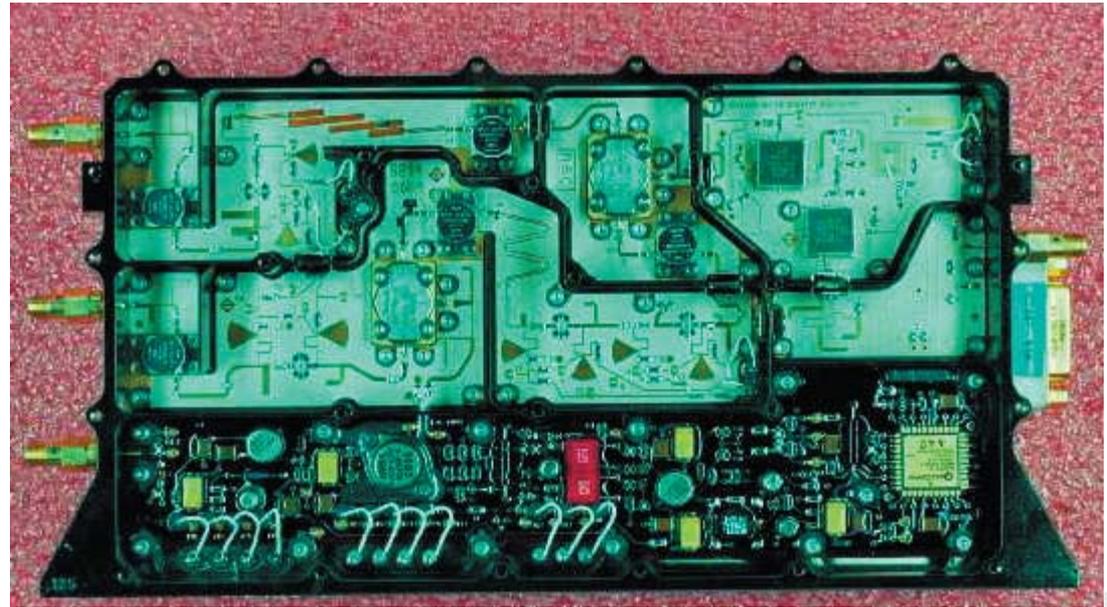


# System example synthesizer



- Large size (LO)
- Heavy
- Single frequency

→ small and integrated chip



[http://www.saabgroup.com/en/ProductsServices/BusinessUnit/saab\\_ericsson\\_space.htm](http://www.saabgroup.com/en/ProductsServices/BusinessUnit/saab_ericsson_space.htm)

<http://products.saabgroup.com/PDBWebNew/GetFile.aspx?PathType=ProductFiles&FileType=Files&Id=6071>

# Phase noise

Simplified Leeson equation

$$L(f_m) = \frac{FkTG}{8Q_L P} \left( \frac{f_r}{f_m} \right)^2$$

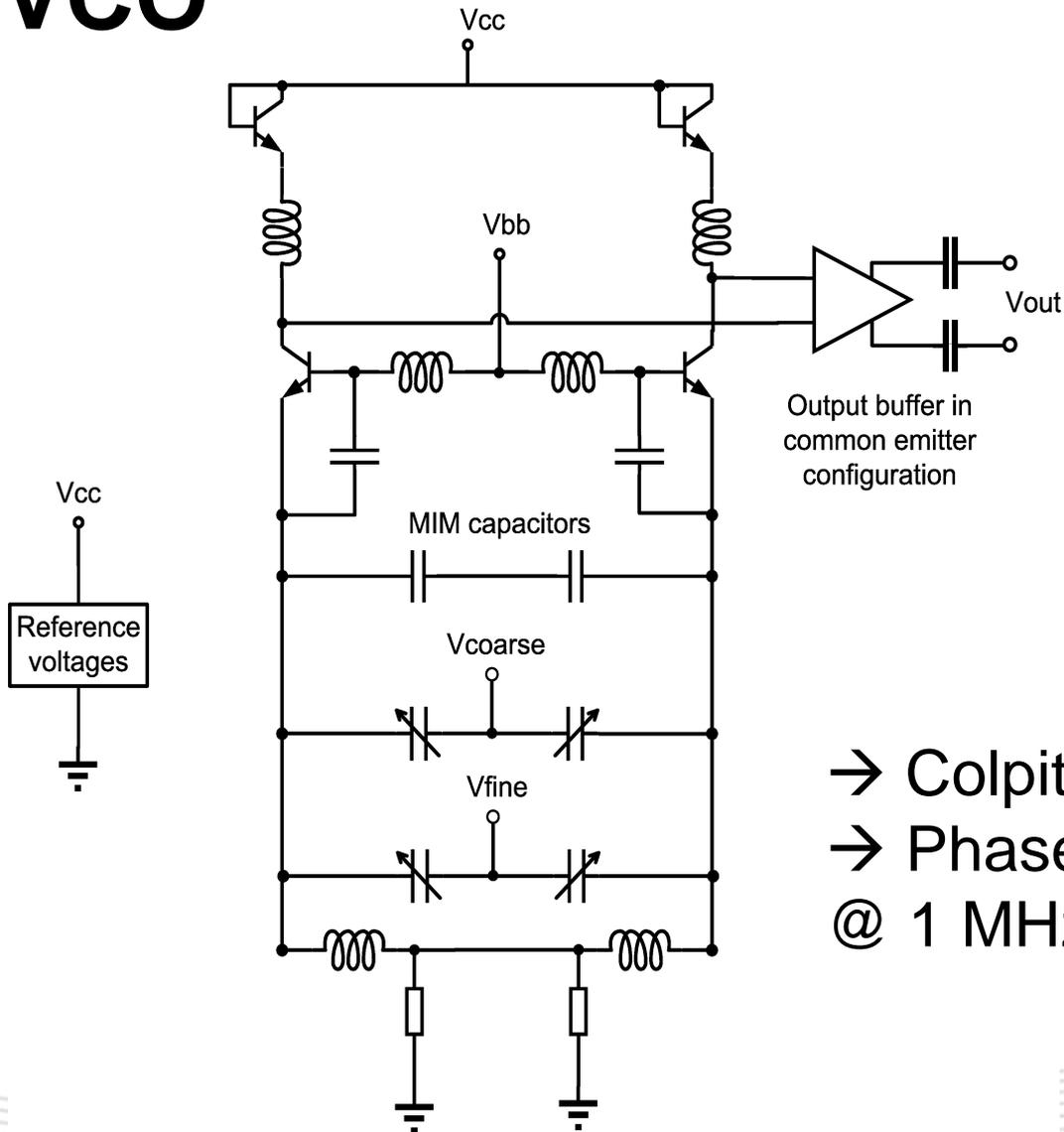
$$|S_{21}| = \frac{1}{G} = 1 - \frac{Q_L}{Q_0}$$

- G: Gain of active part  
F: Noise figure of active part  
Q<sub>L</sub>: Loaded Q of resonator  
f<sub>r</sub>: Resonance frequency  
f<sub>m</sub>: Offset frequency from carrier  
P: Output power of active part  
S<sub>21</sub>: Transmission coefficient of resonator at resonance

# VCO requirement

- High quality factor of the resonator
- Large voltage swing (high output power)
- High breakdown voltage for active part transistor technology
- Use a transistor with low  $1/f$  noise

# VCO



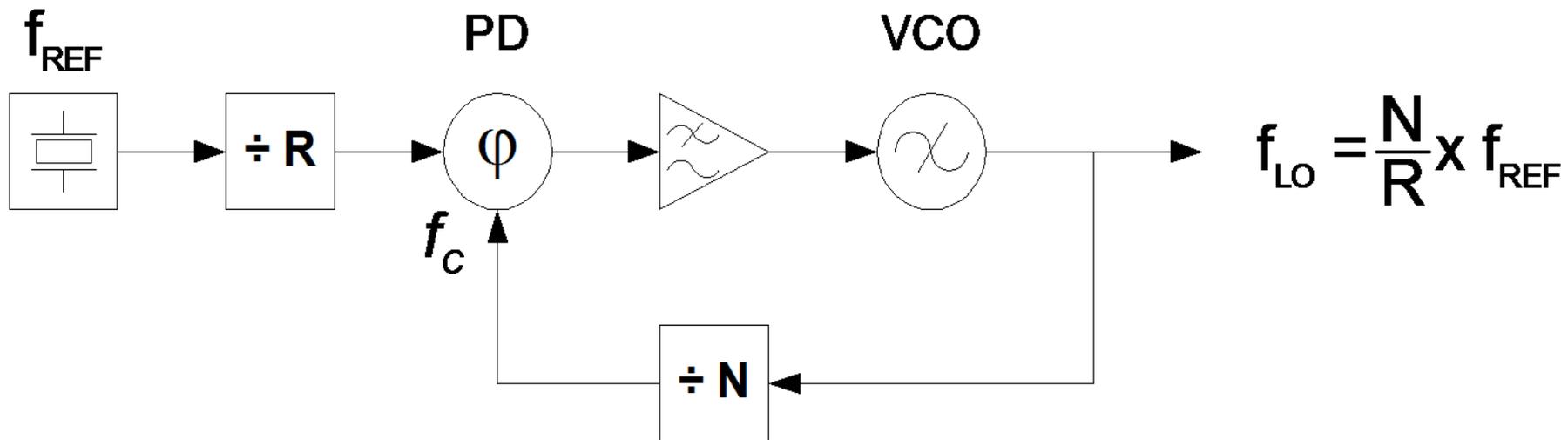
Output buffer in common emitter configuration

- Colpitts
- Phase noise:  $-115 \text{ dBc/Hz}$   
@ 1 MHz offset (20 GHz)

# PLLs

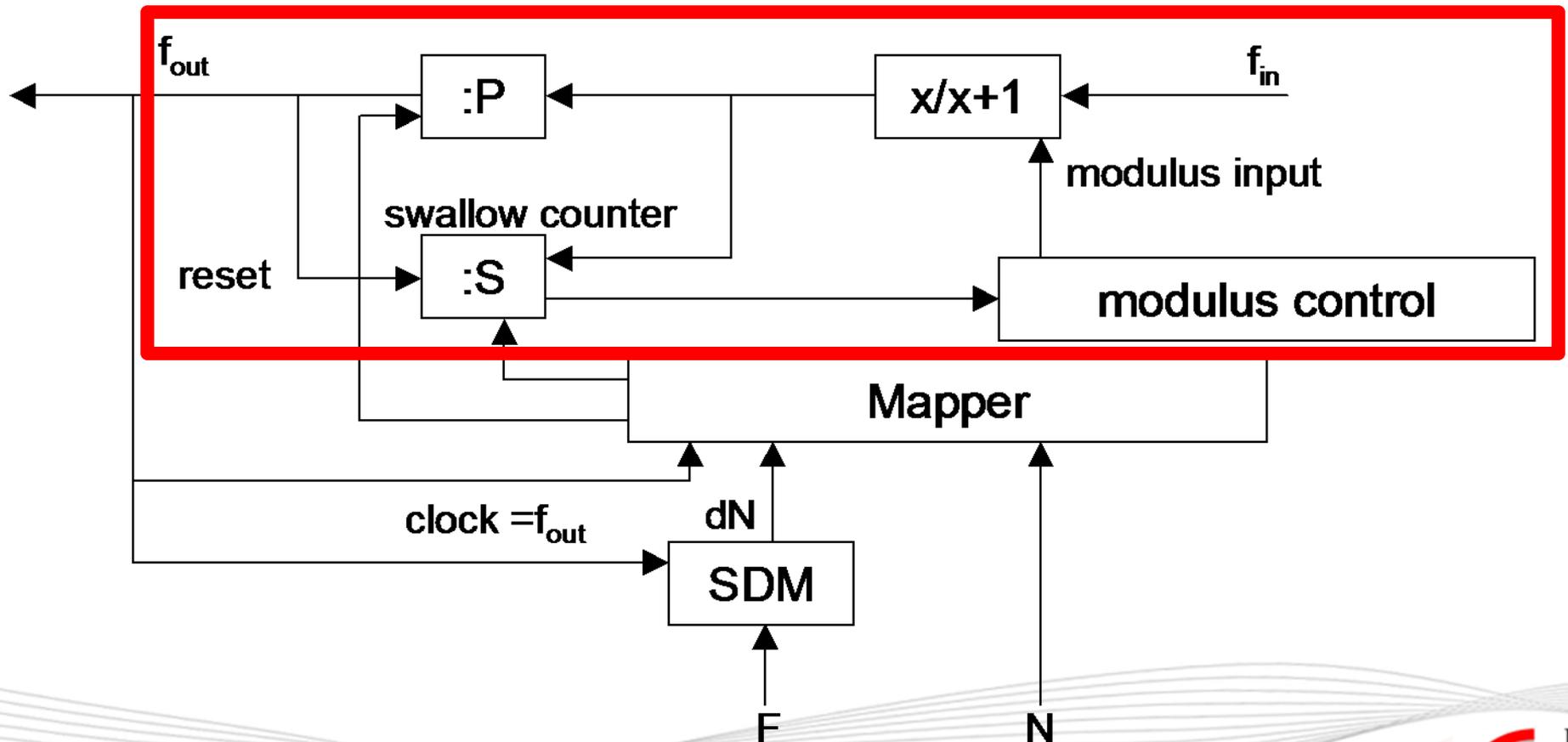
- Close to the carrier phase noise is determined by the reference crystal
- Inside PLL loop the phase noise of a synthesizer is determined by the PLL (phase detector). VCO noise is attenuated.
- Output PLL loop the phase noise of a synthesizer is determined by the VCO phase noise

# Integer-N PLL with reference divider



# How to generate arbitrary frequencies?

→ Build a programmable 1/N-divider



# Continuous division (example $x=8$ )

→ Divide  $S$  times by  $x+1$  and  $P-S$  times by  $x$

$$N=(x+1)*S+x*(P-S)=8*P+S, P>S$$

...

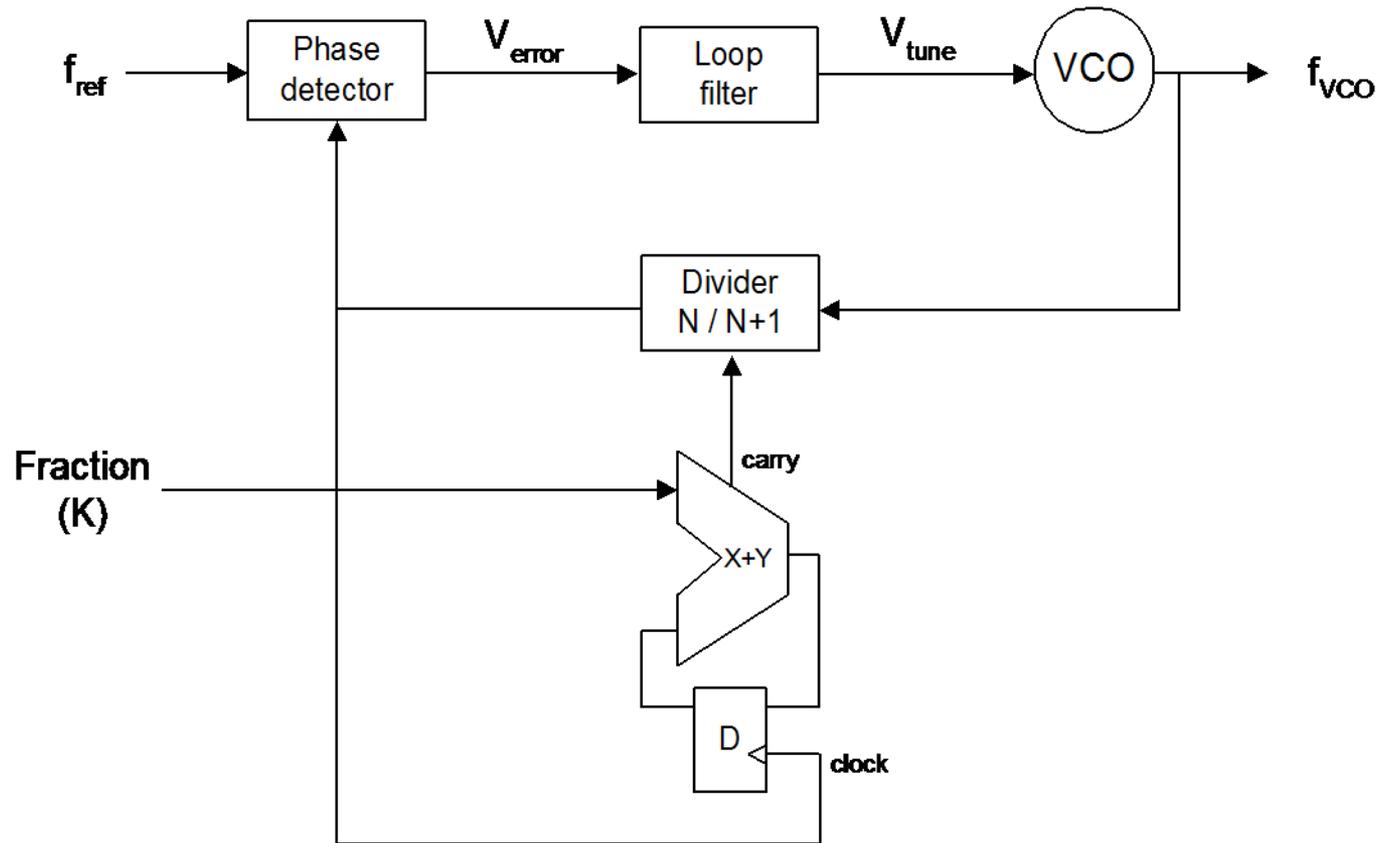
$$P=6, S=0..6: N=8*6+0..8*6+7=48..54, 55 \text{ not possible}$$

$$P=7, S=0..7: N=8*7+0..8*7+7=56..63$$

$$P=8, S=0..7: N=8*8+0..8*8+7=64..71$$

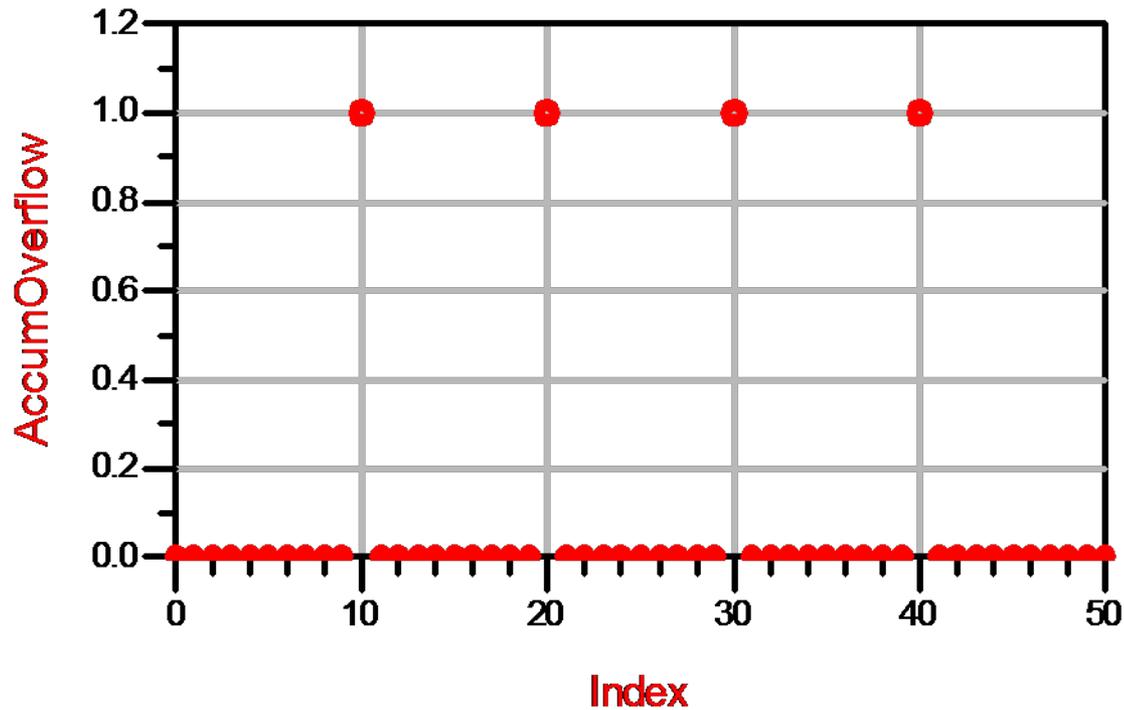
...

# Simplified fractional-N PLL example



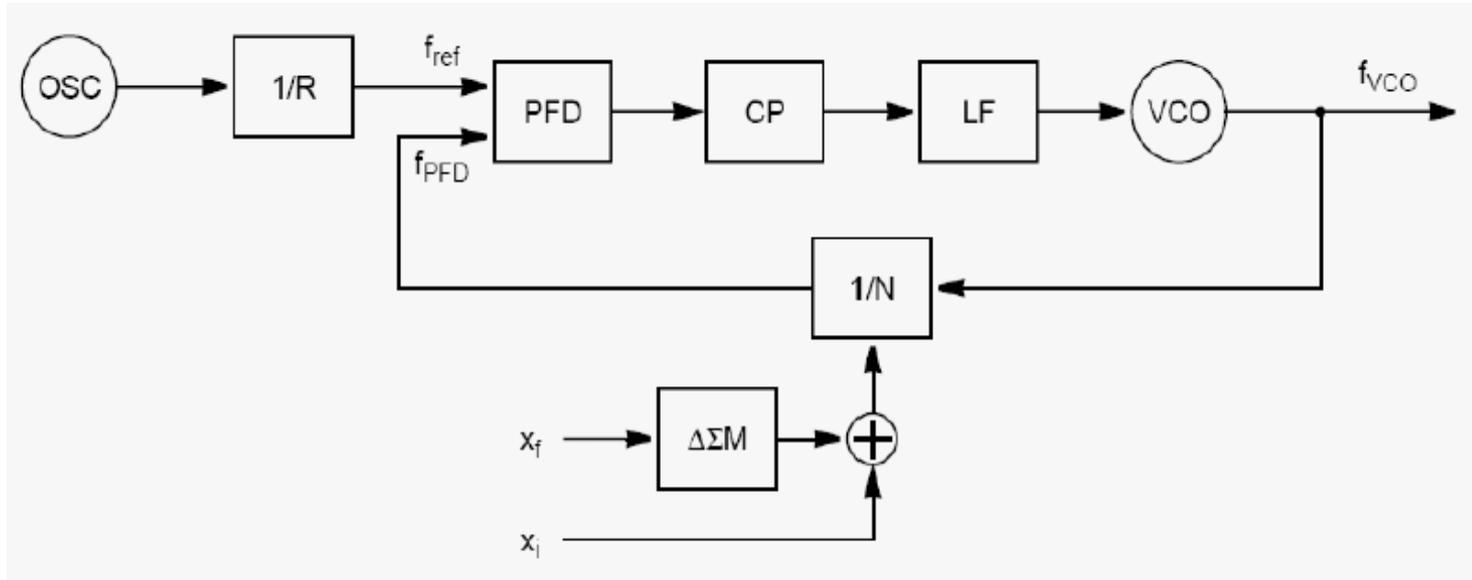
Ratio: 10.1: Divide 9 times by 10 and one time by 11 (next page)

# Accumulator



This division schema generates large spurs.

# Sigma Delta Modulator (SDM)



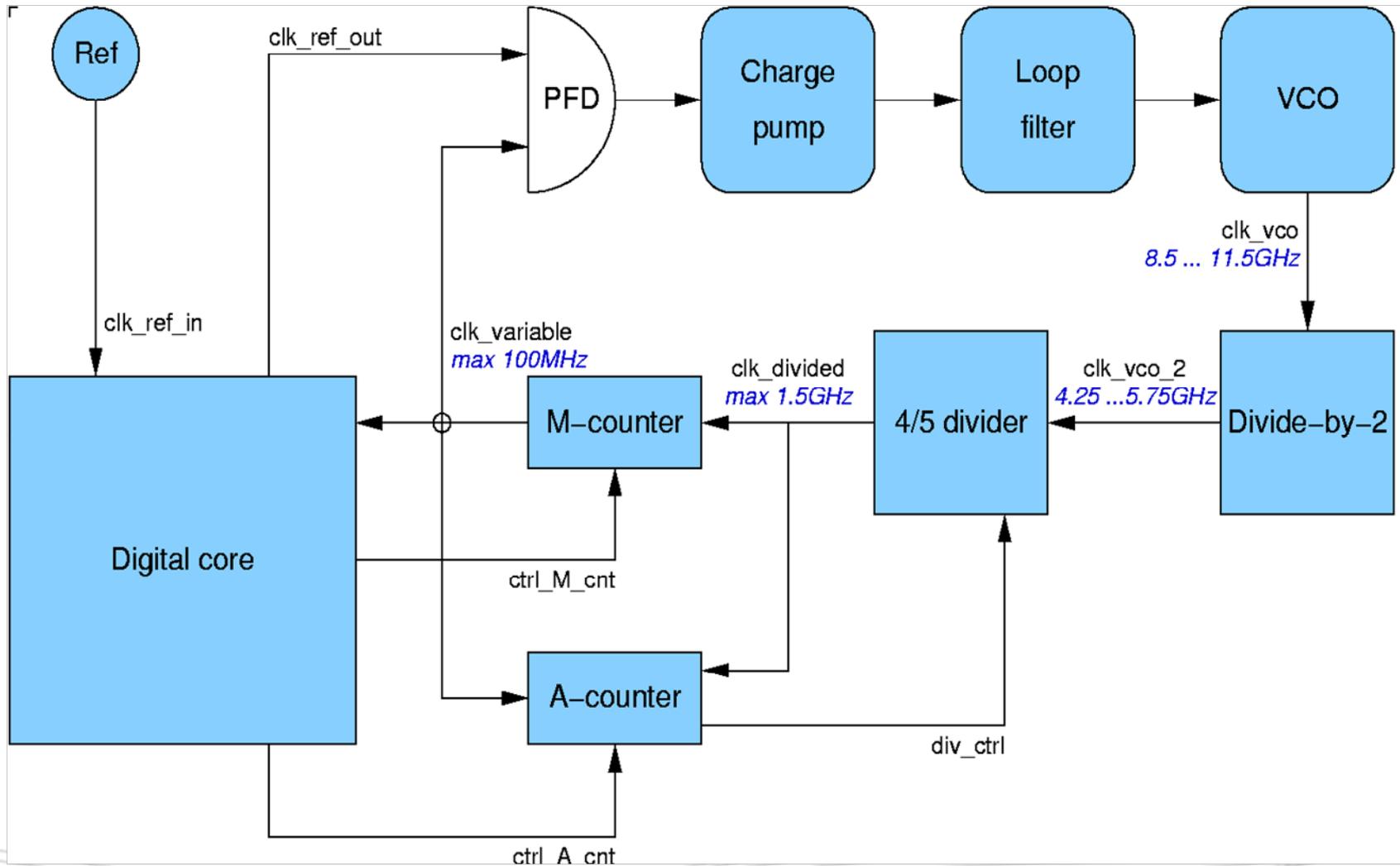
Modulator input: Only fractional part  $x_f$   
 SDM generates series of integer numbers  $n_i$   
 $n_i \in M$ ,  $2^M$  values are available for  $M$

$$x_f = \bar{n}_i = \lim_{N \rightarrow \infty} \frac{1}{N} \sum_{i=1}^N n_i$$

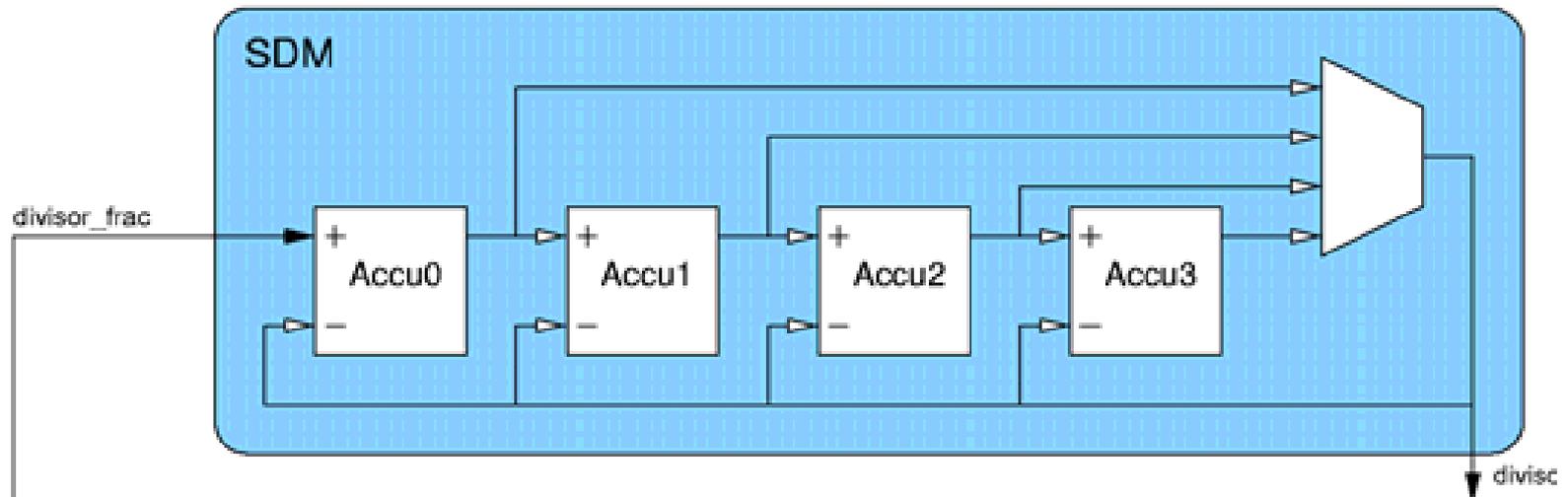
Time average value at SDM output

Example: 2, -4, -2, 3, 0, 3 -1, -3, 2, 1, ... for  $x_f = 0.1$

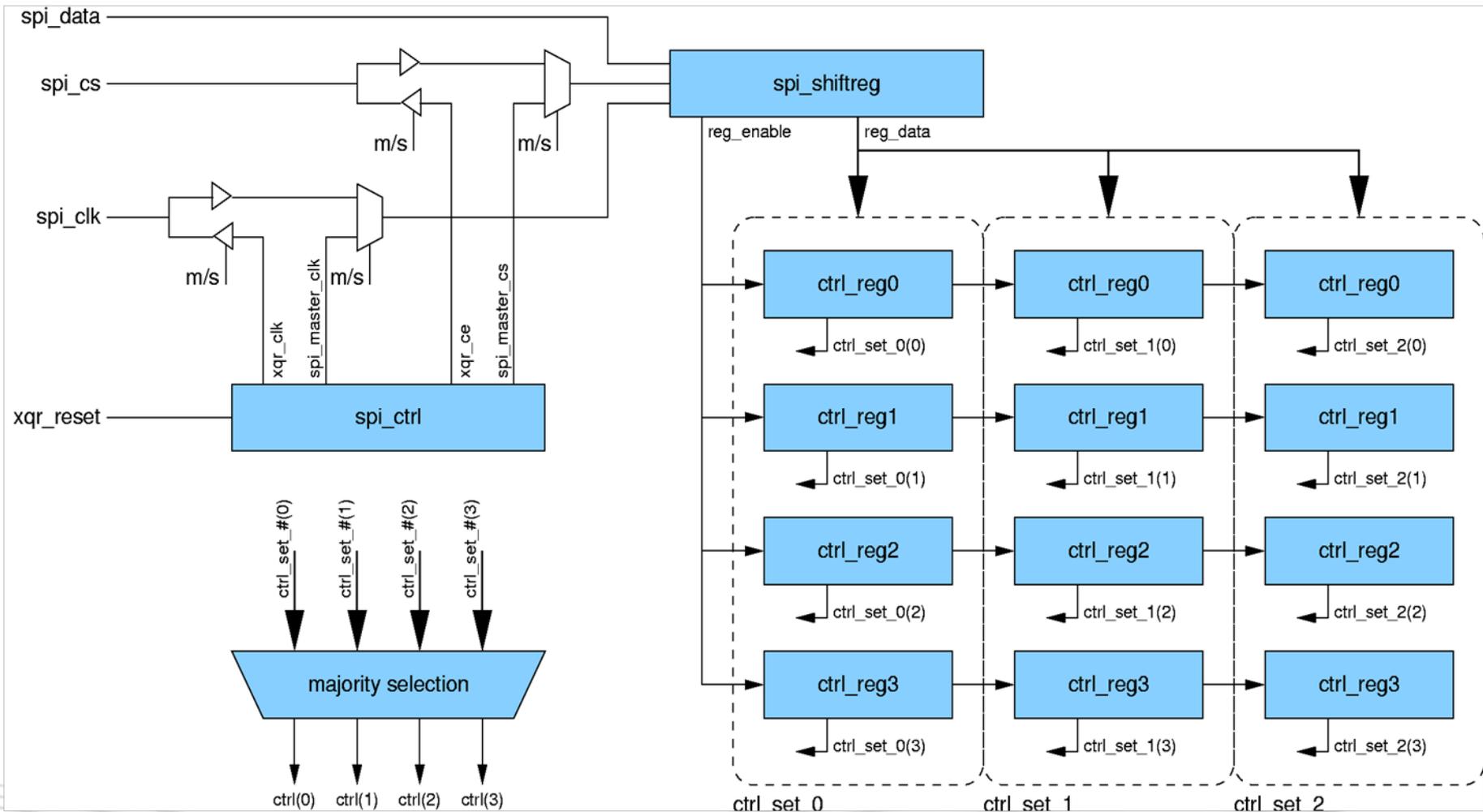
# Synthesizer architecture (1)



# Synthesizer architecture (2)

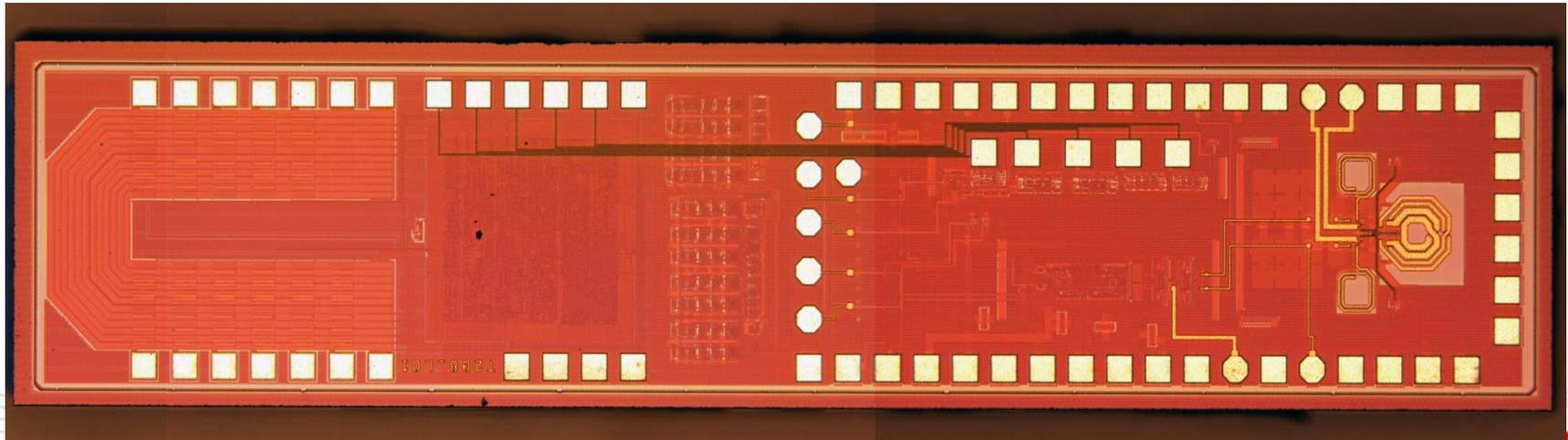


# Synthesizer architecture (3)

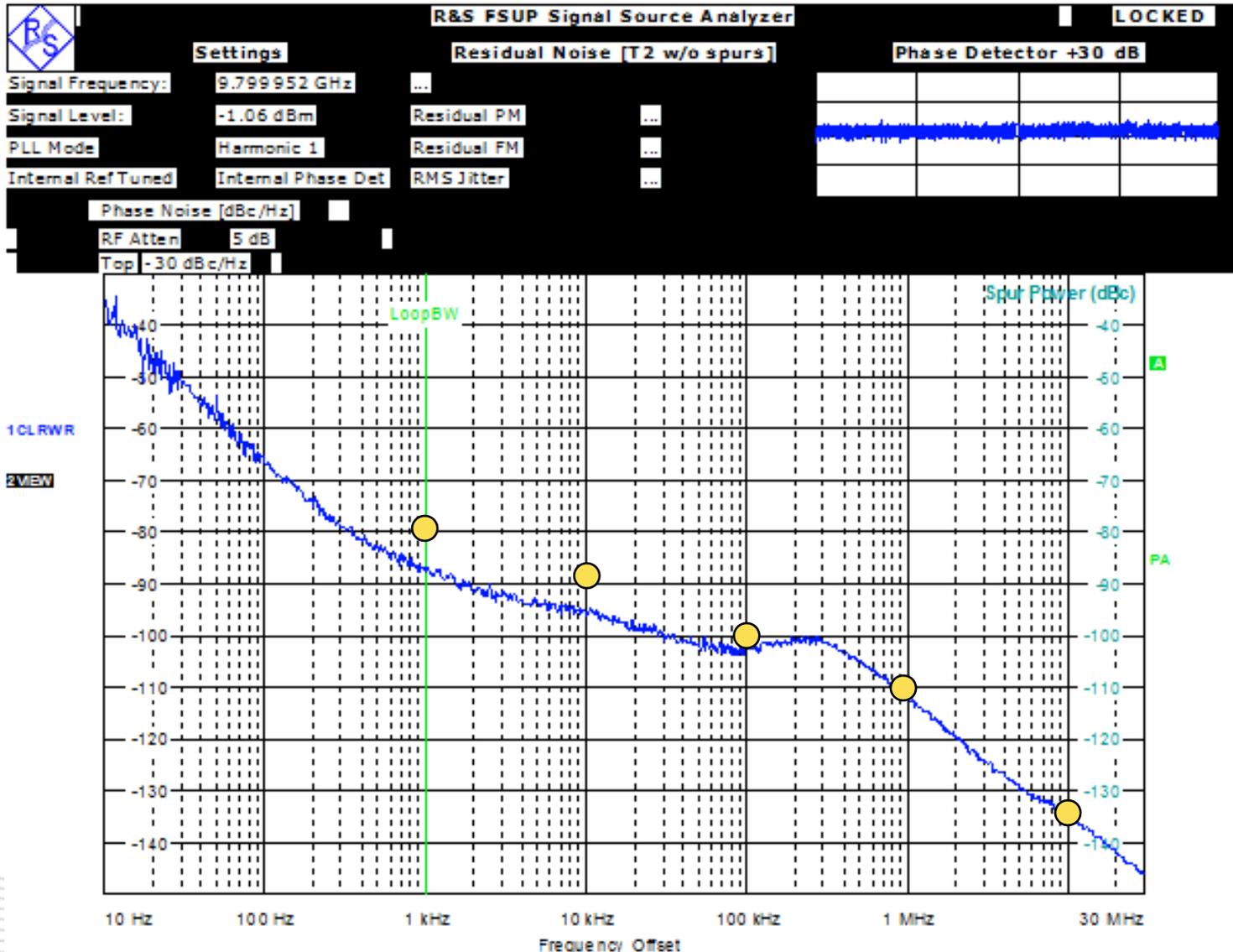


# SiGe Design

- World best 1-chip synthesizer
- 250 MHz-24 GHz PLL
- Integrated 17...20 GHz or 8...12 GHz VCO
- Fractional-N



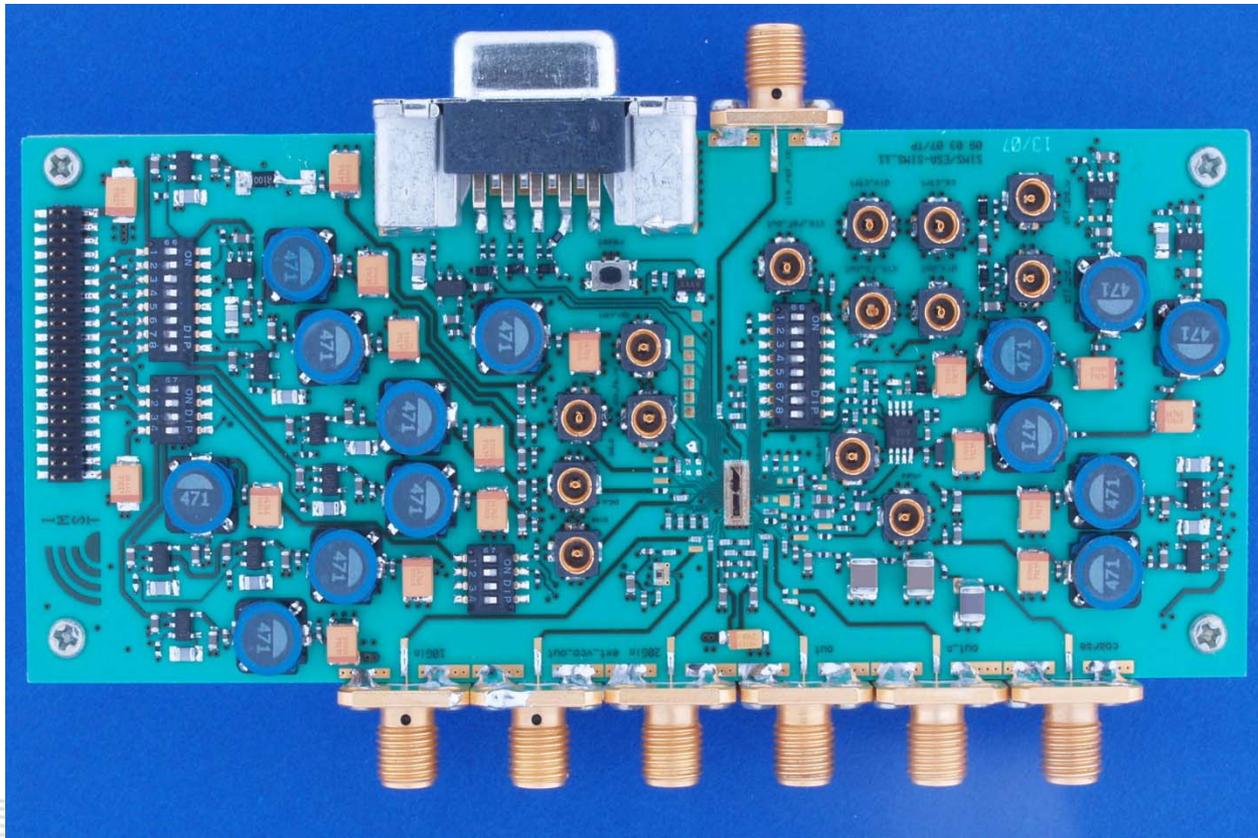
# Measurement results



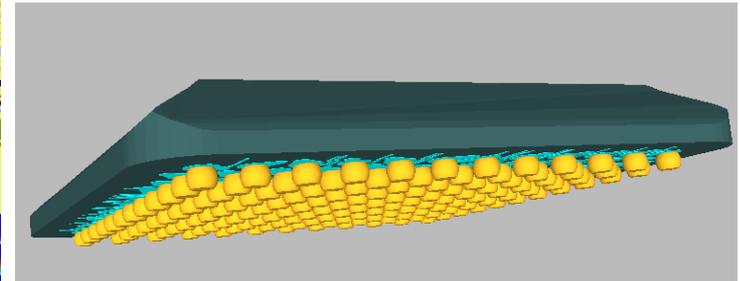
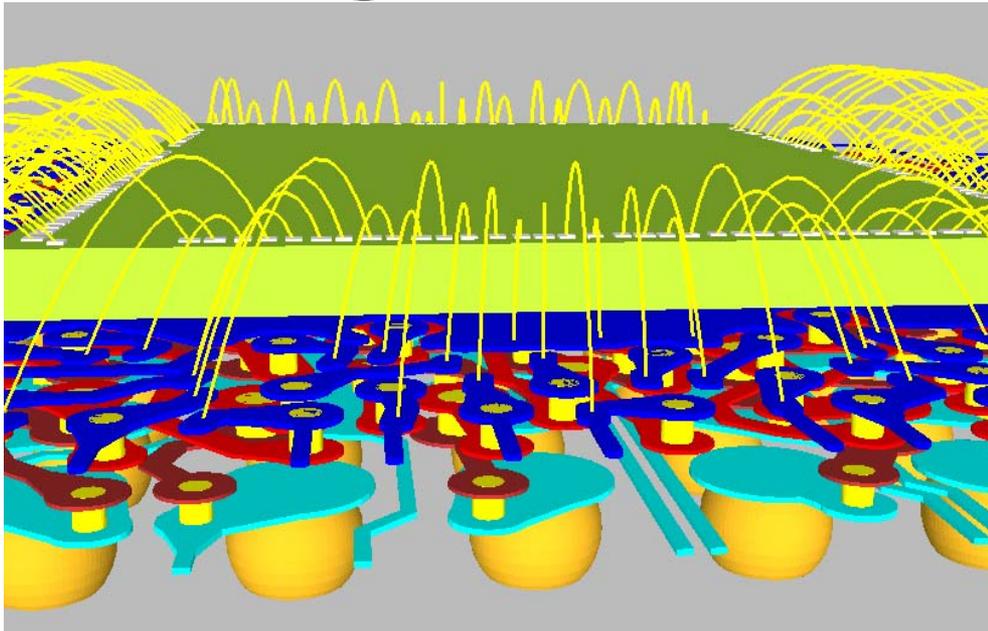
# Synthesizer application test board

→ PC interface

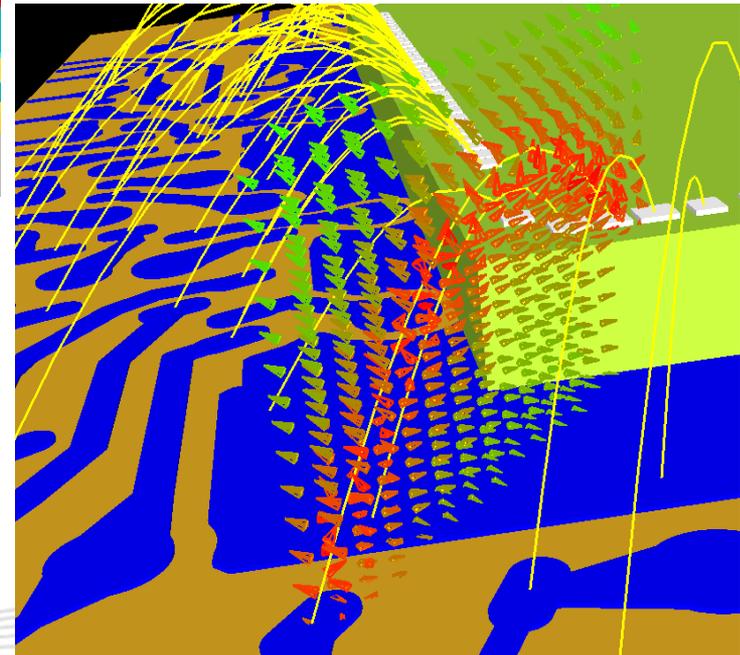
→ Many test ports



# Packages

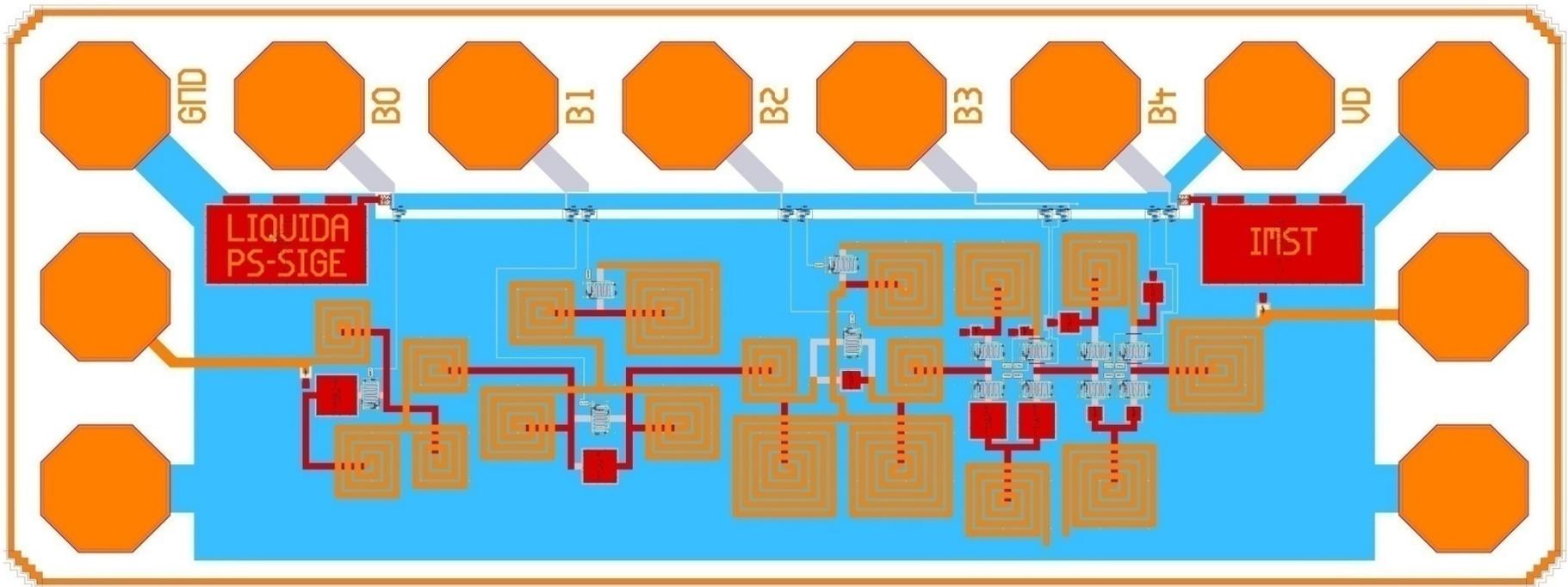


- BGA simulation
- Equivalent circuits
- S-parameter files
- Magnetic field



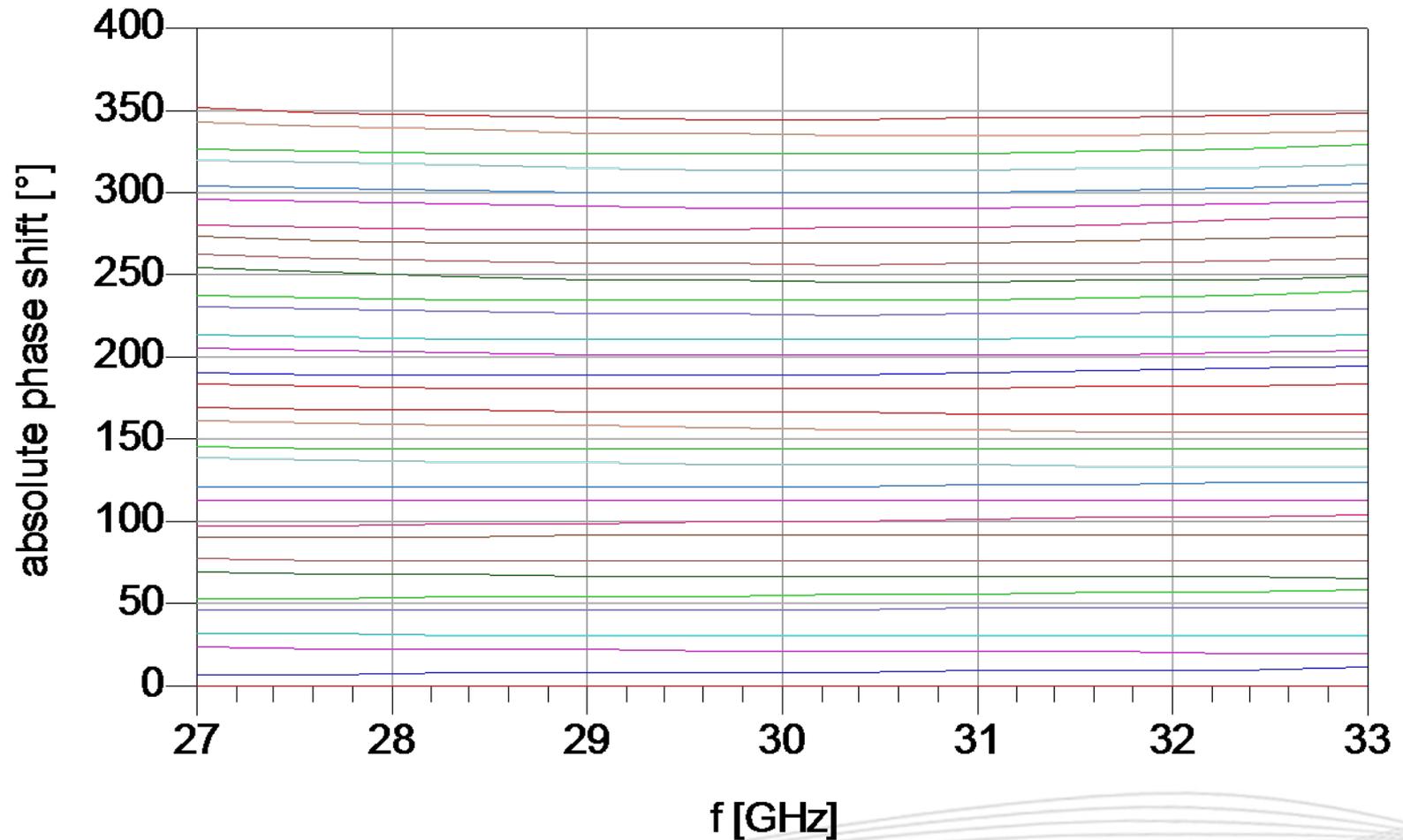
# World smallest phase shifter (ka)

Size 960 x 360  $\mu\text{m}^2$ , Core 620 x 210  $\mu\text{m}^2$



$V_D = 3 \text{ V}$ ,  $V_C (B0-B4) = 0 \text{ V} / 3 \text{ V}$  (active / not active)

# Phase diagram



# Any questions?

